

**KONTRON
LOGIC ANALYZER
DIAGNOSTIC PROGRAM
(LDP)**

SMK-LA-1010-01

NOVEMBER 1985

** KONTRON
ELECTRONICS**
1230 CHARLESTON ROAD
MOUNTAIN VIEW, CA 94039-7230

PREFACE

The Kontron Logic Analyzer Diagnostic Program (LDP) is primarily intended to be used by engineers and technicians to test the high-speed component boards (TBQ, SEQ, DMB) of the logic analyzer. To test the KDT6 and LA INT boards, see the Service Manual: Kontron LA, Volume 1 (SMK-LA-1001). The basic operating text is the Kontron Logic Analyzer Series III Operations (LA-5000).

This manual contains the following chapters and appendices:

- Chapter 1 - Introduction
- Chapter 2 - Test Setup
- Chapter 3 - Memory Tests
- Chapter 4 - TBQ Tests
- Chapter 5 - SEQ Tests
- Chapter 6 - DMB Tests
- Appendix A - LDP Menu Input Fields
- Appendix B - LDP Test Failures

For easy reference, additional schematics are provided at the end of this manual that are also duplicated in SMK-LA-1001 and LA-5000.

REVISION HISTORY

<u>Title</u>	<u>Number</u>	<u>Date</u>	<u>Notes</u>
Kontron Logic Analyzer Diagnostic Program (LDP)	SMK-LA-1010-01	11/85	Preliminary

RELATED PUBLICATIONS

Kontron Logic Analyzer Series III Operations	LA-5000-03	9/85	
Service Manual: Kontron LA, Volume 1	SMK-LA-1001-01	3/85	
Kontron LA Universal Probe Rack	CAN-175	10/84	

WARNING

This equipment generates, uses and can radiate radio frequency energy. If it is not installed and used in accordance with this instruction manual, it may cause interference to radio communications. Kontron has constructed this equipment in accordance with good engineering design and practice, in order to minimize such interference. Because it is classified as "commercial test equipment", the equipment is exempt from the current FCC rules. Therefore, it has not been tested for compliance with the limits for Class A computing devices pursuant to Subpart J of Part 15 of the FCC rules, which are designed to provide reasonable protection against such interference. Operation of this equipment in a residential area may cause interference, in which case the user will be required, at his own expense, to take whatever measures may be required to correct the interference.

CONTENTS

	Page
CHAPTER 1 - INTRODUCTION	
1.1 Purpose	1-1
1.2 Contents	1-1
1.2.1 Organization of This Manual	1-2
1.2.2 Quick Reference Guide	1-2
1.3 Hardware Description	1-4
CHAPTER 2 - TEST SETUP	
2.1 Pre-Test Instructions	2-1
2.2 Test Run Procedures	2-1
2.2.1 Self-Test Method	2-2
2.2.2 Manual Method	2-2
CHAPTER 3 - MEMORY TESTS	
3.1 Data Tests	3-1
3.2 Address Tests	3-2
CHAPTER 4 - TBQ TESTS	
4.1 Time Base Test	4-3
4.2 All Clocks Triggered by Divider Chain Test	4-4
4.3 Slow-Clock-Detection and Probe ID Test	4-7
4.4 Qualifier Inputs Test	4-9
4.5 Interlace Clocks ILA1, ILB1, ILA2 and ILB2 Test	4-11
CHAPTER 5 - SEQ TESTS	
5.1 Level Counter and Occurrence Counter Test	5-3
5.2 Trigger Filter 0 Test	5-4
5.3 Trigger Filter 1 Test	5-5

	Page
CHAPTER 6 - DMB TESTS	
6.1 Condition GLIT Test	6-3
6.2 All Trigger-Delay-Counters Test	6-7
6.3 Glitch-Latch Test	6-9
6.4 Transitional Clocking Signal (TCLK) Test	6-11
6.5 Conditions 2 and 3 (Data Qualified Recording) Test	6-13
6.6 Probe Test	6-15
6.7 DMB Inputs and Additional Data RAM Test	6-17

APPENDIX A - LDP MENU INPUT FIELDS

APPENDIX B - LDP TEST FAILURES

ADDITIONAL SCHEMATICS

ILLUSTRATIONS

FIGURES

<u>Number</u>	<u>Title</u>	<u>Page</u>
1-1	LA Board Configuration	1-4
1-2	LA Hardware Functional Block Diagram	1-6
4-1	Test Loop Flowchart	4-4
4-2	TBQ72 Flowchart	4-6
4-3	QUALTS Flowchart	4-8
4-4	ILAB12 Flowchart	4-10
5-1	LEVINC Flowchart	5-2
6-1	GLAGLB Flowchart	6-2
6-2	DELCNT Flowchart	6-6
6-3	GLIT Flowchart	6-8
6-4	TRANS Flowchart	6-10
6-5	DATAQUAL Flowchart	6-12
6-6	PROBETS Flowchart	6-14
A-1	LDP Main Menu	A-1
A-2	Single-Test Menu	A-3

INTRODUCTION

1.1 PURPOSE

Because of the complex architecture of the equipment, the Kontron Logic Analyzer (LA) is difficult to test. A special program, the Logic Analyzer Diagnostic Program (LDP), has been developed to conduct appropriate tests and report the results. The purpose of this manual is to acquaint you with the LDP tests and how to perform them.

1.2 CONTENTS

This manual contains the following chapters and appendices:

Chapter 1 - Introduction

Chapter 2 - Test Setup

Chapter 3 - Memory Tests

Chapter 4 - TBQ Tests

Chapter 5 - SEQ Tests

Chapter 6 - DMB Tests

Appendix A - LDP Menu Input Fields

Appendix B - LDP Test Failures

Information on the CPU and I/O boards (KDT6, LA INT) is found in the Kontron LA Service Manual, Volume 1 (SMK-LA-1001). The basic text for operating the LA is the Kontron Logic Analyzer Series III Operations (LA-5000) manual. There is also a Customer Application Note (CAN-175) that explains how the Universal Probe Rack (UPR) operates and specifies pinout connections.

1.2.1 ORGANIZATION OF THIS MANUAL

The LDP tests are grouped in the order the hardware is configured (i.e., TBQ, SEQ, DMB), therefore, you should follow that sequence in testing.

To enhance readability, the test material in Chapters 4 through 6 is presented as follows: flowchart (if applicable), description of test, and schematics for the board. The flowcharts describe the principle underlying each test. They are intended to help the user follow the step-by-step operation, and thus enable him to find the point where the error occurred. The test descriptions suggest the cause of possible errors.

Appendix A explains what each LDP menu does and shows the associated LA sample screen shots. Appendix B describes some possible reasons for LDP test failures and also includes sample screen shots. There are additional schematics at the end of this manual pertaining to the motherboard and the KDT6 and LA INT boards (see section 1.3).

1.2.2 QUICK REFERENCE GUIDE

This subsection is designed to give you a "hands-on" approach to locating information relevant to testing the LA. The items are listed alphabetically with the corresponding manual and chapter numbers:

<u>What</u>	<u>Where</u>
Address tests	SMK-LA-1010, Chapter 3
Back panel connections	LA-5000, Chapter 1
Computer test software	SMK-LA-1001, Chapter 9
Data tests	SMK-LA-1010, Chapter 3
Disassembly of housing/boards	SMK-LA-1001, Chapter 2 (LA-SERV)

Kontron LA Diagnostic Program (SMK-LA-1010-01)

<u>What</u>	<u>Where</u>
Disk drives	SMK-LA-1001, Chapter 5
ECL bus boards	SMK-LA-1010, Chapters 4-6
Error detection at board level	SMK-LA-1001, Chapter 2 (LA-SERV)
Front panel keys	LA-5000, Chapter 2
Hardware description	SMK-LA-1010, Chapter 1
LA equipment	SMK-LA-1010, Chapter 2
LDP test software	SMK-LA-1010, Chapter 2
Power supply	SMK-LA-1001, Chapter 8
Recording operations	LA-5000, Chapter 2
Self-test probe connections	LA-5000, Chapter 3
Service remarks	SMK-LA-1001, Chapter 2 (LA-SERV)
Test instructions	SMK-LA-1010, Chapter 2
Theory of operations	LA-5000, Chapter 7
TTL bus boards	SMK-LA-1001, Chapters 3-4
Universal Probe Rack connection	CAN-175

1.3 HARDWARE DESCRIPTION

Each Kontron LA has the following board configuration (see Figure 1-1):

- KDT6 is the Z80-based, general-purpose computer board that has 256K of memory with two serial ports, one parallel port, and a floppy disk controller.
- LA INT is the I/O board that controls the reset logic, serial/parallel ports, GPIB/RS-232 connections, interface to the front panel keyboard, and the CPU-driven TTL connection.
- TBQ is the Time Base and Clock Qualifier board that controls clock generation.
- SEQ is the Trigger Sequencer Controller board that handles triggering.
- DMB is the Data Memory Board (0 to 4) that maintains data recording. Each board supports two probes and has its own clock, either external or internal.
- TMB is the Time Measurement Board, which is an optional component that records time information during Data Qualified and Transition Recording.

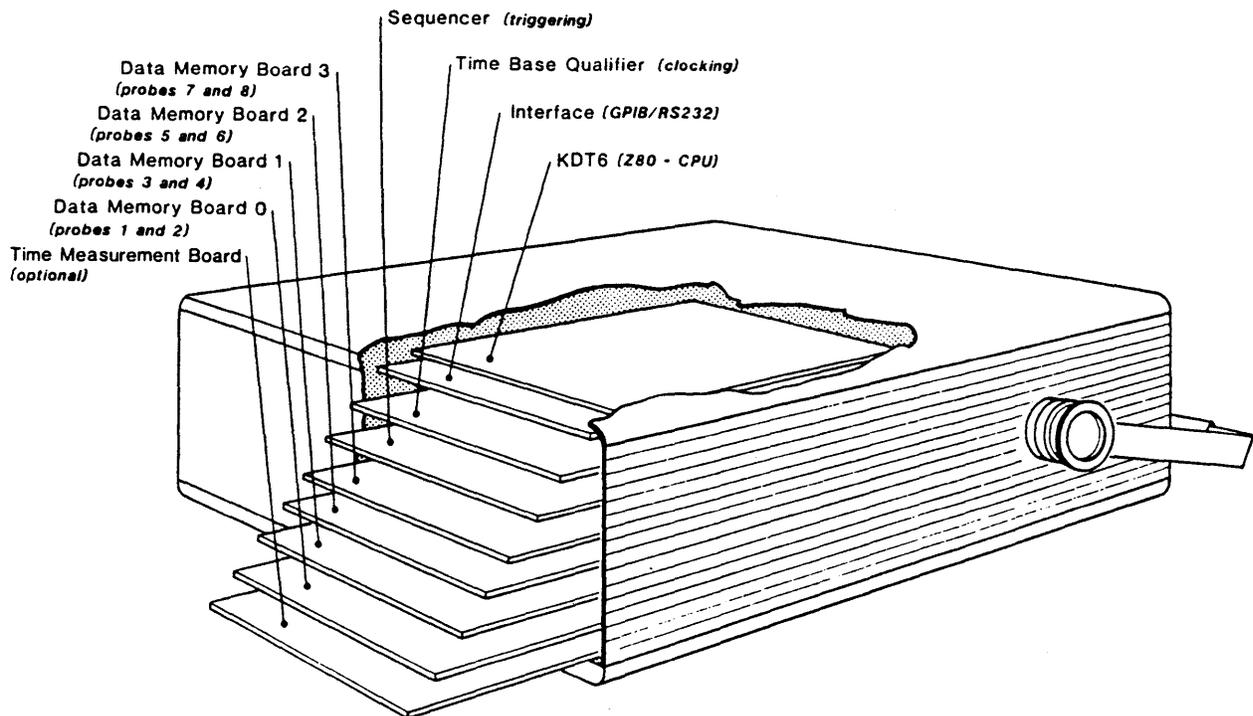


Figure 1-1. LA Board Configuration

Kontron LA Diagnostic Program (SMK-LA-1010-01)

The boards are all plugged into the LA's motherboard, which has a double Eurocard bus. There are seven pairs of 64-pin connectors; each connector pair is assigned to one of two buses:

- A-Bus

This is a slower TTL bus used for memory access by the CPU as well as for managing other computer components.

- B-Bus

This is a high-speed ECL bus used for communication between boards during a recording or trigger search.

See Figure 1-2 for a functional block diagram of the LA hardware.

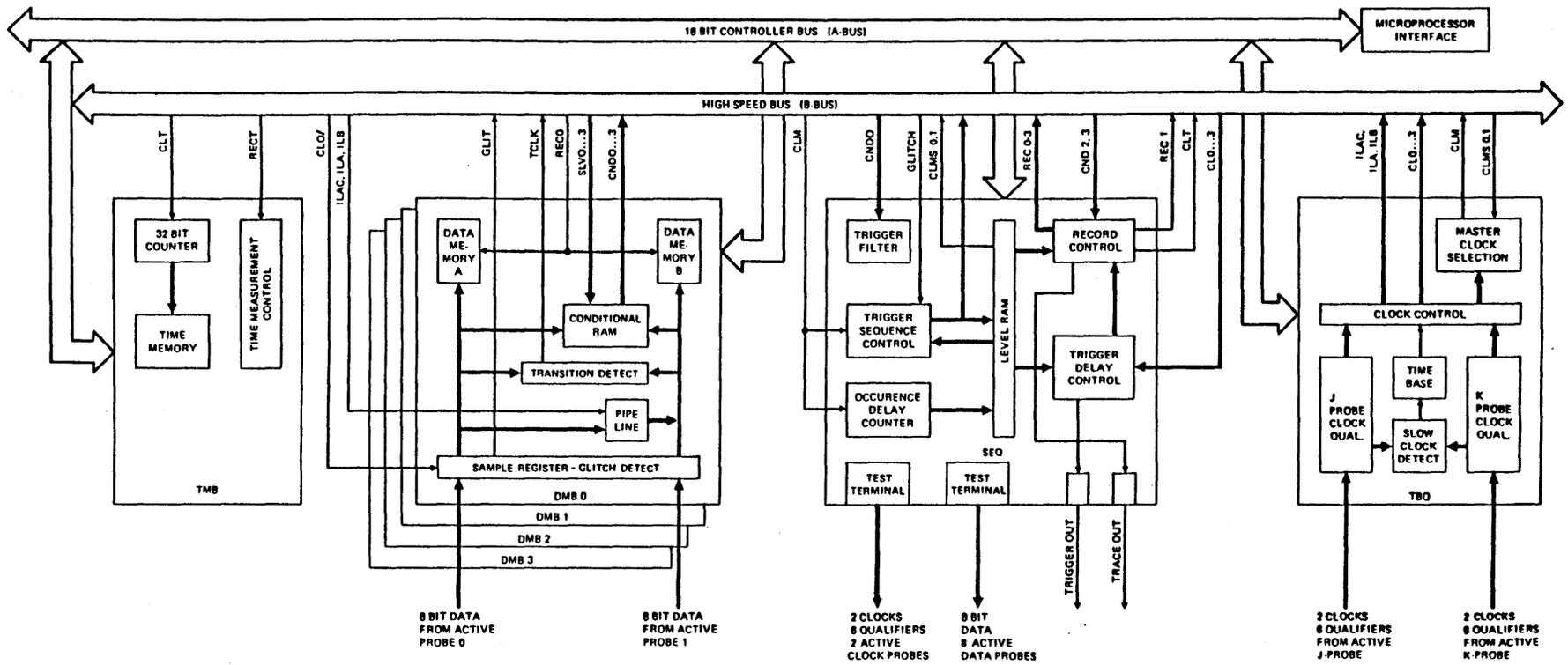


Figure 1-2. LA Hardware Functional Block Diagram

2.1 PRE-TEST INSTRUCTIONS

Including this manual, we recommend that you have the following assembled prior to testing:

Documentation: See publications listed in section 1.2

Disks: Computer Test, SMK-LA-1001-01
KLA/KSA Diagnostic Program (LDP), SMK-LA-1010-01

Equipment: LA-32, LA-48 or LA-64

Probes (LA-SPDA):

32 channels = 6
48 channels = 8
64 channels = 10

Universal Probe Rack (LA-UPR-10)

LA test configurator with flat ribbon cables

We also suggest that you review the Quick Reference Guide in subsection 1.2.2, which identifies where supplemental testing information is located.

2.2 TEST RUN PROCEDURES

Again, we advise you to conduct your testing according to the board configuration (see section 1.3). To test the KDT6 and LA INT boards, insert the Computer Test disk into drive A, press the RESET button to automatically load the program, and follow the prompts to complete testing.

The two methods for using the LDP software to test the TBQ, SEQ and DMB boards are:

- Self-Test (with UPR and test configurator)
- Manual (without UPR and test configurator)

2.2.1 SELF-TEST METHOD

For the self-test method, perform the following steps:

1. Connect all probes into the LA-UPR-10.
2. Connect all probes to their respective positions in the rear of the LA.
3. Connect one ribbon cable of the test configurator to the front of the LA-UPR-10. Next, connect the other ribbon cable to the Data Probe/Clock Probe test terminals on the LA's back panel. These test terminals are controlled by the pattern generator circuit on the SEQ board.
4. Insert the LDP disk into drive A, press RESET to load the program, and press key 1 to start the test; follow the LDP prompts to complete testing. NOTE: If you want the test to run automatically without stopping, press the "+" key before pressing key 1, which toggles to OFF (default is ON).

2.2.2 MANUAL METHOD

If no Universal Probe Rack is available, connect the probes to the Data Probe test terminal on the LA's back panel according to the LDP operating instruction prompts. For the manual method, perform the following steps:

1. Insert LDP disk into drive A and press RESET to load the program.
2. After the Main Menu (see Figure A-1) has appeared on the screen, you can press the "+" key, which eliminates test interruption after each screen.
3. Press key 1 to start the test.
4. If the screen shows "No defective board detected", the test is finished and the equipment is in perfect working condition.
5. If, however, errors are detected and there is no indication as to which test recognizes the error, follow steps 6 through 8.
6. Push the "+" key to follow the test run on the screen.
7. Resume the test run by pressing key 1.

8. If the test indicating the presence of an error is found, press the RUBOUT key (external keyboard) or the F1 key (KLA keyboard) to get back to the Main Menu.
9. Press the "+" key again, which indicates "stop after each screen is off".
10. Press key 2 to get into the Single-Test Menu.
11. In the Single-Test Menu if you want the test to run continuously, set the flag ON by pressing key C (see Figure A-2).
12. Using the menu, select a test and then start the test by pressing the RUN/STOP key.
13. Because the audible error detection is switched ON, a "beep" will sound off during each test run when it identifies which board has an error.

WARNING: Exchanging boards is not recommended while the power is on.

It is important to note that all data lines must go across the TBQ board and to the data bus. If one of the lines is defective, almost all tests are going to yield a negative result.

MEMORY TESTS

In order to test the various functions of the LA boards, all RAMs located on the boards have to be in excellent working condition. Therefore, software diagnosis starts out with memory tests, followed by an operation check of the interface with the TBQ, SEQ and DMB boards. These memory tests are subdivided into data tests and address tests, which are described in the following sections.

3.1 DATA TESTS

In data tests, the same data pattern is laid down in all memory elements in order to ignore possible addressing mistakes. The data pattern itself is constructed in such a way that every bit at one point has a low and a high state. Moreover, the layout of the data pattern can indicate faulty connections between the data bits.

This kind of data test can be conducted with the following memories:

Specific RAM	Addresses*Data
TBQ Qualifier RAM	256*8 (exists 2x)
SEQ Level Address RAM	16*4
SEQ Occurrence Counter RAM low byte	16*8
SEQ Occurrence Counter RAM high byte	16*8
SEQ Level Status RAM	16*8
SEQ Trigger Filter RAM	16*4
DMB Condition RAM	256*8 (exists 4x)

Reasons for negative test results:

- Defective RAM
- Defective buffer
- Errors in the data logger

In the case of DMB Data RAM and TMB Data RAM, data cannot be written in from the computer directly; however, it is generated and written in by the DMB and TMB, respectively. The computer's task is to read the data and check it for accuracy of information.

3.2 ADDRESS TESTS

In order to find addressing errors, the RAMs are loaded with a non-repetitive pattern. This assures that each pattern is only laid down at one distinctive point in the RAM. The computer reads this pattern and checks it for accuracy of information.

Reasons for negative test results:

- Defective RAM
- Defective address counter
- Error in address logger

On the SEQ, the address counter is tested for the level address (Register 60H) in addition to the tests mentioned above. In order to yield a positive result in the test, it is not absolutely necessary that the RAMs are in perfect working condition.

Address counters located on the DMBs are also tested for data RAMs. According to the selected memory depth (2K, 4K, 8K), it is determined if the address counter can count properly all the way through the entire depth of memory. If another test is conducted, it shows whether the address counter can be precharged with any permissible value.

TBQ TESTS

This chapter contains the tests listed below for the Time Base and Clock Qualifier (TBQ) board. The flowchart for each test (if applicable) precedes the description of the test. Schematics for the TBQ board are at the end of the chapter.

- 4.1 Time Base Test
- 4.2 All Clocks Triggered by Divider Chain Test
- 4.3 Slow-Clock-Detection and Probe ID Test
- 4.4 Qualifier Inputs Test
- 4.5 Interlace Clocks ILA1, ILB1, ILA2 and ILB2 Test

This page intentionally left blank

4.1 TIME BASE TEST

Name of the test in the source listing: CLOKTS
In the Single-Test Menu of the LDP: Special Test 01

Purpose: CLOKTS determines if the time base works properly.

Reasons for negative test results:

- CL 1000 does not show up (error in clock generator or in divider chain).
- Error in the slow-clock-detection (check by means of Special Test 03, see section 4.3).

Description of the test:

The different clockings are generated in a divider chain (see page 2 of the TBQ schematics). If the slowest clocking is operating (i.e., 1000ms; hereafter referred to as CL 1000), it can safely be assumed that the divider chain is in perfect working condition.

Because CL 1000 is used in the slow-clock-detection, it is possible to test its operation via software.

The signal ENEX/ is induced and reinduced in Coil 1 (no more than 65,535 times). Thus, an external clocking rhythm is stimulated because the signals TJ0, TJ1, TK0 and TK1 toggle in the clocking rhythm of ENEX/ (see page 4 of the TBQ schematics).

Moreover, Coil 1 reads Register 73H until the date 0FH changes into 00H, which should occur when the next SYNC signal comes on. (The FLIP-FLOPs L6, K6, J5 and K5 are induced as variable cycle operations.) If the date 00H is not found within 65,535 cycles, the test result is negative.

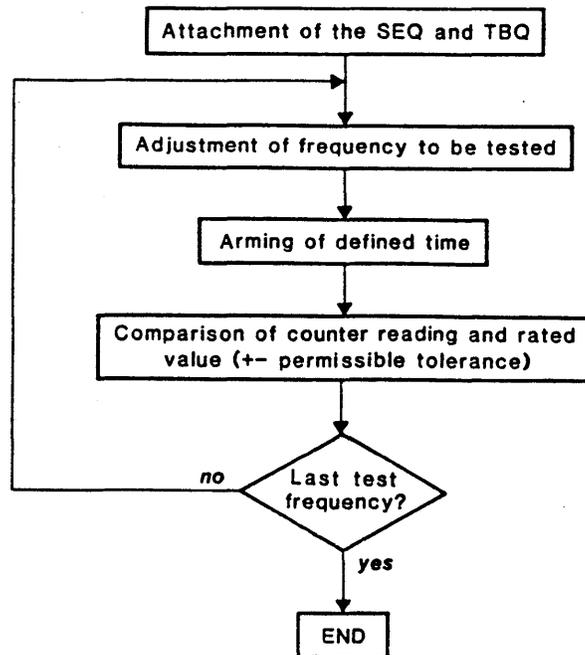


Figure 4-1. Test Loop Flowchart

4.2 ALL CLOCKS TRIGGERED BY DIVIDER CHAIN TEST

Name of the test in the source listing: CLOKT2
In the Single-Test Menu of the LDP: Special Test 02

Purpose: CLOKT2 determines if the adjustable frequencies have the proper value, and if they have been selected and processed properly.

Reasons for negative test results:

- Error detection (too fast or too slow) in all frequencies indicates a missing condition increment (Cause: DMB(s) or SEQ).
- Error detection in some frequencies indicates that there are either errors in the occurrence counter (SEQ) or in the time base (TBQ).

Description of the test:

A 16-bit wide occurrence counter is located on the SEQ. The counter uses a clock that has been selected by the TBQ. If this counter is asked to count for a specific period of time, an exactly defined counter reading has to be reached when given a precise frequency of counting. This enables the user to determine whether or not the counter readings and clockings are correct.

NOTE: A prerequisite for this test is that the counter must be in excellent working condition. Experience with this test has shown that the counter itself is imperfect rather than the clocking.

In order for the occurrence counter to work, three conditions have to be met:

1. Condition 0 (increment) has to be active. To achieve an active Condition 0, the Condition RAMs on the DMBs have to be filled with 11H. In addition, the Condition RAMs have to be enabled accordingly (load Register n2 with 30H).
2. No final trigger should have been found yet. By filling the Level Status RAMs of the sequencer with 1BH, the result is that no final trigger can be found. (Bit 4 is high at all times.)
3. The LA has to be "armed". The "arming" of the LAs is done via Register 72 on the TBQ.

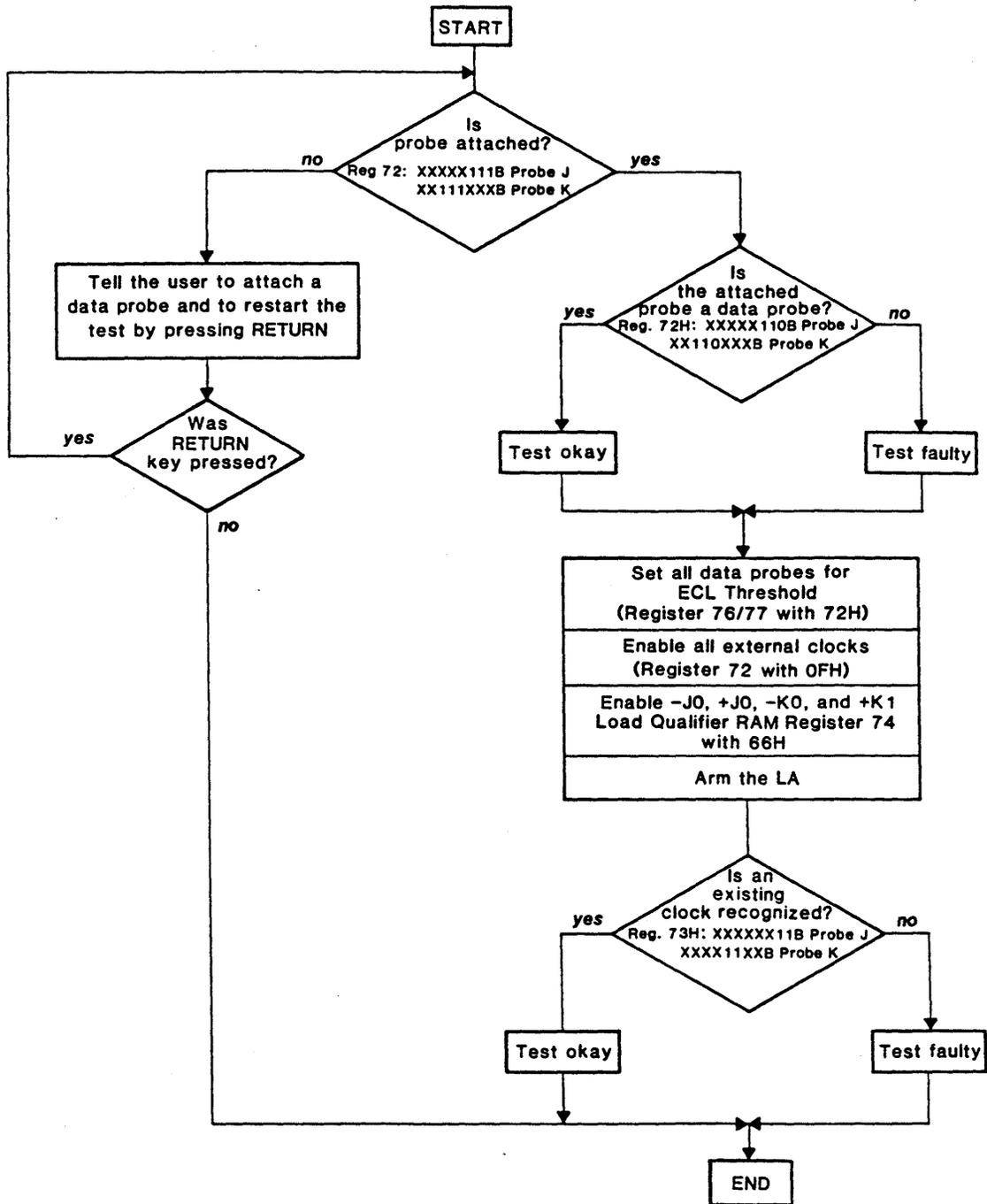


Figure 4-2. TBQ72 Flowchart

4.3 SLOW-CLOCK-DETECTION AND PROBE ID TEST

Name of the test in the source listing: TBQ72
In the Single-Test Menu of the LDP: Special Test 03

Purpose: TBQ72 determines if

- a. An attached data probe is recognized properly.
- b. The slow-clock-detection works properly.

Reasons for negative test results:

As per a:

- Route-marking characteristic on the probe was improperly wired or not wired at all.
- Error in the data line of Register 72.

As per b:

- Probe is not properly attached to the SEQ.
- Probe or test configurator wire defective (test has to be conducted).
- Slow-clock-detection defective (see section 4.1).

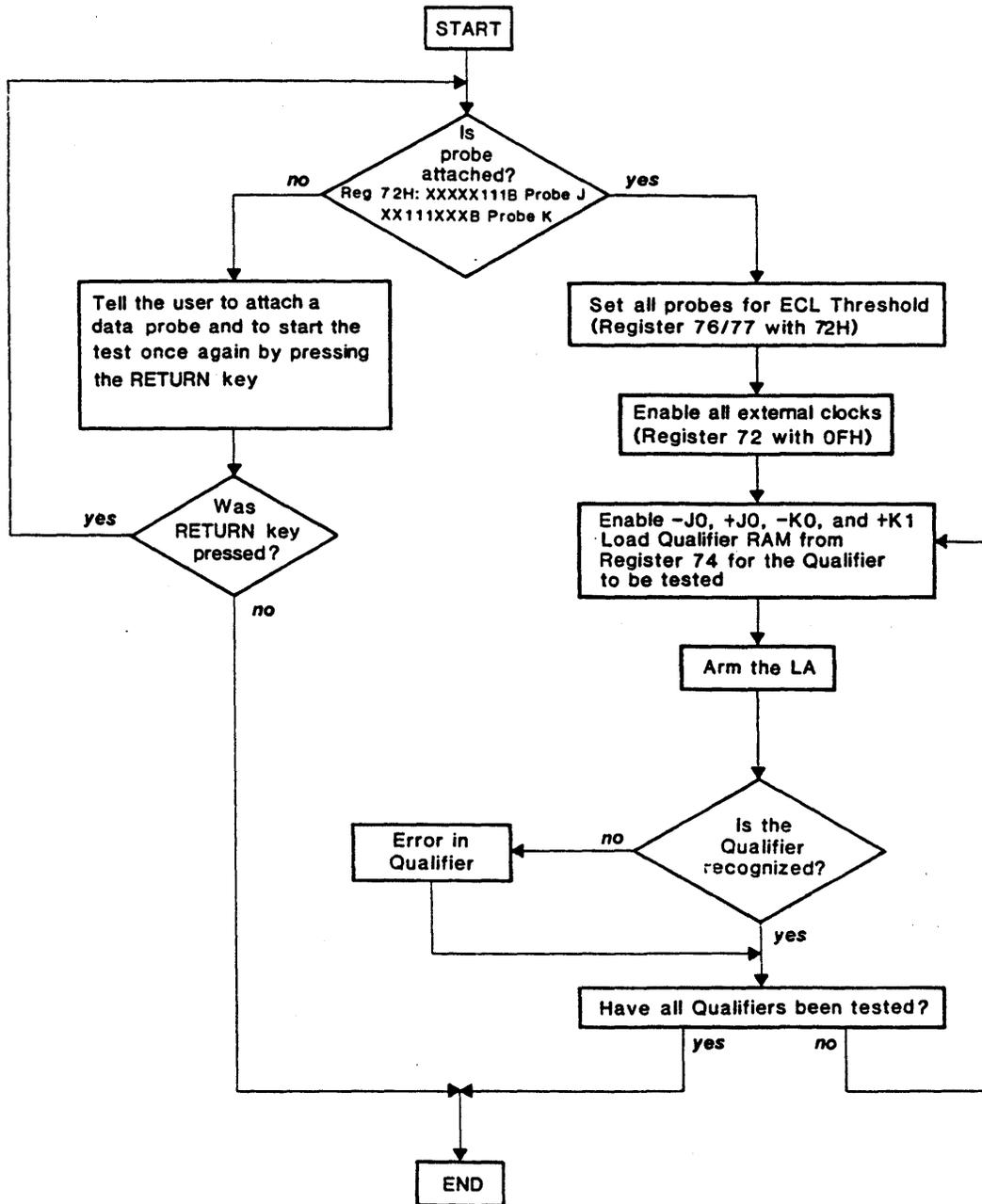


Figure 4-3. QUALTS Flowchart

4.4 QUALIFIER INPUTS TEST

Name of the test in the source listing: QUALTS
In the Single-Test Menu of the LDP: Input Tests 09 and 10

Purpose: QUALTS checks the data line from the pattern generator on the SEQ up to the Qualifier RAM on the TBQ.

Reasons for negative test results:

- Probe is not correctly attached to the SEQ.
- Probe or test configurator wire is defective (test has to be conducted).
- Pattern generator on the SEQ does not supply the right pattern.
- Input buffer on the TBQ is defective.

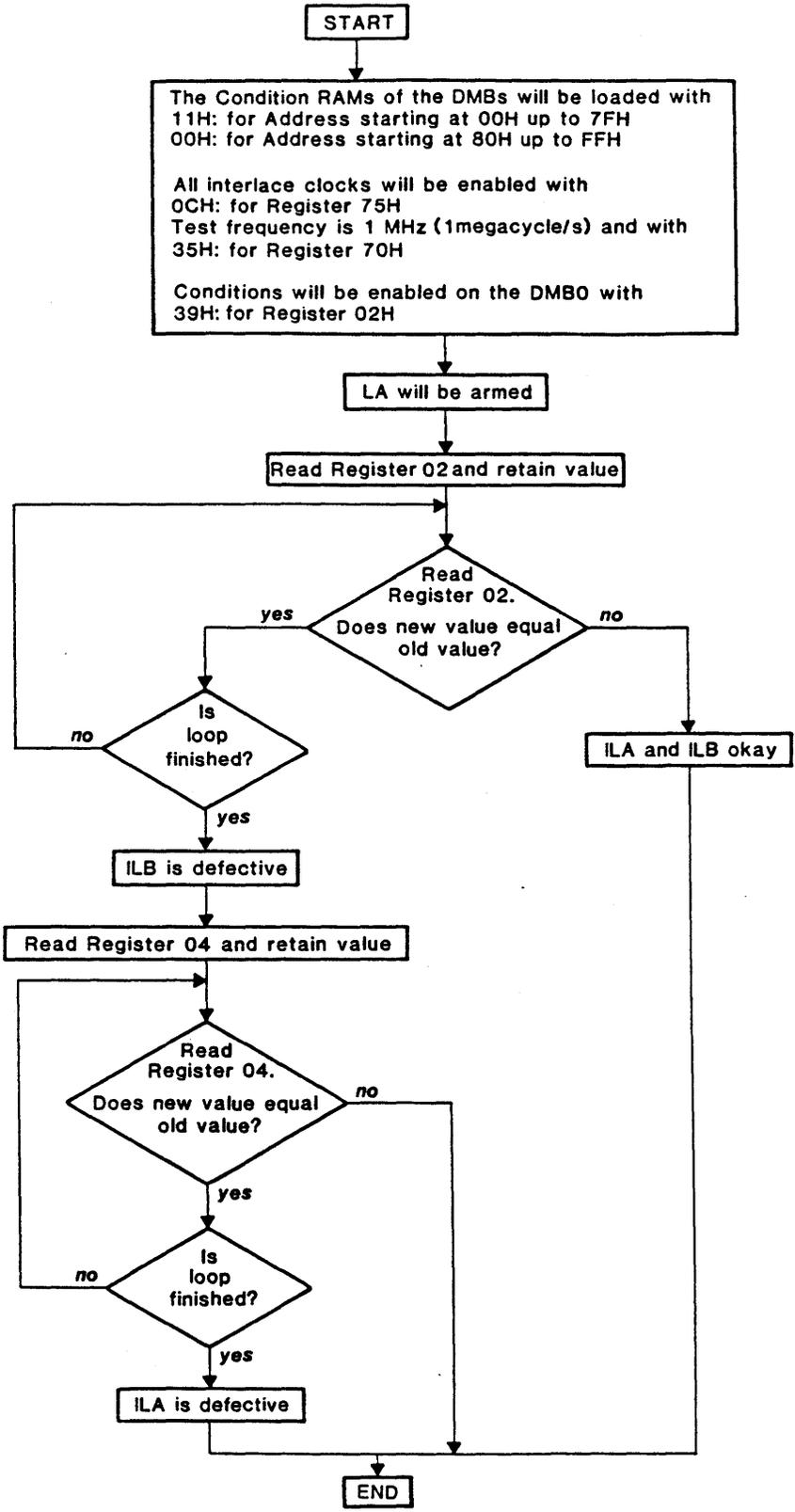


Figure 4-4. ILAB12 Flowchart

4.5 INTERLACE CLOCKS ILA1, ILB1, ILA2 AND ILB2 TEST

Name of the test in the source listing: ILAB12

In the Single-Test Menu of the LDP: Special Test 06

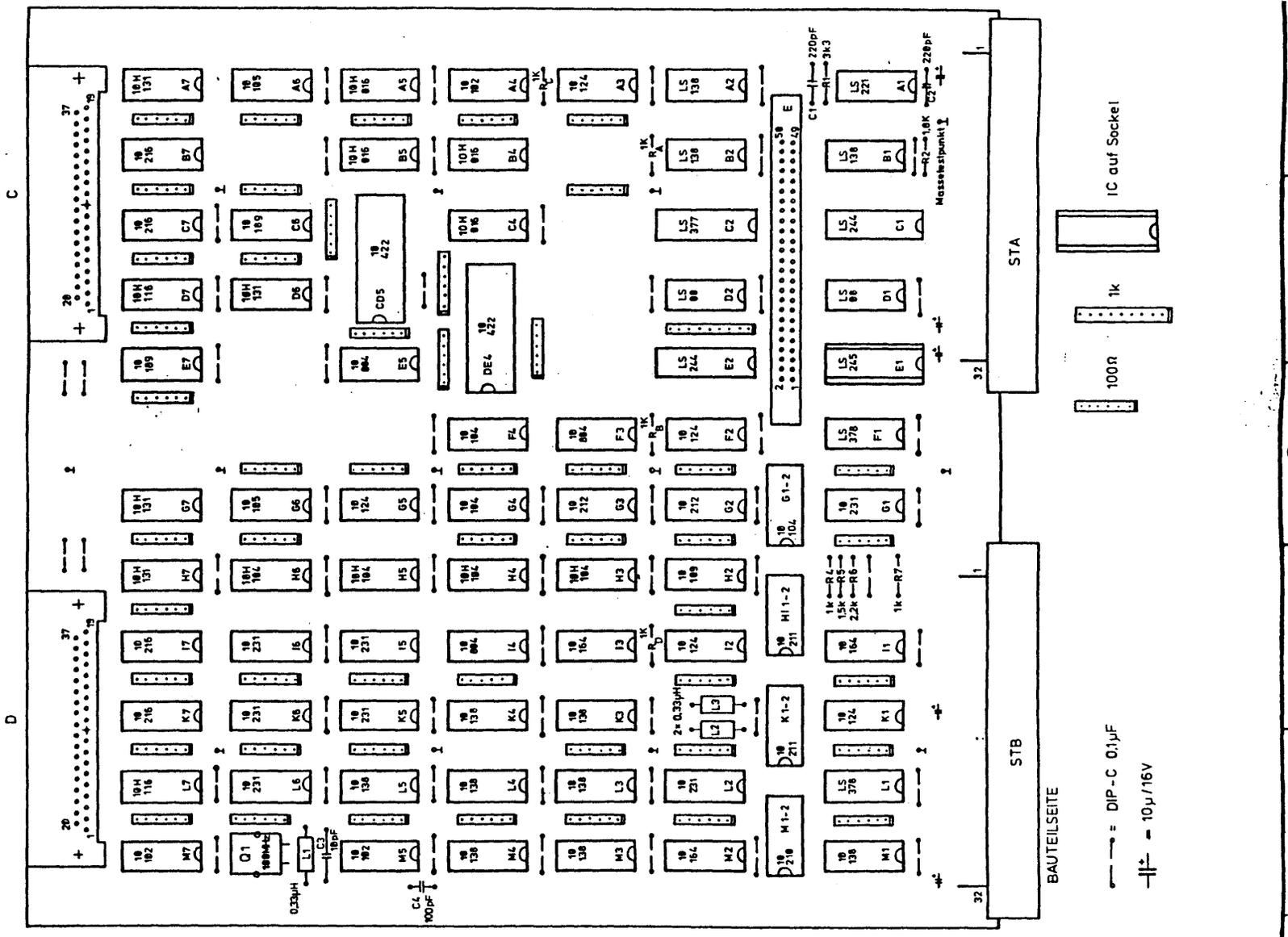
Purpose: ILAB12 determines if the interlace clocks are present, if they are selected properly, and indicates whether they are processed.

Reasons for negative test results:

- Control error on the TBQ (Register 75H, bits 2 and 3).
- Errors in the interlace clocks themselves.

This page intentionally left blank

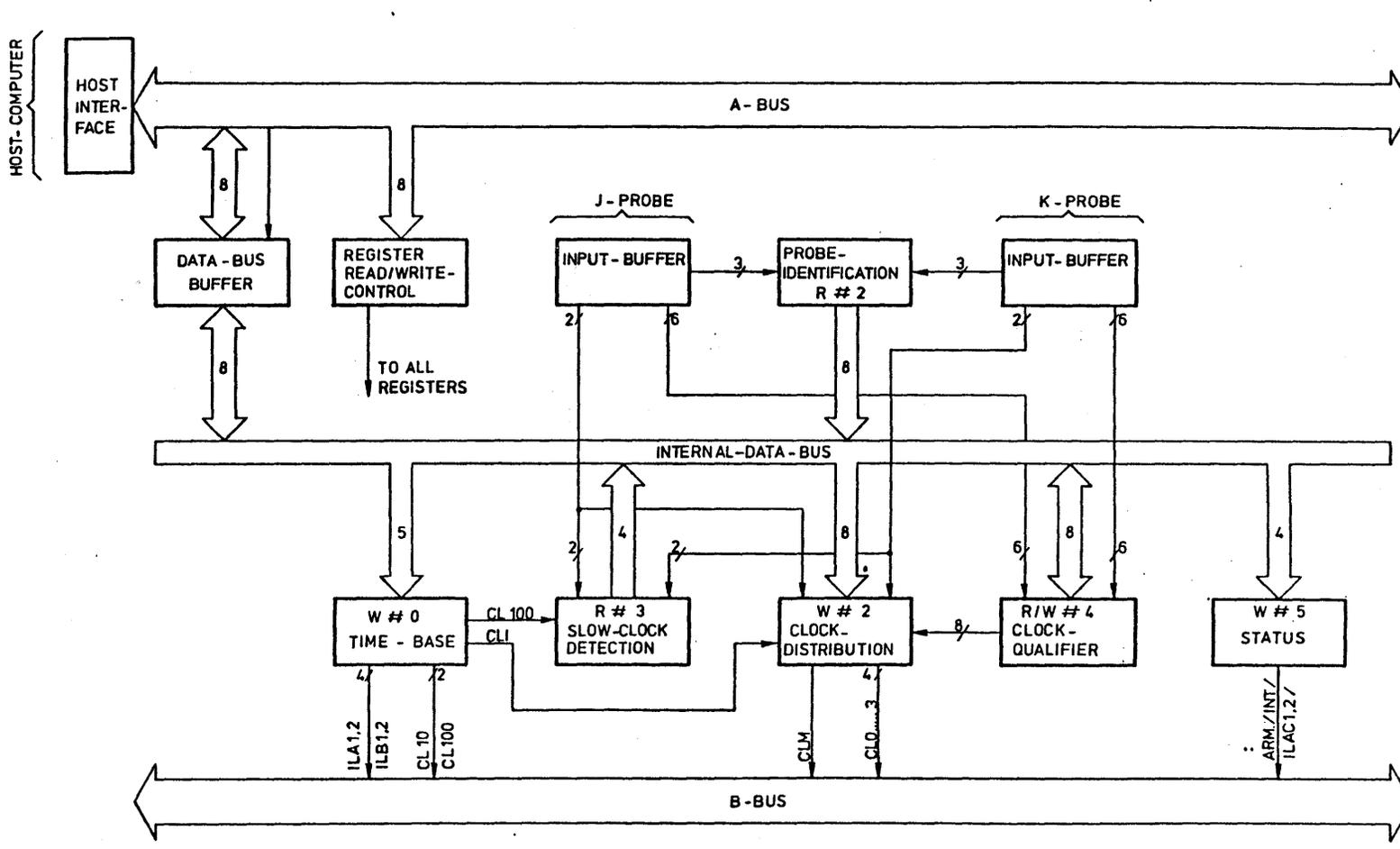
Für diese Zeichnung bestehen
vier Los- und Rücklötlötstellen



EE	Tag	Name	Benennung	KLA - SP-TBQ	
Bearb.	09.81	HE			
Gepr.	26.1.82	<i>Heid</i>			
3.1		211.83	1/2		
1.4	145	20.4.82	1/2		
1.3	144	19.4.82	1/2		
	139	2.3.82	1/2		
1.2		26.1.82	1/2		
Rev.	Anderungs-Nr.	Tag	Name	Zeichn.-Nr.	312
				zu Gerät	zu Anlage



BAUTEILSEITE
 — = DIP-C 0.1µF
 — = 10µ/16V



Die Daten sind ausschließlich für den internen Gebrauch bestimmt.

			Tag	Name	Benennung KLA-TBQ TIME BASE QUALIFIER	Blatt-Nr. 312
			Bearb. 10.7.81	Hönsel		
			Gepr. 26.1.82	Hönsel	Zeichn.-Nr. 312	Blatt-Nr. v. Bl.
3.1			2.11.83	Vg		
1.4	145		20.4.82	Hönsel	zu Gerät	zu Anlage
1.3	144		19.4.82	Hönsel		
1.2			26.1.82	Hönsel		
Rev.	Anderungs-Nr.	Tag	Name			

GND E-2,4,6,8,10
 GND E-17,16,18,20
 GND E-26,28,30,32
 GND E-34,36,38,40
 GND E-42,44,46,48

DA0 E-1
 DA1 E-3
 DA2 E-5
 DA3 E-7
 DA4 E-9
 DA5 E-11
 DA6 E-13
 DA7 E-15
 TRG E-50

BS0/ A-17c
 BS1/ A-18c
 BS2/ A-19c
 BS3/ A-20c
 BS4/ A-21c
 BS5/ A-22c
 BS6/ A-23c
 BS7/ A-24c
 BS8/ A-16c

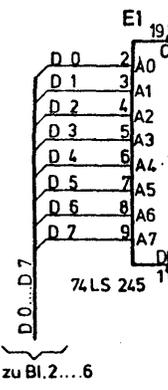
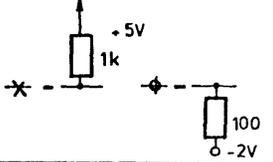
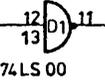
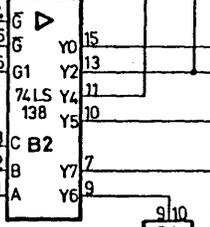
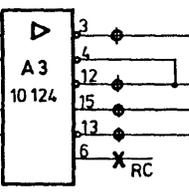
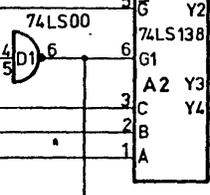
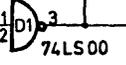
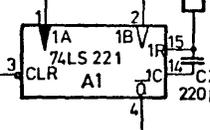
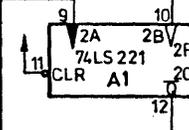
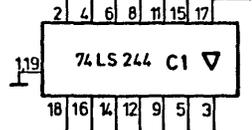
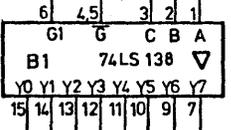
RA0 A-4c
 RA1 A-5c
 RA2 A-6c
 RA3 A-7c

DB0 E-24
 DB1 E-21
 DB2 E-22
 DB3 E-23
 DB4 E-49

ASTB/ E-17
 BSTB/ E-43

BRDY E-45

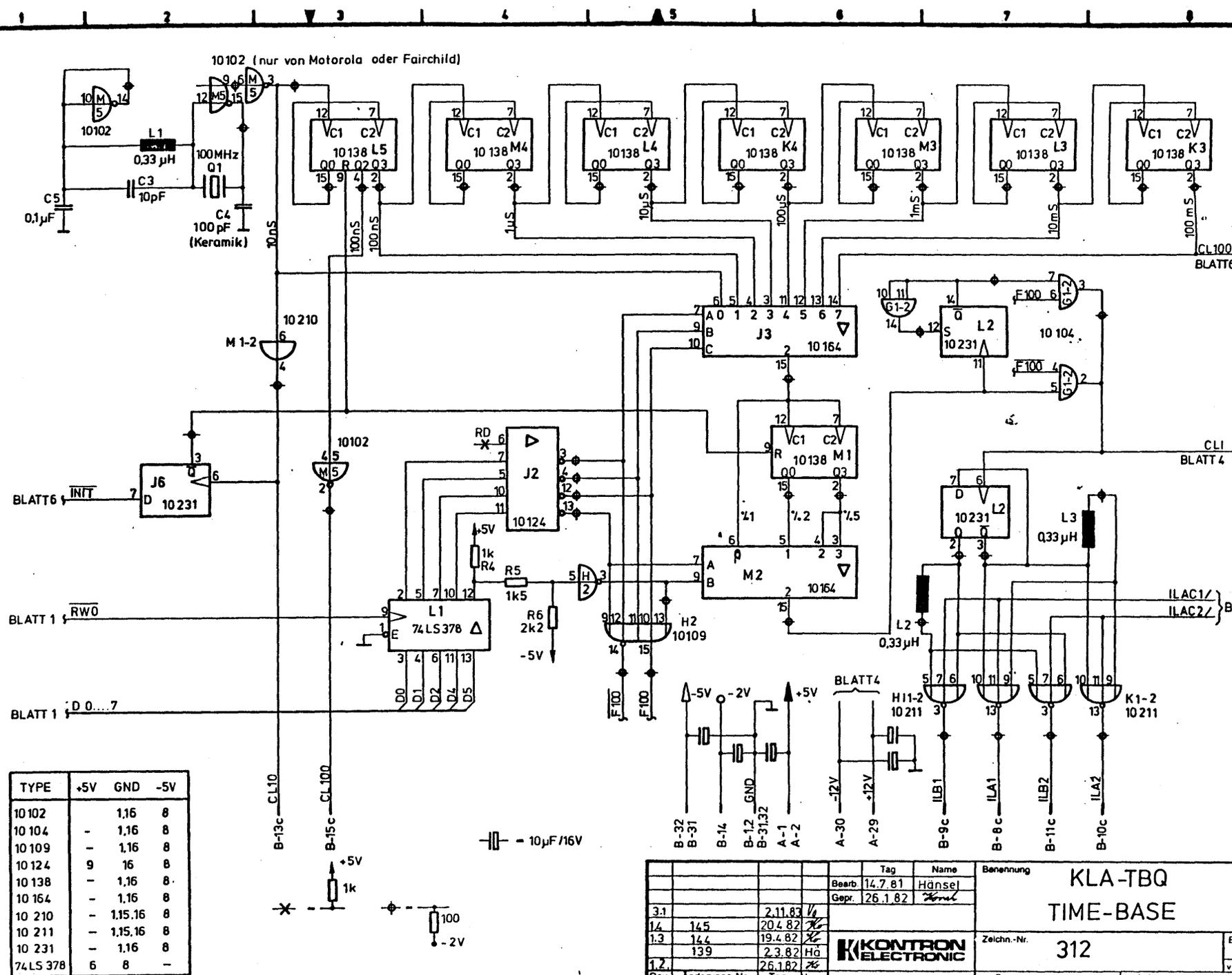
ARDY E-19



TYPE	+5V	GND	-5V
74LS00	14	7	-
74LS138	16	8	-
74LS221	16	8	-
74LS244	20	10	-
74LS245	20	10	-
10124	9	16	8

zu Bl. 2...6

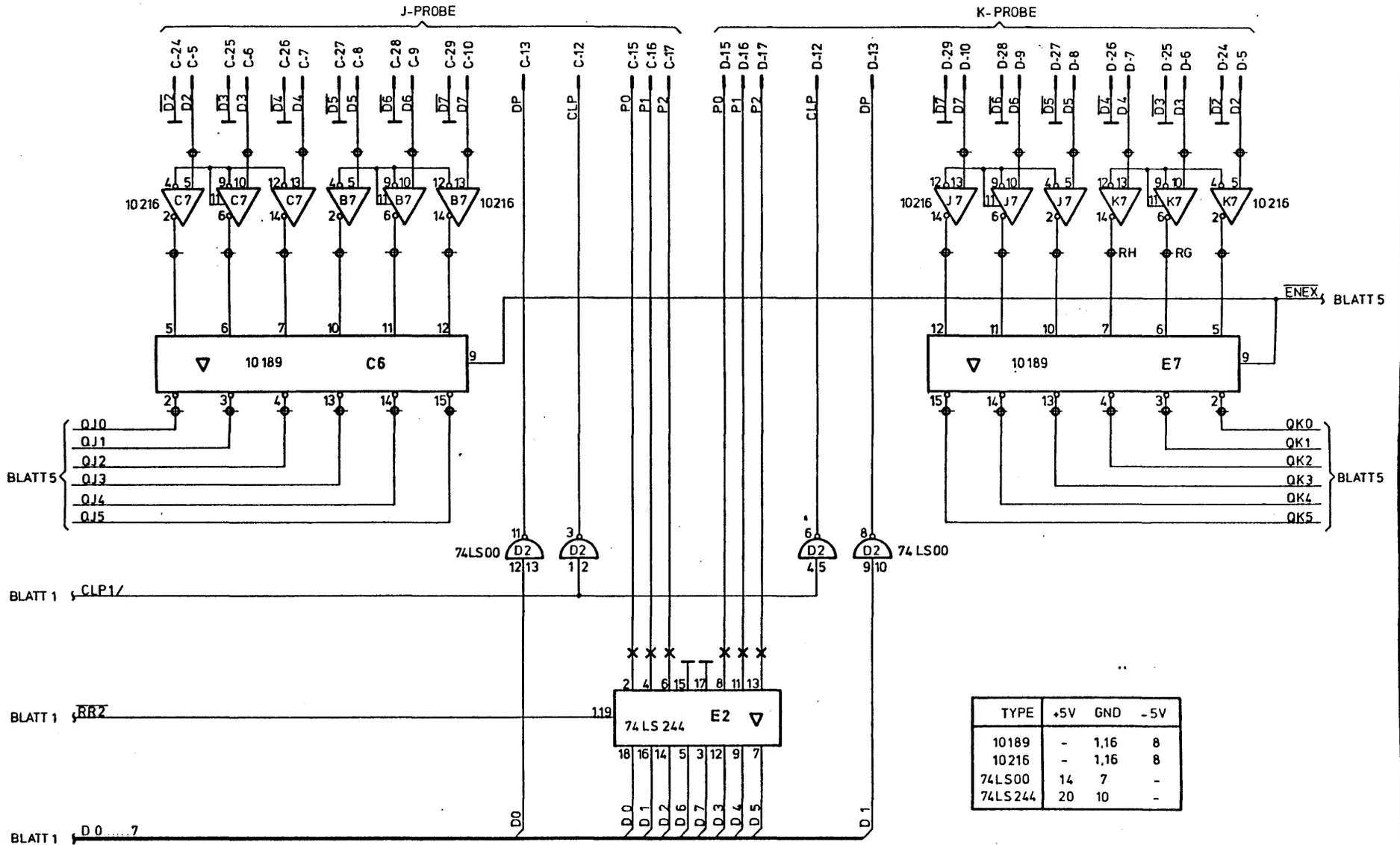
Rev.	Anderungs-Nr.	Tag	Name	Benennung	Blatt-Nr.
3.1		2.11.83	/	KLA - TBQ HOSTINTERFACE, REGISTER-CONTROL	1
1.4	145	20.4.82	/		
1.3	144	19.4.82	/		
1.2		26.1.82	/		
Tag: 13.7.81 Name: Hänagl Gepr.: 26.1.82 Name: <i>Hänagl</i>				Benennung: KLA - TBQ HOSTINTERFACE, REGISTER-CONTROL	Blatt-Nr.: 1 v. 6 Bl.
Rev. 1.2 Tag: 26.1.82 Name: <i>Hänagl</i>				Zeichn.-Nr.: 312	zu Gerät: zu Anlage:



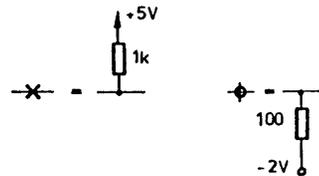
TYPE	+5V	GND	-5V
10102		1,16	8
10104	-	1,16	8
10109	-	1,16	8
10124	9	16	8
10138	-	1,16	8
10164	-	1,16	8
10210	-	1,15,16	8
10211	-	1,15,16	8
10231	-	1,16	8
74LS378	6	8	-

Bearb. 14.7.81		Name Hnsel		Benennung	KLA-TBQ TIME-BASE
Gepr. 26.1.82		Hnsel			
3.1	2.11.83			Zeichn.-Nr. 312	Blatt-Nr. 2 v. 6 Bl.
14	14.5	20.4.82			
1.3	14.4	19.4.82			
	139	2.3.82			
1.2	26.1.82			zu Gerat	zu Anlage
Rev.	Änderungs-Nr.	Tag	Name		

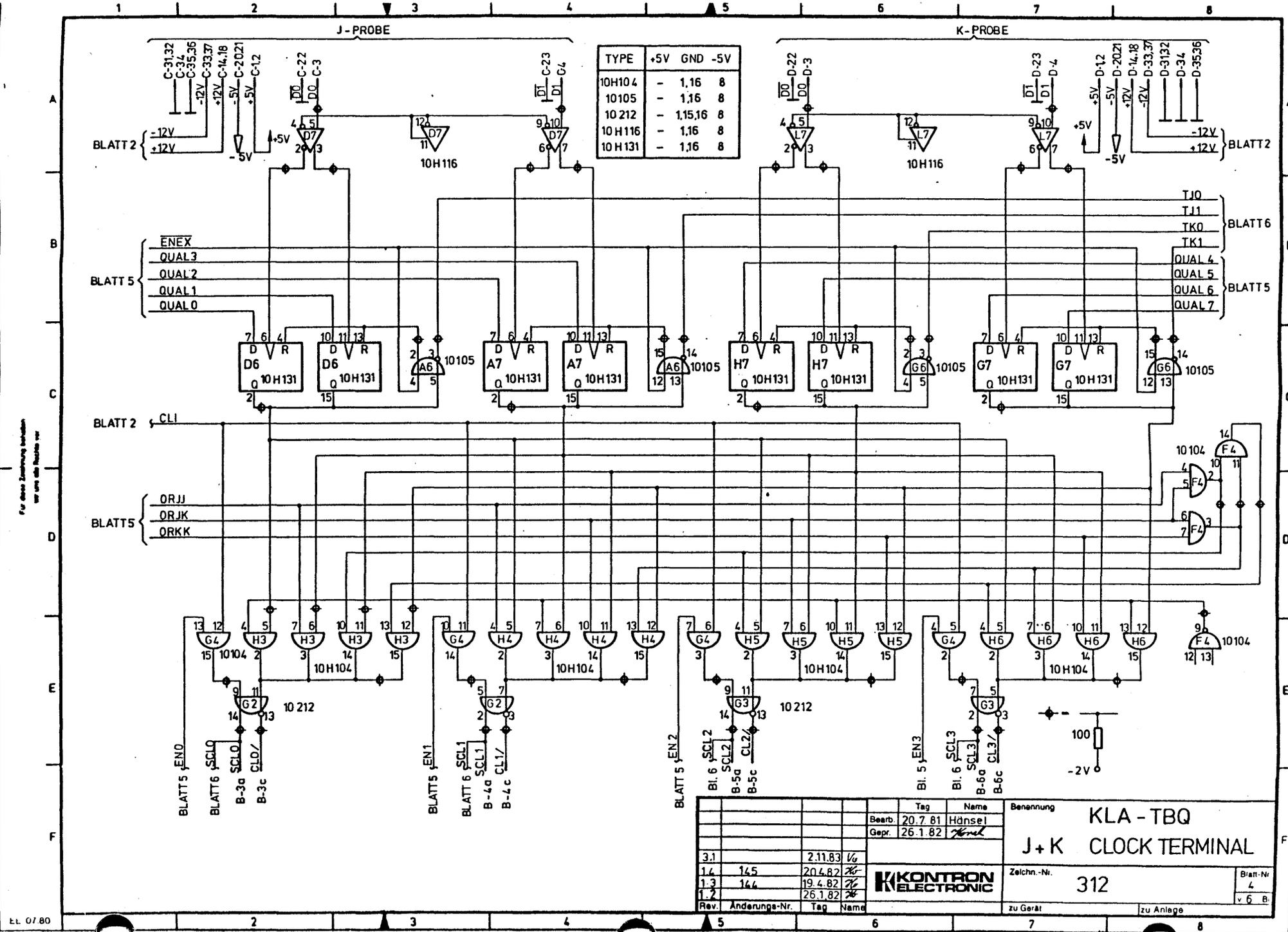
Für diese Zeichnung bestehen
vier von drei Blättern vor



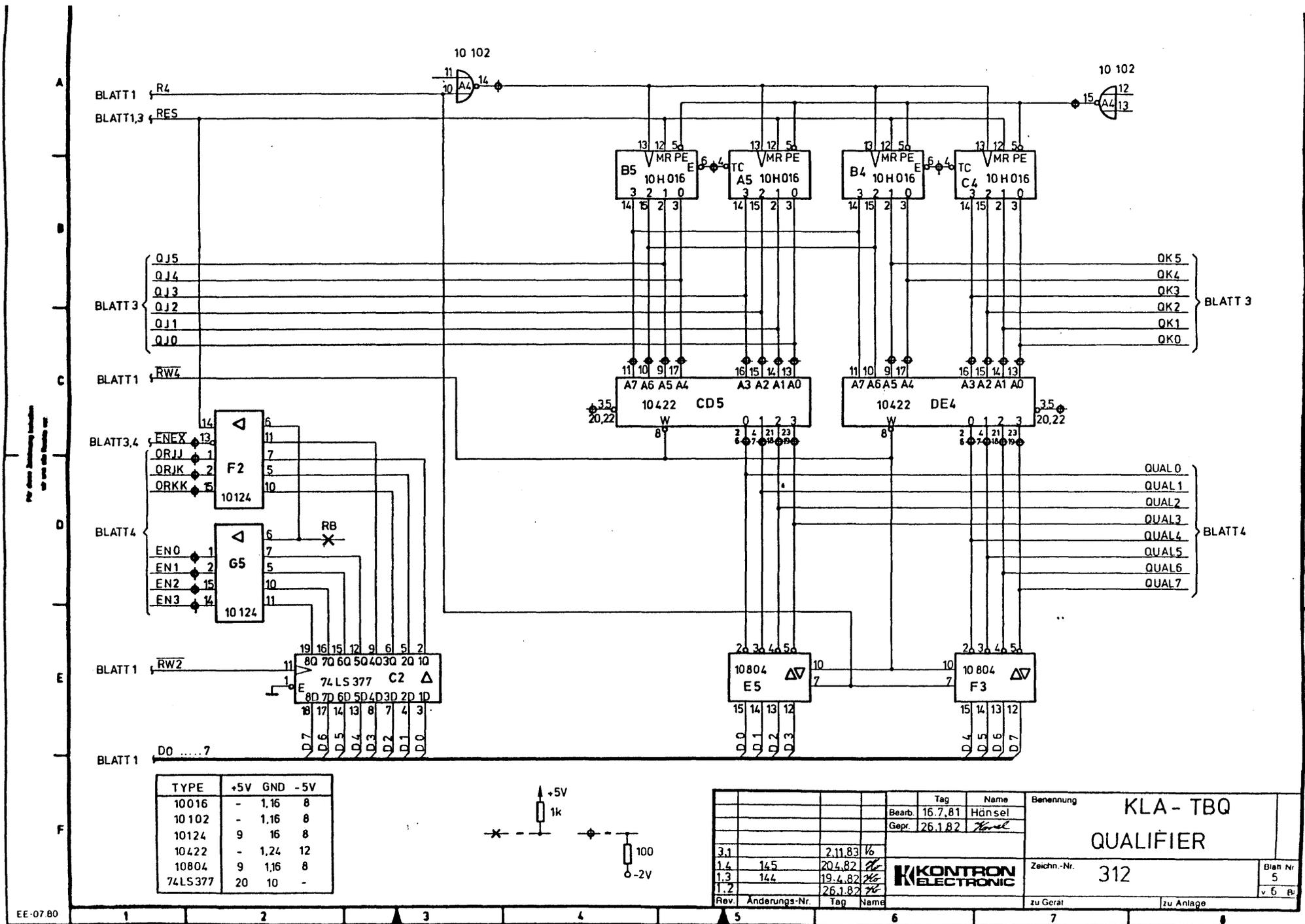
TYPE	+5V	GND	-5V
10189	-	1,16	8
10216	-	1,16	8
74LS00	14	7	-
74LS244	20	10	-



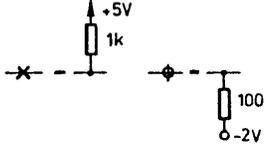
Rev.	Anderungs-Nr	Tag	Name	Benennung	KLA - TBQ J+K- QUALIFIER TERMINAL	Zeichn.-Nr. 312	Blatt Nr 3 v. 6 Bl
3.1		2.11.83	H				
1.4	145	20.4.82	Z				
1.3	144	19.4.82	Z				
1.2		26.1.82	Z				
Bearb.		21.8.81	Hänsel				
Gepr.		26.1.82	M				
KONTRON ELECTRONIC				zu Gerät	zu Anlage		



Für diese Zeichnung bestehen wir uns als Rechte vor

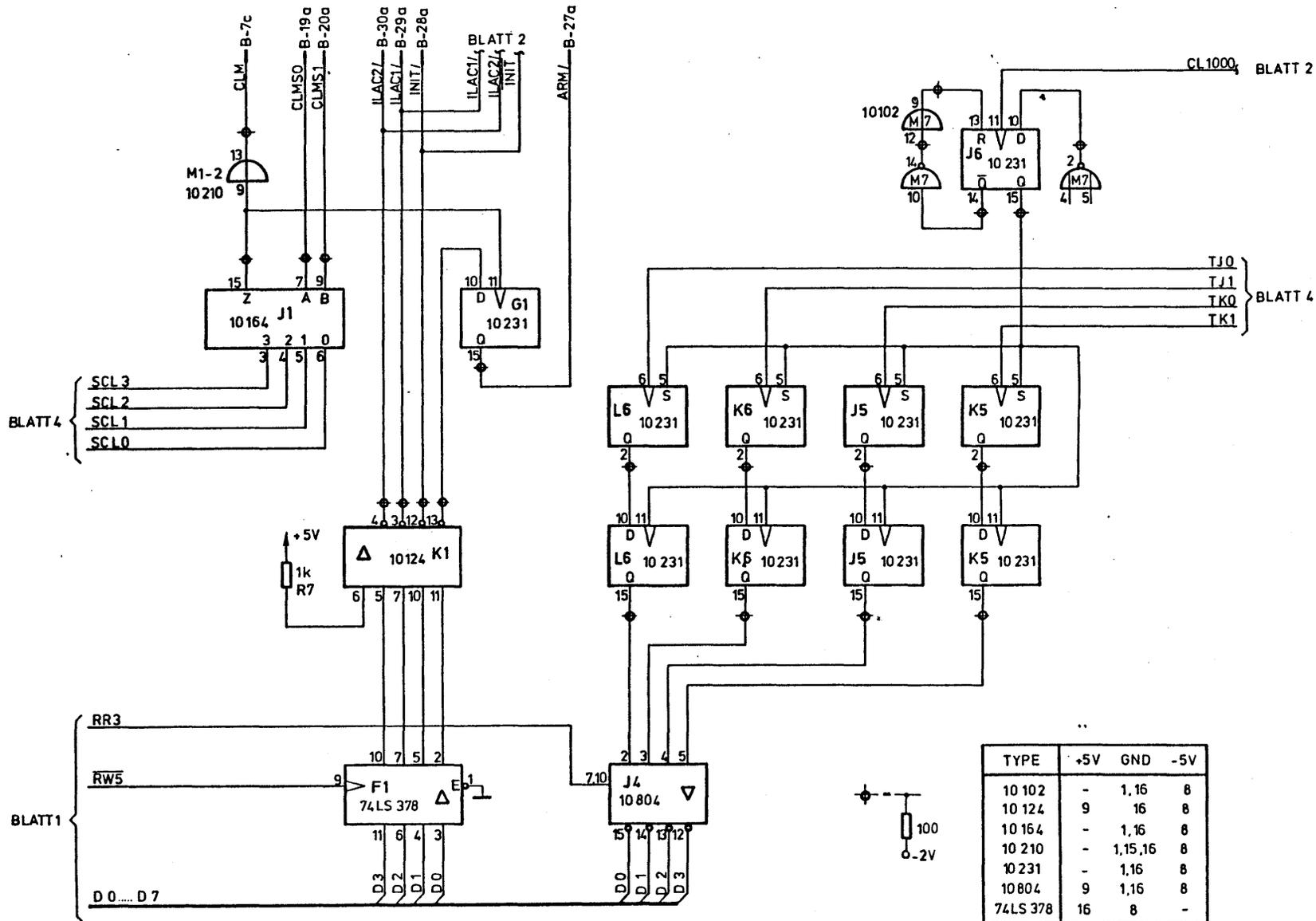


TYPE	+5V	GND	-5V
10016	-	1,16	8
10102	-	1,16	8
10124	9	16	8
10422	-	1,24	12
10804	9	1,16	8
74LS377	20	10	-



Rev.	3.1	1.4	1.3	1.2	2.11.83	204.82	19.4.82	26.1.82	Tag	Name	Benennung	KLA - TBQ QUALIFIER	Zeichn.-Nr. 312	Blatt Nr. 5
Rev.	3.1	1.4	1.3	1.2	2.11.83	204.82	19.4.82	26.1.82	Tag	Name	Benennung			
Rev.	3.1	1.4	1.3	1.2	2.11.83	204.82	19.4.82	26.1.82	Tag	Name	Benennung	Blatt Nr. 5		





	Tag	Name	Benennung KLA - TBQ MASTER-CLOCK-SELECT SLOW - CLOCK-DETECT	Zeichn.-Nr. 312	Blatt Nr. 6 v 6 Bl.
	Bearb.	16.7.81 Hansel			
	Gepr.	26.1.82 <i>Korn</i>			
3.1		2.11.83 <i>V</i>	KONTRON ELECTRONIC	zu Gerat	zu Anlage
1.4	1.45	20.4.82 <i>Z</i>			
1.3	1.44	19.4.82 <i>Z</i>			
1.2		26.1.82 <i>Z</i>			
Rev.	Änderungs-Nr.	Tag	Name		

SEQ TESTS

This chapter contains the tests listed below for the Trigger Sequencer Controller (SEQ) board. The flowchart for each test (if applicable) precedes the description of the test. Schematics for the SEQ board are at the end of the chapter.

- 5.1 Level Counter and Occurrence Counter Test
- 5.2 Trigger Filter 0 Test
- 5.3 Trigger Filter 1 Test

Kontron LA Diagnostic Program (SMK-LA-1010-01)

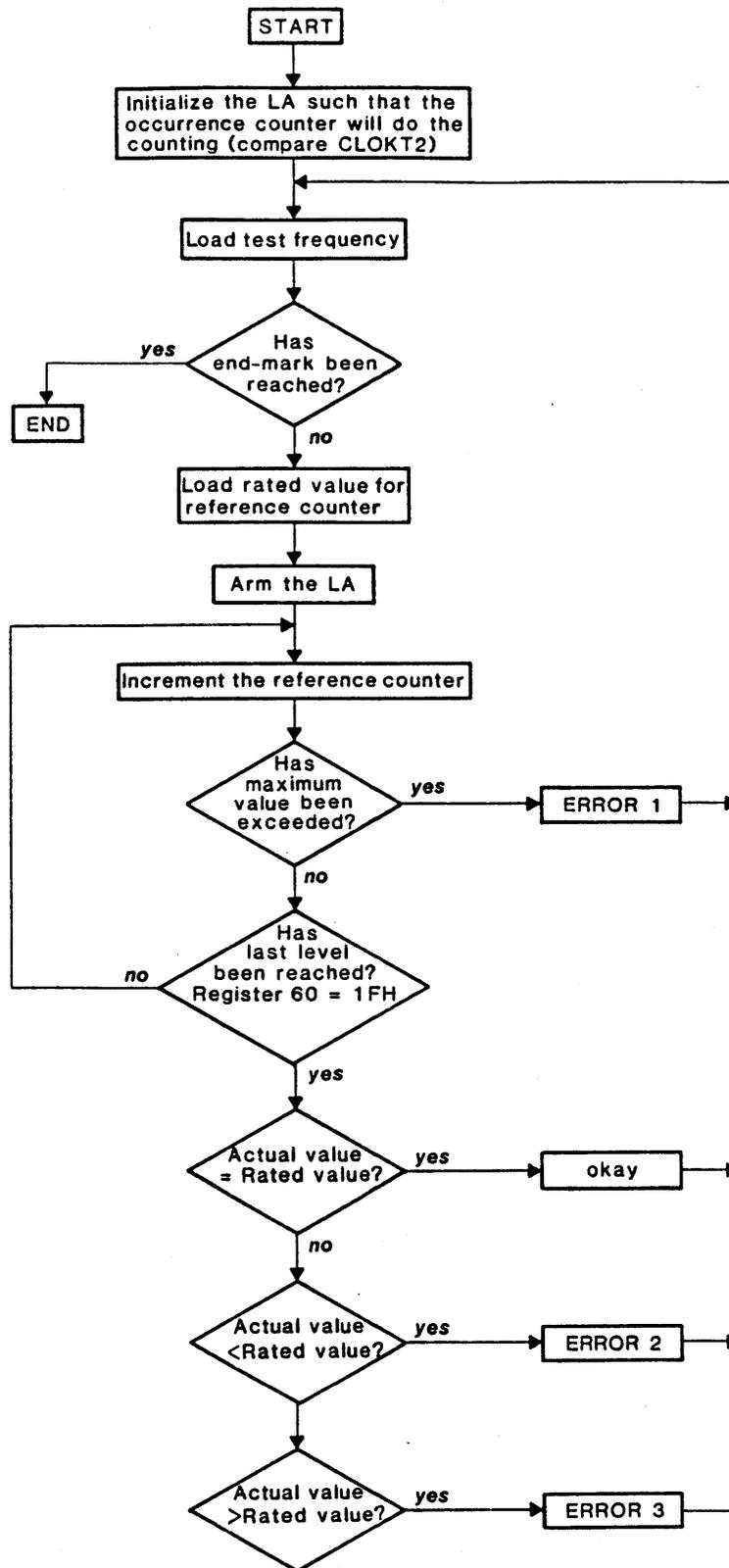


Figure 5-1. LEVINC Flowchart

5.1 LEVEL COUNTER AND OCCURRENCE COUNTER TEST

Name of the test in the source listing: LEVINC
In the Single-Test Menu of the LDP: Special Test 04

Purpose: LEVINC determines if the occurrence counter is loaded properly at every level, if it counts properly, and if the passage through all trigger levels takes place at the right time.

Description of errors:

Error 1:

The reference counter has reached a value of 8,000H; thus, it is safe to assume that the last level is not reached.

Possible causes:

- It is unlikely that the occurrence counter "got stuck" in one of the levels.
- The occurrence counter probably does not work at all.

Error message in the program:

"Last level was not reached"

Error 2:

The last level was reached, but too late.

Possible causes:

- The level counter does not increment.
- The occurrence counter is loaded improperly.
- The occurrence counter counts improperly.
- Errors in the data line of Register 60H.

Error message in the program:

"Last level was reached too late"

Error 3:

The last level was reached, but too early.

Same causes as in Error 2

Error message in the program:

"Last level was reached too early"

5.2 TRIGGER FILTER 0 TEST

Name of the test in the source listing: TRGFLO
In the Single-Test Menu of the LDP: Special Test 07

Purpose: TRGFLO determines if the trigger filter for Condition 0 (increment) is in proper working condition.

Reasons for negative test results:

- Trigger filter is loaded improperly.
- Trigger filter does not operate properly.
- Error in the logic (which is influenced by the trigger filter).

In principle, the sequence of operation in this test is the same as in LEVINC. The differences between the two tests are:

- Only one test frequency of 100 kHz (100 kilocycles/s)
- In Level Status RAM, trigger filter 0 is enabled (1 AH)

5.3 TRIGGER FILTER 1 TEST

Name of the test in the source listing: TRGF11
In the Single-Test Menu of the LDP: Special Test 08

Purpose: TRGF11 determines if the trigger filter for Condition 1 (JUMP) is in proper working condition.

Reasons for negative test results:

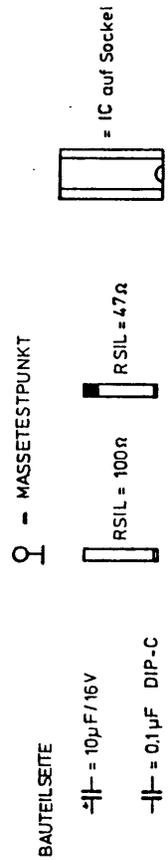
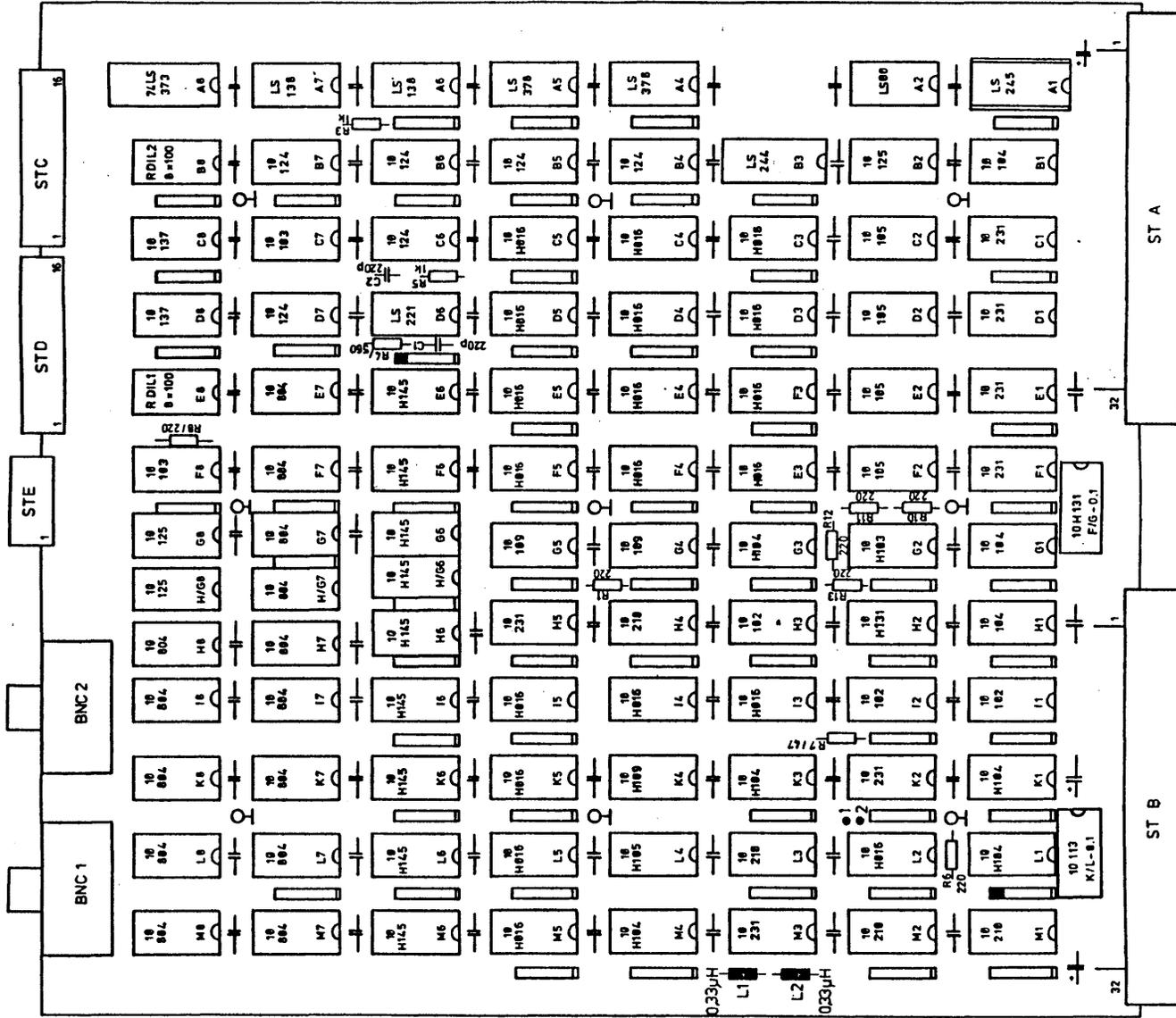
- Trigger filter is loaded improperly.
- Trigger filter does not operate properly.
- Error in Condition 1 (JUMP).
- Error in the logic (which is influenced by the trigger filter).

In contrast to TRGF10, the Level Status RAM is loaded with 19H (enable trigger filter 1) and the Condition RAMs are loaded with EEH (Condition 0 is not active; Condition 1 is active). Otherwise, Special Test 08 is conducted in the same way as Special Test 07.

NOTE: This is the only test that uses the condition JUMP. It checks to see that the JUMP to every level is conducted properly.

This page intentionally left blank

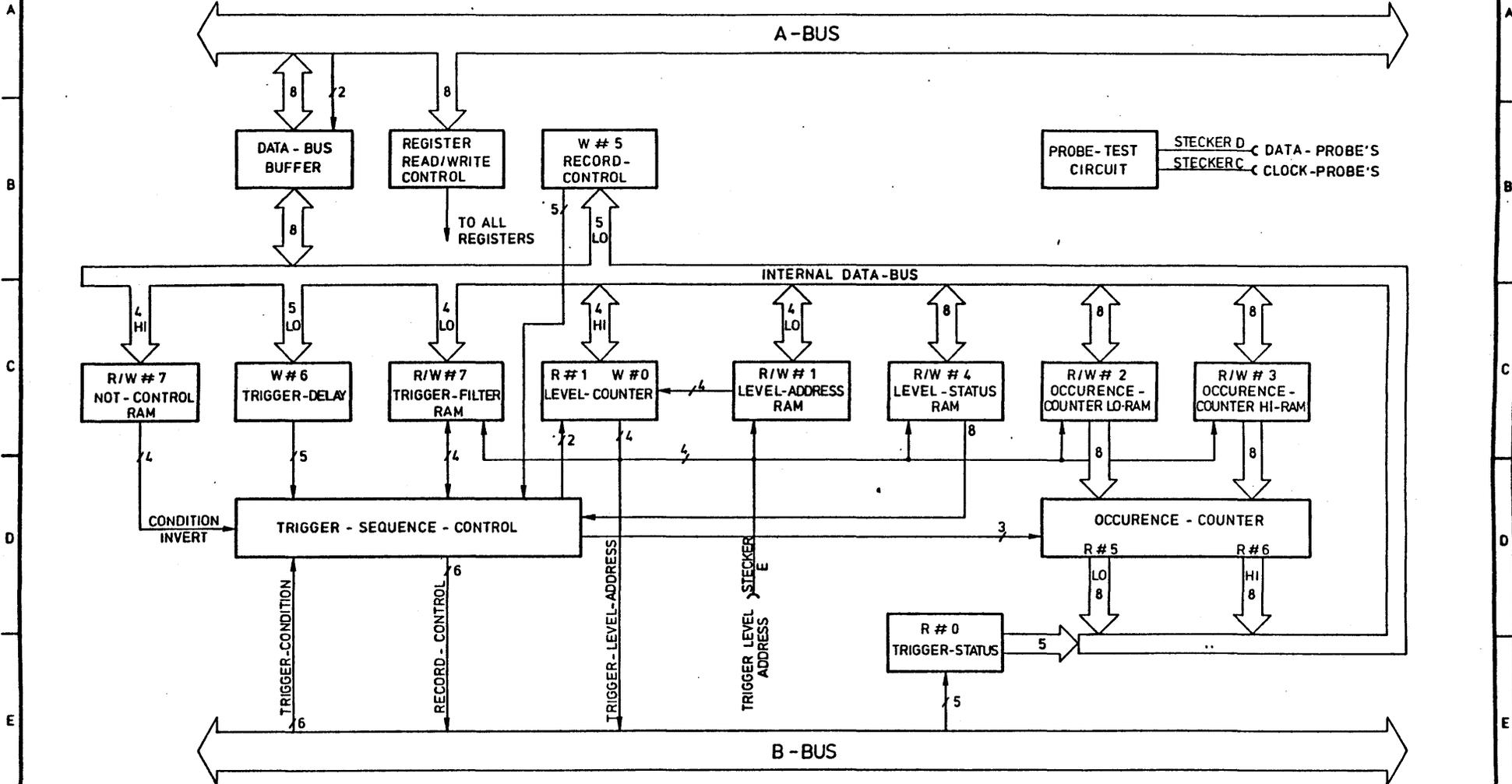
Für diese Zeichnung gelten die in der Normenliste aufgeführten Normen.



Rev	Änderungs-Nr.	Tag	Name	Benennung	Blatt-Nr.
3.1		2.11.83	HE	KLA - SEQ BESTÜCKUNGSSKIZZE	313
1.4	153	15.7.82	HE		
1.3	146	20.4.82	HE		
1.2	143	19.4.82	HE		
1.1		27.1.82	HE		

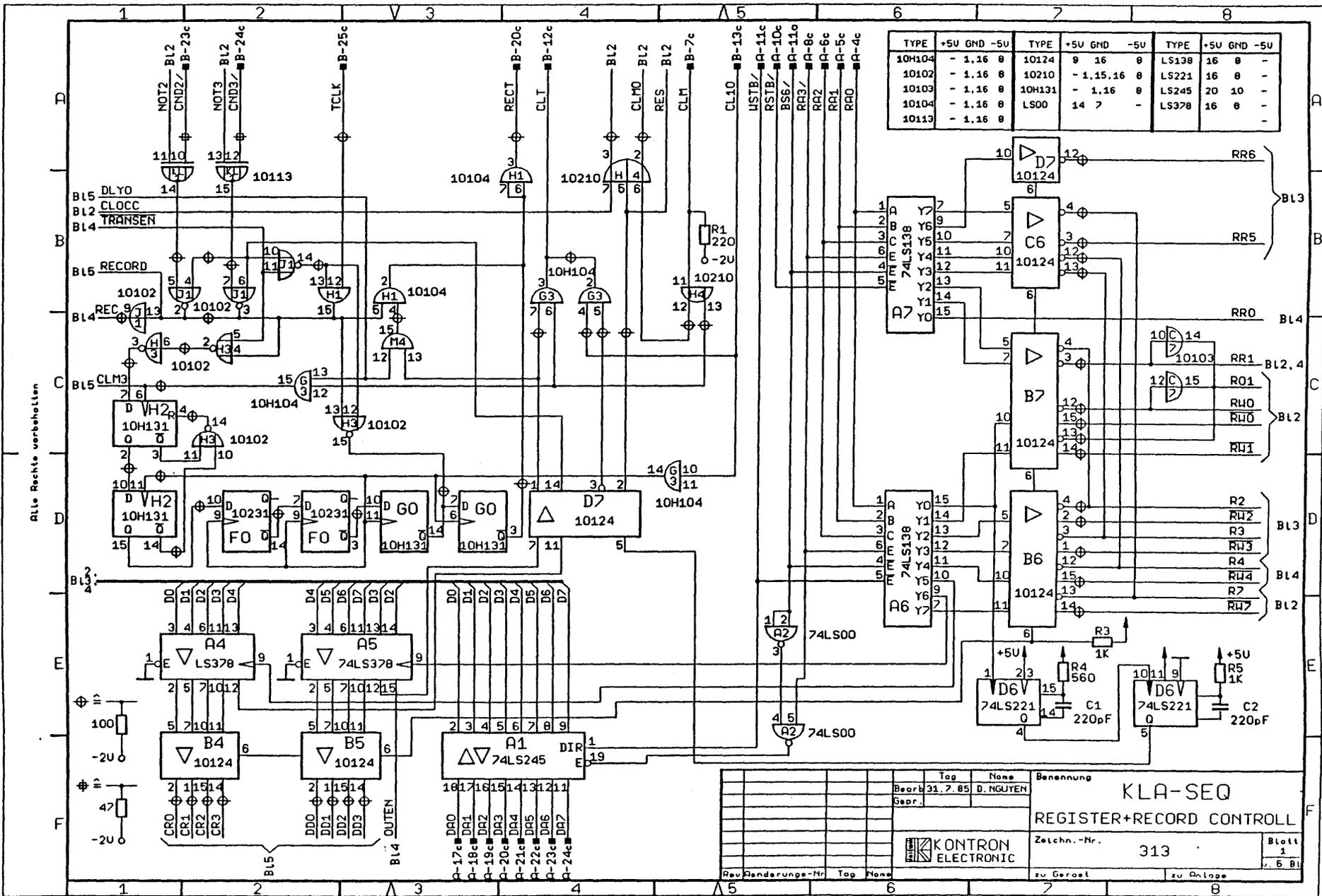
EE	Tag	Name	Benennung
Bearb.	08.81	HE	
Gepr.	24.1.81	HE	
KONTRON ELECTRONIC			Zeichn.-Nr.
			zu Gerät
			zu Anlage

1 2 3 4 5 6 7 8



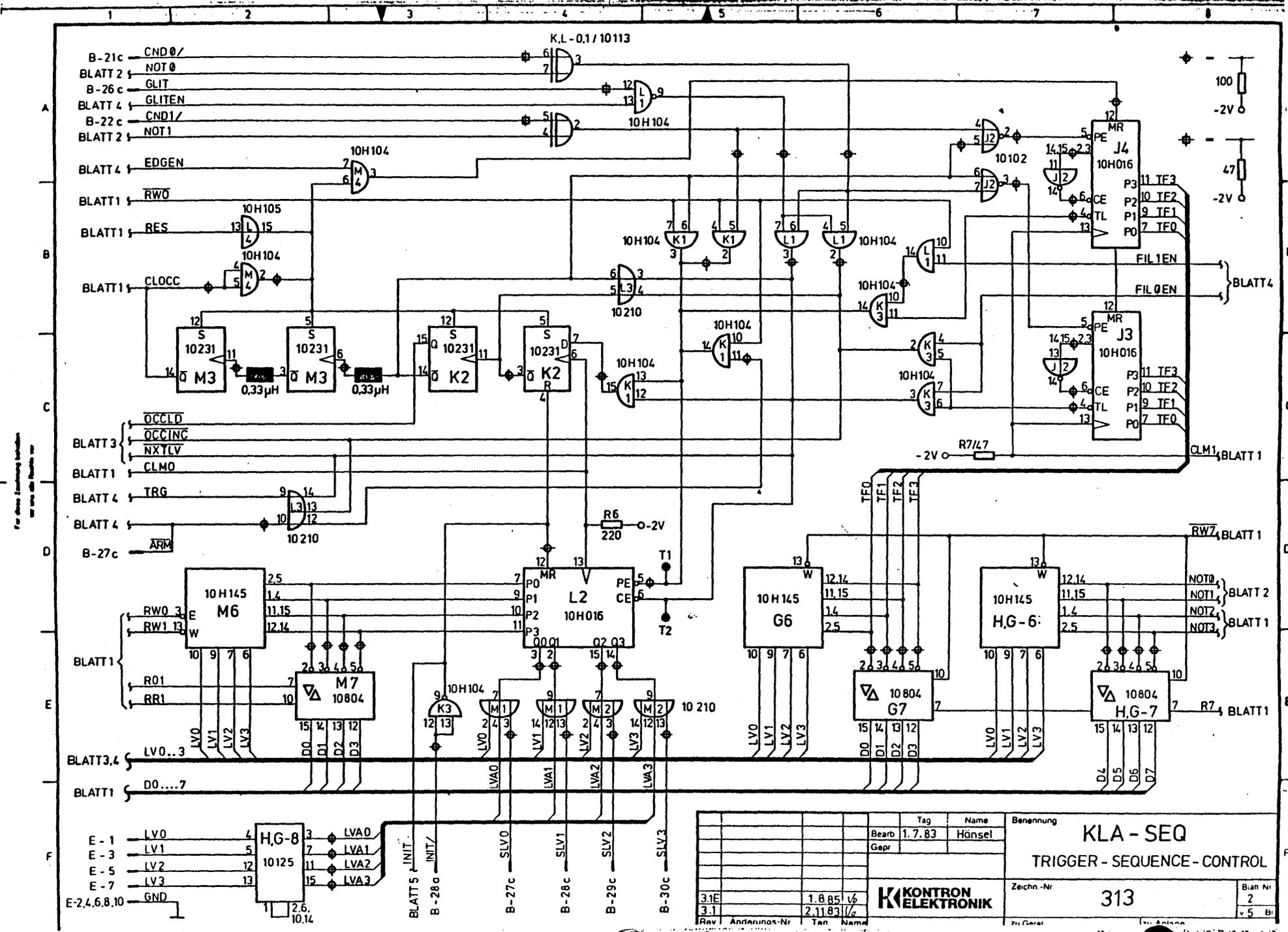
Für diese Zeichnung bestehen
keine weiteren Änderungen

			Tag	Name	Benennung	KLA - SEQ SEQUENCE-CONTROL	Blatt-Nr.
			Bearb. 20.7.81	Hänsel	313		
			Gepr. 29.1.82	Hänsel		Zeichn.-Nr.	313
3.1		2.11.83	✓				
1.4	153	15.7.82	✓				
1.3	146	20.4.82	✓				
1.2	143	19.4.82	✓				
1.1		27.1.82	✓				
Rev.	Änderungs-Nr.	Tag	Name	zu Gerät		zu Anlage	



Alle Rechte vorbehalten

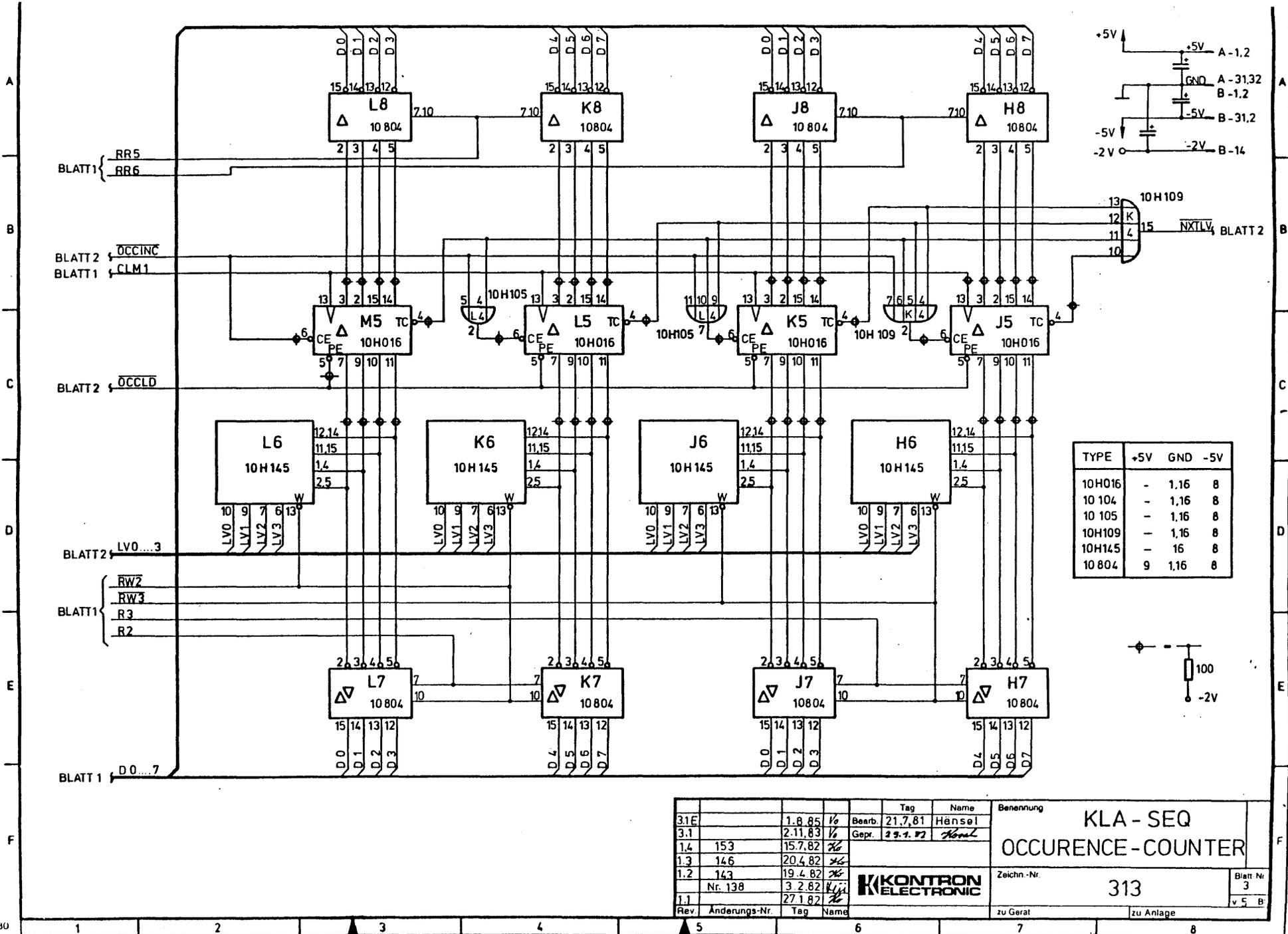
Rev. Änderungen-Nr.		Tag	Name	Benennung	
		31.7.85	D. NGUYEN	KLA-SEQ	
				REGISTER+RECORD CONTROL	
		KONTRON ELECTRONIC		Zeichn.-Nr. 313	
				Blatt 1	
				zu Gerüst 5 Bl	
				zu Anlage	



Tag		Name		Benennung	
Bearb.	1.7.83	Hänsel		KLA - SEQ	
Gepr.				TRIGGER - SEQUENCE - CONTROL	
Zu Gepr.				Zeichn.-Nr. 313	
Rev. Änderungs-Nr.				Blatt Nr. 2	
Tan. Name				v. 5. Bl.	

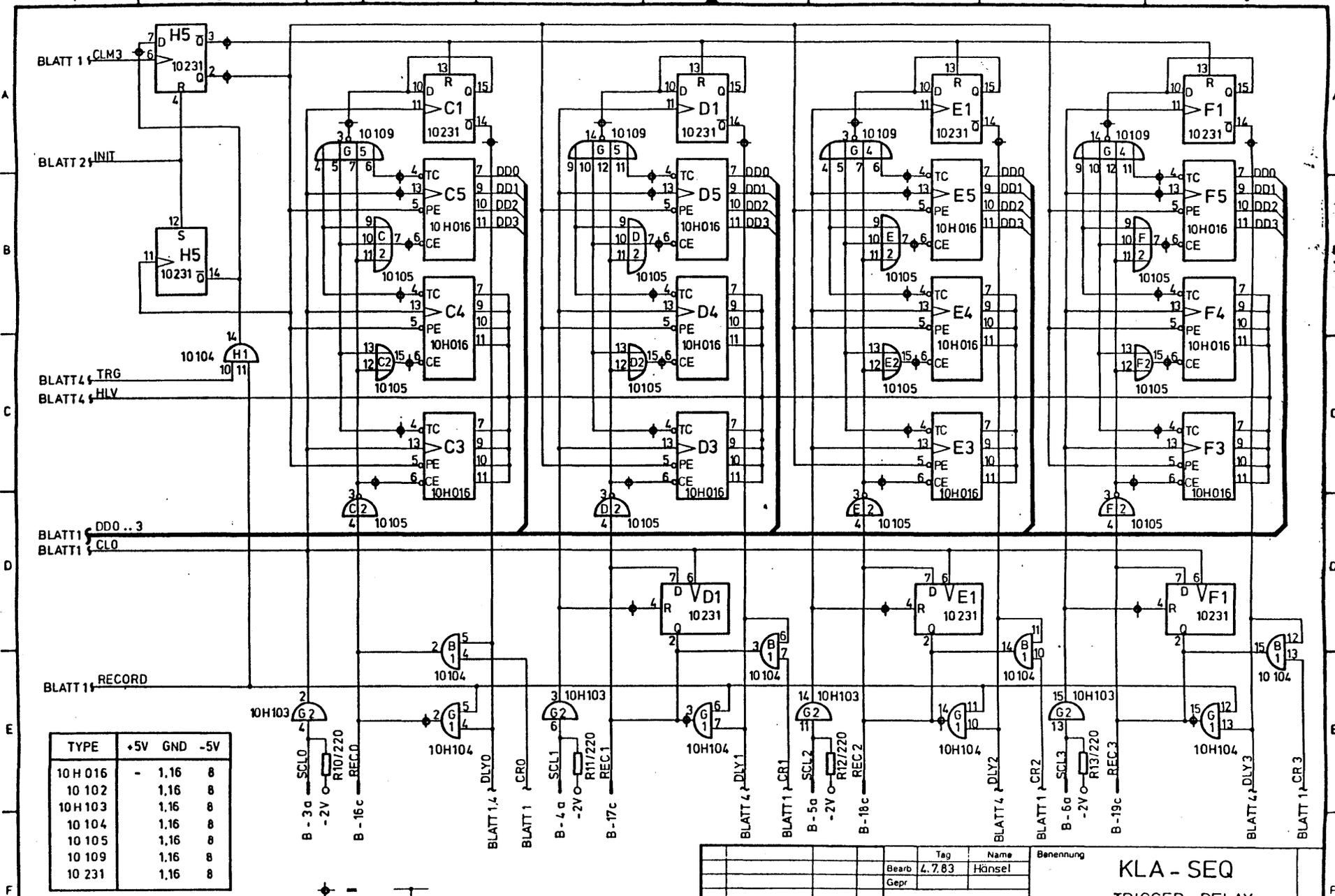


Für diese Zeichnung bestehen
keine weiteren Blätter



TYPE	+5V	GND	-5V
10H016	-	1.16	8
10 104	-	1.16	8
10 105	-	1.16	8
10H109	-	1.16	8
10H145	-	16	8
10804	9	1.16	8

3.1F	1.8.85	1/0	Bearb.	21.7.81	Hänsel	Benennung KLA - SEQ OCCURENCE-COUNTER	Zeichn.-Nr. 313	Blatt-Nr. 3		
3.1	2.11.83	1/0	Gepr.	29.7.82	Hänsel					
1.4	15.7.82	1/0	KONTRON ELECTRONIC					zu Gerät	zu Anlage	
1.3	14.6	20.4.82								1/0
1.2	14.3	19.4.82								1/0
1.1	Nr. 138	3.2.82								1/0
Rev	Anderungs-Nr.	Tag	Name							



TYPE	+5V	GND	-5V
10H016	-	1,16	8
10102		1,16	8
10H103		1,16	8
10104		1,16	8
10105		1,16	8
10109		1,16	8
10231		1,16	8

Tag		Name		Benennung	
4.7.83		Hönsel		KLA - SEQ	
Gepr				TRIGGER - DELAY	
31E		1.8.85 1/2		Zeichn.-Nr	
3:1		2.11.83 1/2		313	
Rev.		Anderungs-Nr.		zu Gerät	
Tag		Name		Izu Anlage	
		KONTRON ELEKTRONIK		Blatt-Nr	
				5	
				v 5 Bl.	

Für diese Schaltung sind die Bauteile mit den folgenden Bezeichnungen zu verwenden:

DMB TESTS

This chapter contains the tests listed below for the Data Memory Board (DMB). There can be up to four of these boards, which are numbered 0 through 3. The flowchart for each test (if applicable) precedes the description of the test. Schematics for the DMB board are at the end of the chapter.

- 6.1 Condition GLIT Test
- 6.2 All Trigger-Delay-Counters Test
- 6.3 Glitch-Latch Test
- 6.4 Transitional Clocking Signal (TCLK) Test
- 6.5 Conditions 2 and 3 (Data Qualified Recording) Test
- 6.6 Probe Test
- 6.7 DMB Inputs and Additional Data RAM Test

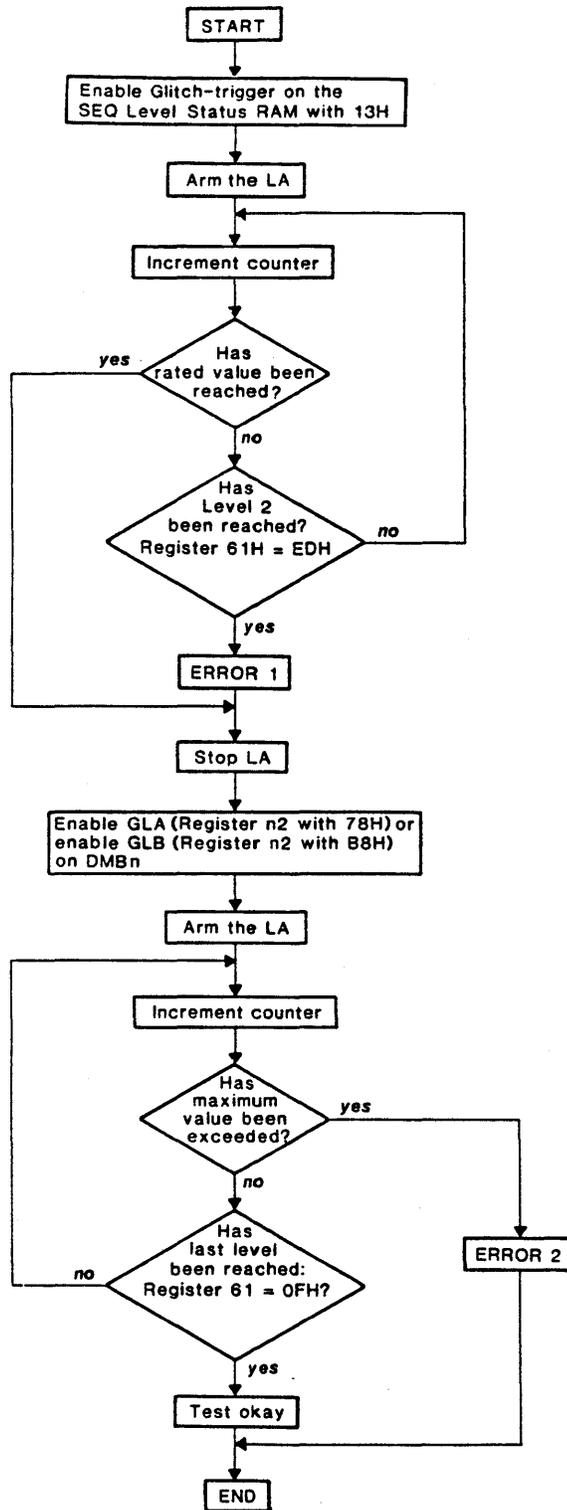


Figure 6-1. GLAGLB Flowchart

6.1 CONDITION GLIT TEST

Name of the test in the source listing: **GLAGLB**
In the Single-Test Menu of the LDP: **Glitch Tests Condition**

Purpose: GLAGLB determines if Condition GLIT is selected properly by each DMB, if Condition GLIT is received properly by the SEQ, and if it is processed.

Description of errors:

Error 1:

Although glitch was not enabled on the DMBs, Level 2 was reached on the SEQ. As a result, Condition GLIT is always active.

Possible causes:

- If errors occur in all eight tests, the cause for the errors is probably found on the SEQ.

Example: Line GLIT, short circuit on low

- If errors occur only in some of the tests, the cause for the errors is probably found on the respective DMB.

Example: Control error in Register 2 on the respective DMB

Error message in the program:

"Condition glit error"

Error 2:

The last level was not reached, probably due to a missing Condition GLIT.

Possible causes:

- If errors occur in all eight tests, the cause for errors is probably found on the SEQ.

Examples: Line GLIT, short circuit on high
Line GLIT interrupted

Possible causes (continued):

- If errors occur in only some of the tests, the cause for the errors is probably found on the respective DMB.

Example: Control error in Register 2 on the respective DMB

Error message in the program:

"Condition glit is missing"

This page intentionally left blank

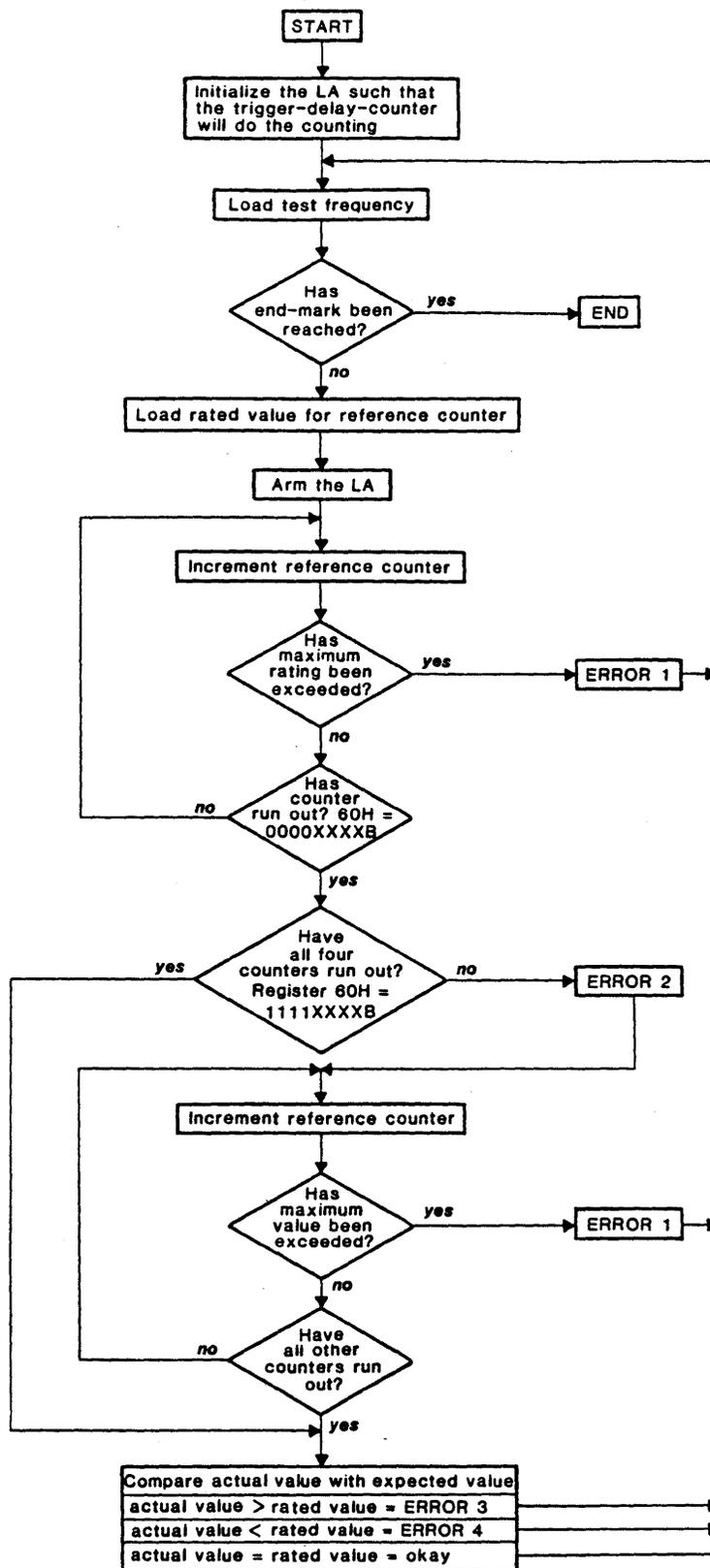


Figure 6-2. DELCNT Flowchart

6.2 ALL TRIGGER-DELAY-COUNTERS TEST

Name of the test in the source listing: DELCNT
In the Single-Test Menu of the LDP: Special Test 05

Description of errors:

Error 1:

The maximum value (8,000H loops) of the reference counter was reached. As a result, no trigger-delay-counter ran out.

Error 2:

At least one trigger-delay-counter has run out. However, not all four trigger-delay-counters have completed the run.

By now, all trigger-delay-counters have run out, but the timing of the work cycle was wrong.

Error 3:

Trigger-delay-counter ran out too late.

Error 4:

Trigger-delay-counter ran out too early.

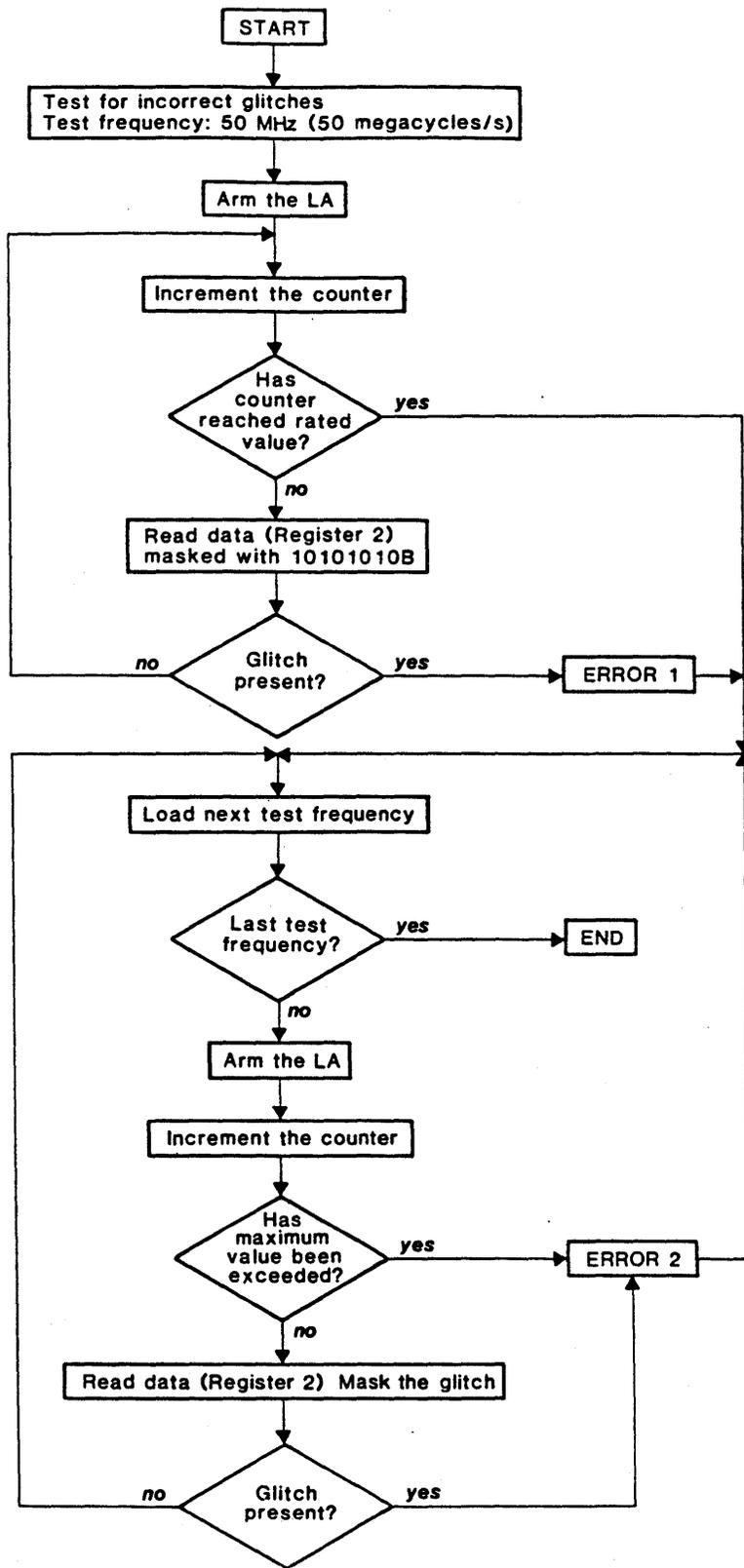


Figure 6-3. GLIT Flowchart

6.3 GLITCH-LATCH TEST

Name of the test in the source listing: **GLIT**
In the Single-Test Menu of the LDP: **Glitch-Latch Tests**

Purpose: GLIT determines if all glitch-latches on the DMBs are working properly.

Description of errors:

Error 1:

Glitches were detected, although no glitches should appear at a test frequency of 50 MHz (50 megacycles/s).

Possible causes:

- Defective FLIP-FLOP at respective input.
- Control error in Register 2 on the respective DMB.

Error message in the program:

"Test of false occurring glitches":

Glitch-latch 01	error/ok
Glitch-latch 03	error/ok
Glitch-latch 05	error/ok
Glitch-latch 07	error/ok

Error 2:

No glitch appeared, although the respective glitch-latch at this particular test frequency should recognize the input signals as glitches.

Possible causes:

- Defective FLIP-FLOP at respective input.
- Control error in Register 2 on the respective DMB.

Error message in the program:

"Test of false missing glitches":

Glitch-latch 01	error/ok
Glitch-latch 03	error/ok
Glitch-latch 05	error/ok
Glitch-latch 07	error/ok

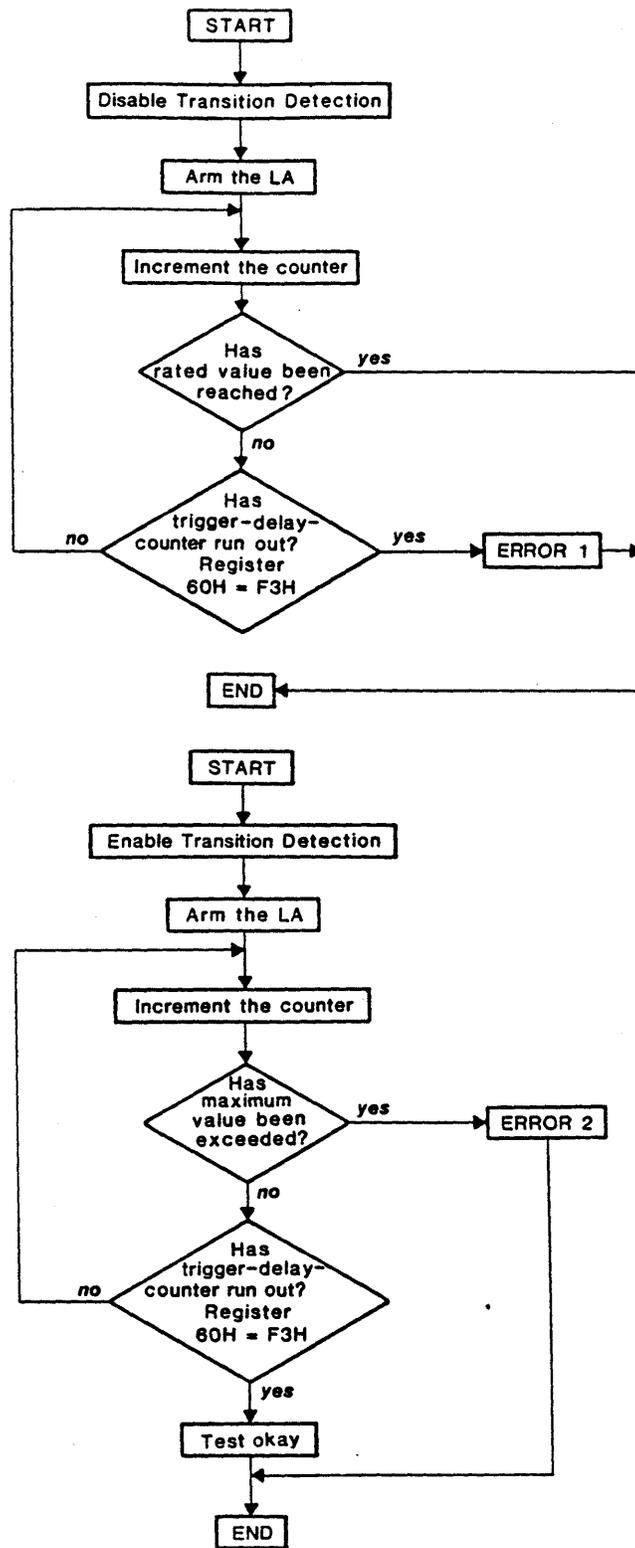


Figure 6-4. TRANS Flowchart

6.4 TRANSITIONAL CLOCKING SIGNAL (TCLK) TEST

Names of the test in the source listing: TRANS
In the Single-Test Menu of the LDP: Transition Tests

Purpose: TRANS determines if the transitional clocking signal (TCLK) is triggered by the DMBs and processed by the SEQ.

Description of errors:

Error 1:

The trigger-delay-counters on the SEQ have run out, although the TRANSITION DETECTION command on the DMBs was disabled. As a result, the transitional clocking signal (TCLK) is permanently active.

Possible causes:

- TCLK short circuit on high.
- Control error in Register 2 on the respective DMB (TRANSITION DETECTION cannot be disabled).

Error message in the program:

"Test of false occurring transitions error"

Error 2:

Trigger-delay-counters on the SEQ did not run out within the maximum time allowed for testing, although TRANSITION DETECTION command on the respective DMB was enabled.

Possible causes:

- If errors occur in all eight tests, the cause for the errors is probably found on the SEQ.

Example: Conductor TCLK, short circuit on low

- If errors occur only in some of the tests, the cause for the errors is probably found on the respective DMB.

Example: Control error in Register 2 on the respective DMB

Error message in the program:

"Transitional clocking signal (TCLK) error"

Kontron LA Diagnostic Program (SMK-LA-1010-01)

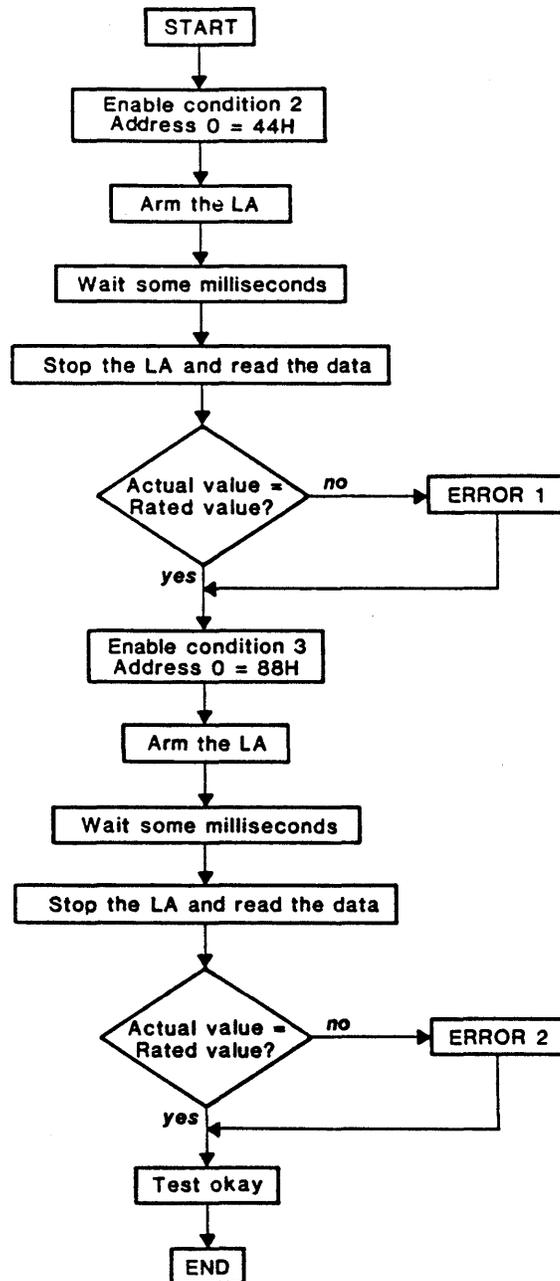


Figure 6-5. DATAQUAL Flowchart

6.5 CONDITIONS 2 AND 3 (DATA QUALIFIED RECORDING) TEST

Name of the test in the source listing: DATAQUAL
In the Single-Test Menu of the LDP: Qualified Recording Test

Purpose: DATAQUAL determines if Conditions 2 and 3 are generated properly by the DMBs and if they are properly processed by the SEQ.

Description of errors:

Error 1:

The data measured does not correspond with the rated values (01, 02, 03, 04, 05, 06, 07, 08, 09, 00, 01, etc.). Condition 2 was set for this data.

Possible cause:

- Errors on the conductor CND2.

Error message in the program:

"Condition 2 error"

Error 2:

The data measured does not correspond with the rated values (01, 02, 03, 04, 05, 06, 07, 08, 09, 00, 01, etc.). Condition 3 was set for this data.

Possible cause:

- Errors on the conductor CND3.

Error message in the program:

"Condition 3 error"

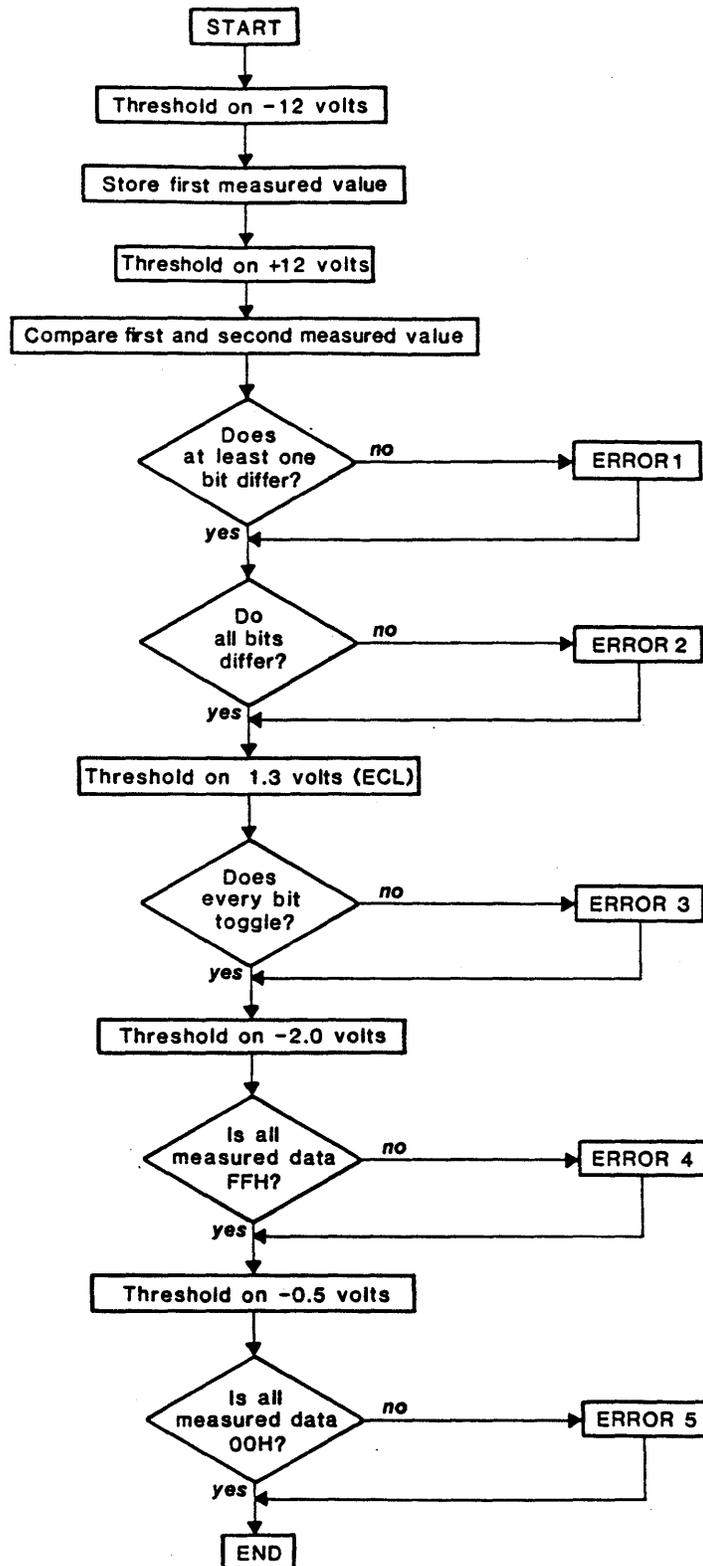


Figure 6-6. PROBETS Flowchart

6.6 PROBE TEST

Name of the test in the source listing: PROBETS
In the Single-Test Menu of the LDP: Probe Tests

Purpose: PROBETS determines if all data probes are working properly.

Description of errors:

Error 1:

In the first and second tests results all bits have the same value, although the threshold is adjusted to -12 volts for the first test and to +12 volts for the second test.

Possible causes:

- Errors in the data transfer from the TBQ to the probe.
- Errors in threshold hardware of the probe.

Error 2:

The first and second tests results showed that not all bits differed.

Possible causes:

- Amplifier in the probe is defective.
- ECL compactor in the probe is defective.

Error message in the program for Test 2:

"Test of all channels via changing threshold voltage"
(Error message is indicated separately for each channel.)

Error 3:

Although the threshold is adjusted to -1.3 volts (ECL threshold), some of the bits never alternate their polarity.

Possible causes:

- Test configurator wire or UPR is defective.
- Amplifier in the probe is defective.

Error message in the program for Test 3:

"Test of all channels via ECL input signal"
(Error message is indicated separately for each channel.)

Kontron LA Diagnostic Program (SMK-LA-1010-01)

Error 4:

Although the threshold is adjusted to -2.0 volts, not all data was FFH. If Error 3 did not occur, Error 4 indicates an undershoot or a negative offset.

Possible cause:

- Amplifier in the probe is defective or misaligned.

Error message in the program for Test 4:

"Test of overshoot respectively positive offset voltage"
(Error message is indicated separately for each channel.)

Error 5:

Although the threshold is adjusted to -0.5 volts, not all data is 00H. If Error 3 did not occur, Error 5 indicates an overshoot or a positive offset.

Possible cause:

- Amplifier in the probe is defective or misaligned.

Error message in the program for Test 5:

"Test of undershoot respectively negative offset voltage"
(Error message is indicated separately for each channel.)

6.7 DMB INPUTS AND ADDITIONAL DATA RAM TEST

Name of the test in the source listing: PODTS
In the Single-Test Menu of the LDP: Input Tests

Purpose: PODTS determines if all memory data on the DMBs supplied by the pattern generator is recorded. Possible addressing errors in the DMB Data RAMs are recognized, because the recorded pattern is induced by a decimal counter.

The pattern generator on the SEQ is tested.

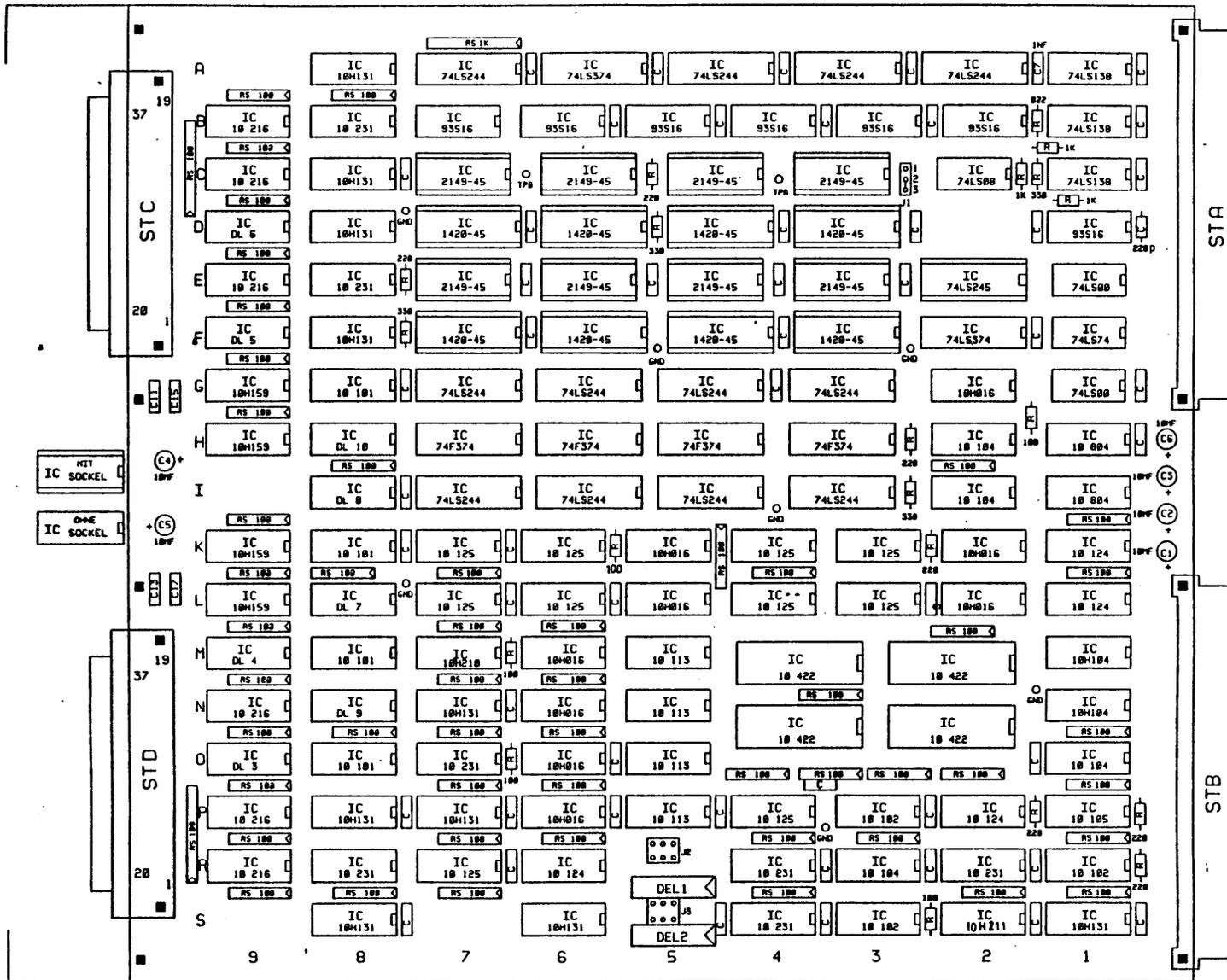
The entire data line (starting from the input buffer up to and including the Data RAM) is tested.

Reasons for negative test results:

- Defective probe
- Pattern generator on the SEQ board is defective
- Test configurator wire or UPR is defective
- Error in the DMB data line
- Data RAM on the DMB is defective

This page intentionally left blank

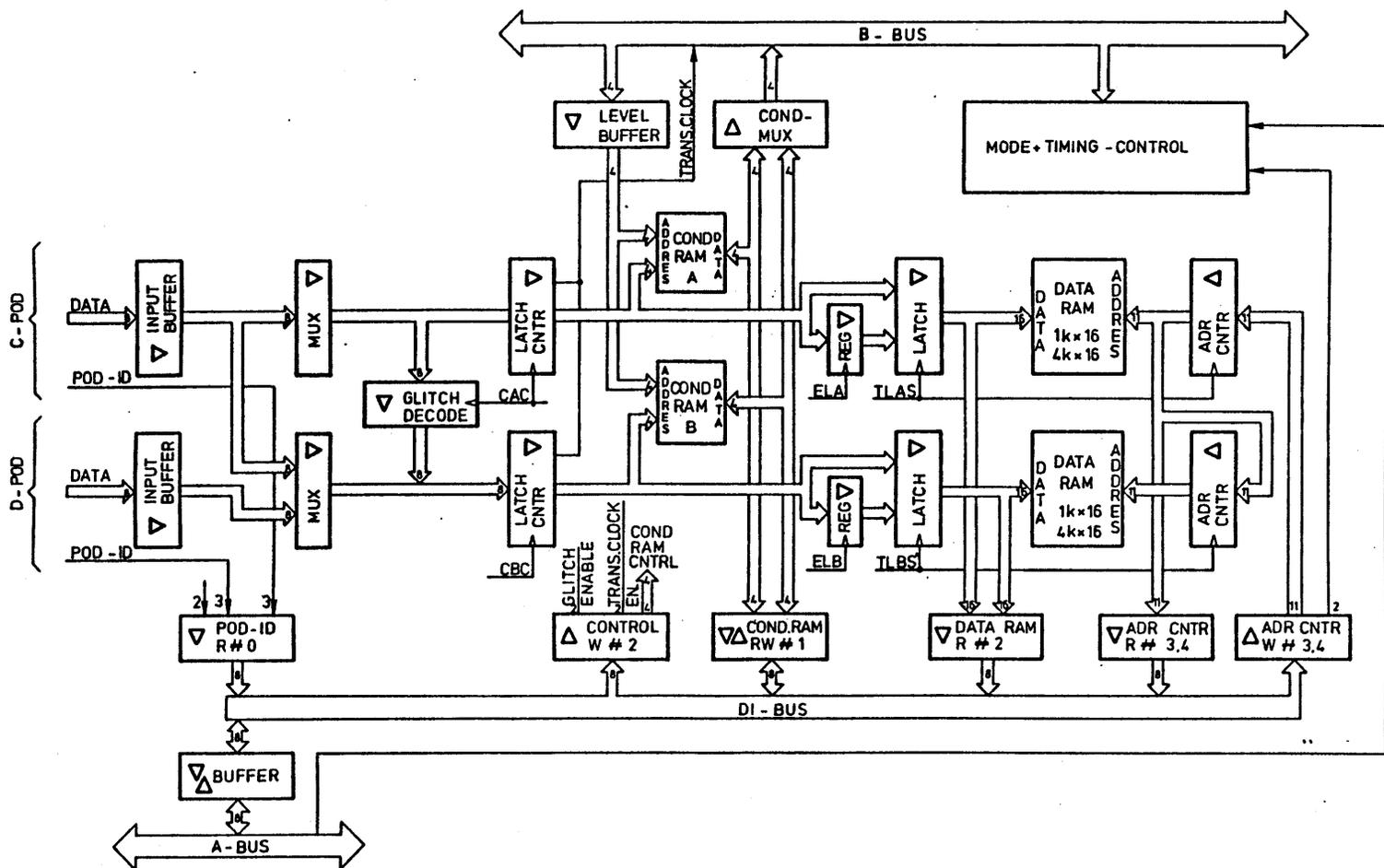
A
B
C
D
E
F



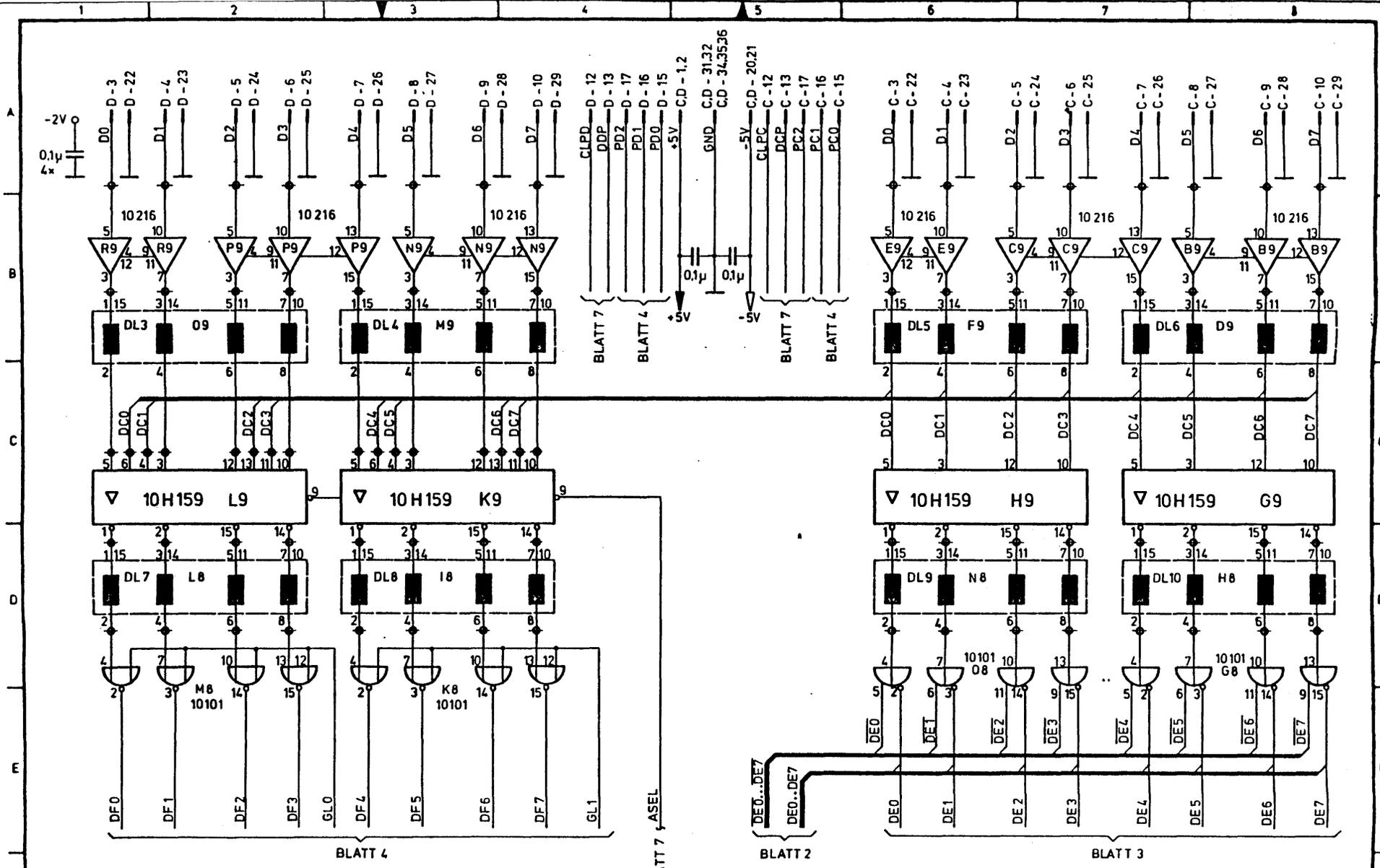
		Tag	Name	Benennung	KLA - DMB DATA - MEMORY - BOARD	Zeichn.-Nr. 311	Blatt-Nr. v. B.
		Bearb.	Hö				
		Gepr.					
3.11							
Rev.	Änderungs-Nr.	Tag	Name	zu Gerät	zu Anlage		

KONTRON
ELEKTRONIK

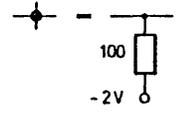
Für diese Zeichnung besteht kein Vertriebsrecht



				Tag	Name	Benennung	KLA-DMB DATA-MEMORY-BOARD	Blatt-Nr.
				Bearb. 10.7.81	Hönsel			
				Gepr. 27.1.82	HÜBNER	Zeichn.-Nr.	311	Blatt-Nr.
3.1								
1.5	152	16.7.82				zu Gerät	zu Anlage	v. Bl.
1.4	142	23.3.82						
1.2		27.1.82						
Rev.	Änderungs-Nr.	Tag	Name					



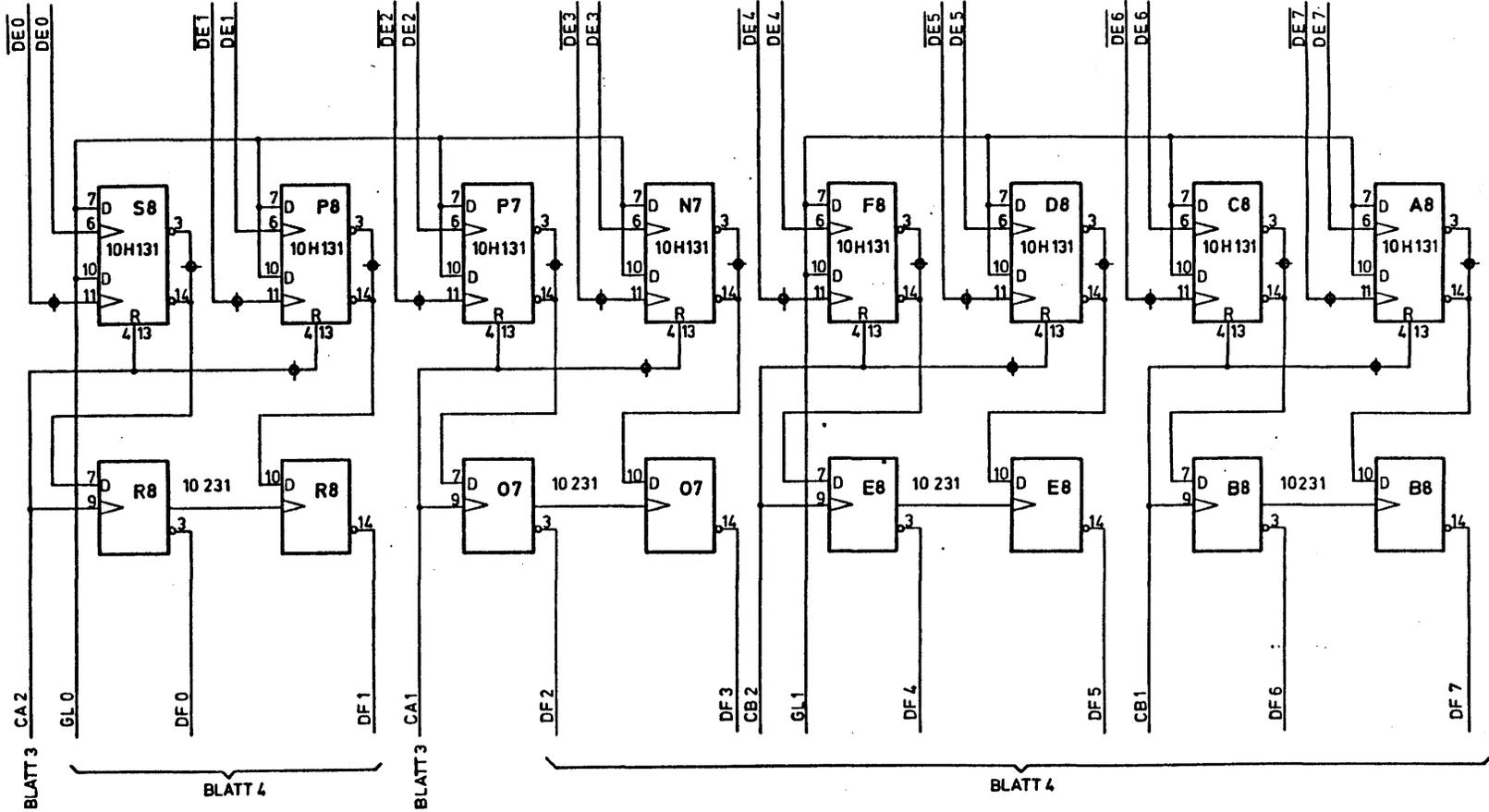
	+5V	GND	-5V
10 216	-	1,16	8
10 159	-	16	8
10 101	-	1,16	8
DL	-	9,12,13,16	-



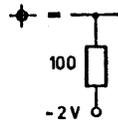
		Tag	Name	Benennung	KLA - DMB FRONT - END	Zechn.-Nr. 311	Blatt Nr. 1 7 U	
		Bearb.	20.7.83					Hänsel
		Gepr.						
3.1	Rev.	Änderungs-Nr.	Tag	Name	Zu Gepr.	Im Anlage		

**KONTRON
ELEKTRONIK**

BLATT 1



	+5V	GND	-5V
10H131	-	16,1	8
10231	-	16,1	8



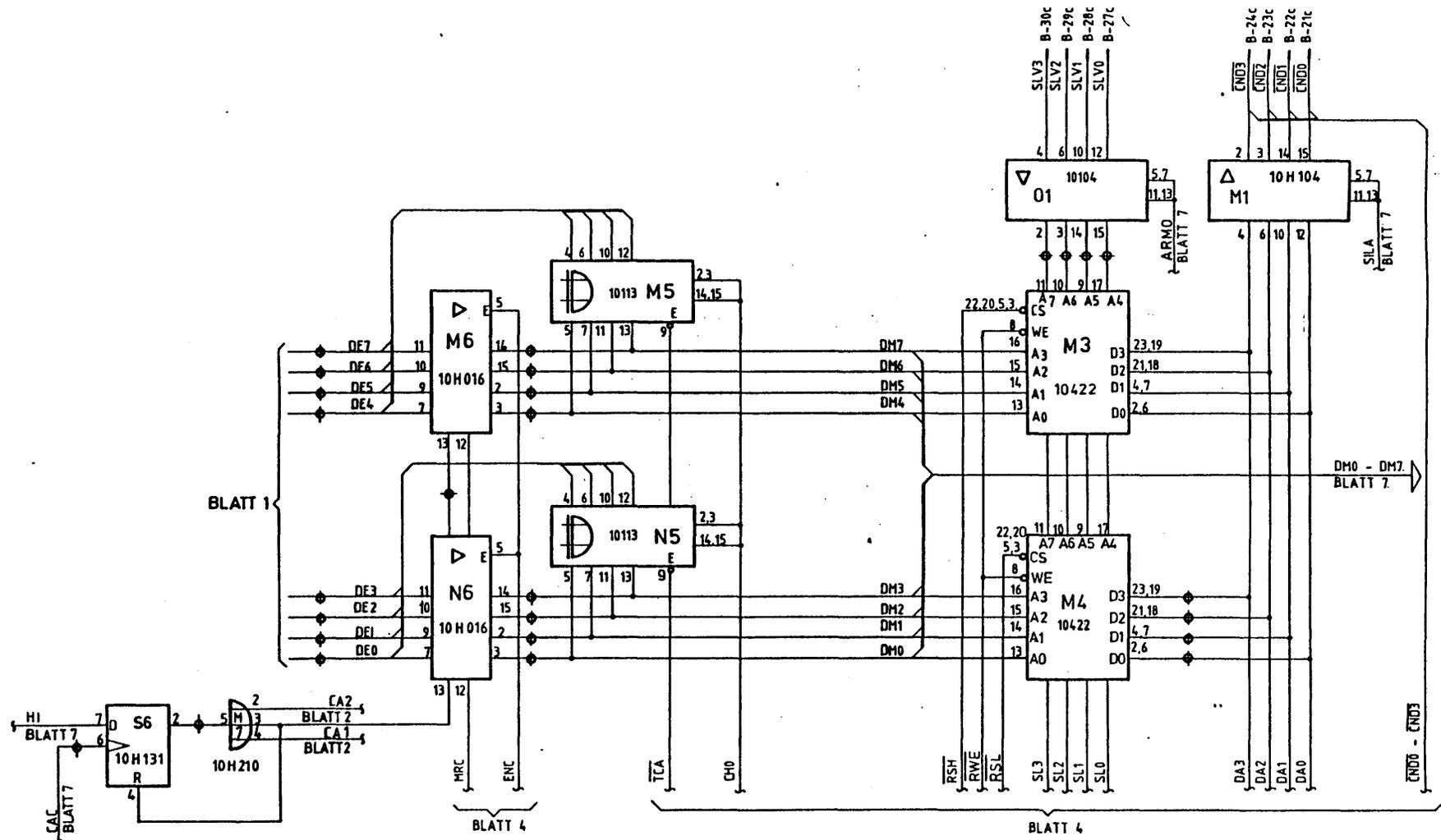
		Tag	Name	Benennung	KLA - DMB GLITCH - LATCH	Blatt-Nr. 2
		25.7.83	Hönsel			
				Zechn.-Nr.	311	v 7 Bl.
3.1				Zu Gerät	Anlage	

**KONTRON
ELEKTRONIK**

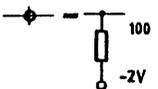
Für diese Zeichnung zuständige
Personen sind hiermit:

A
B
C
D
E
F

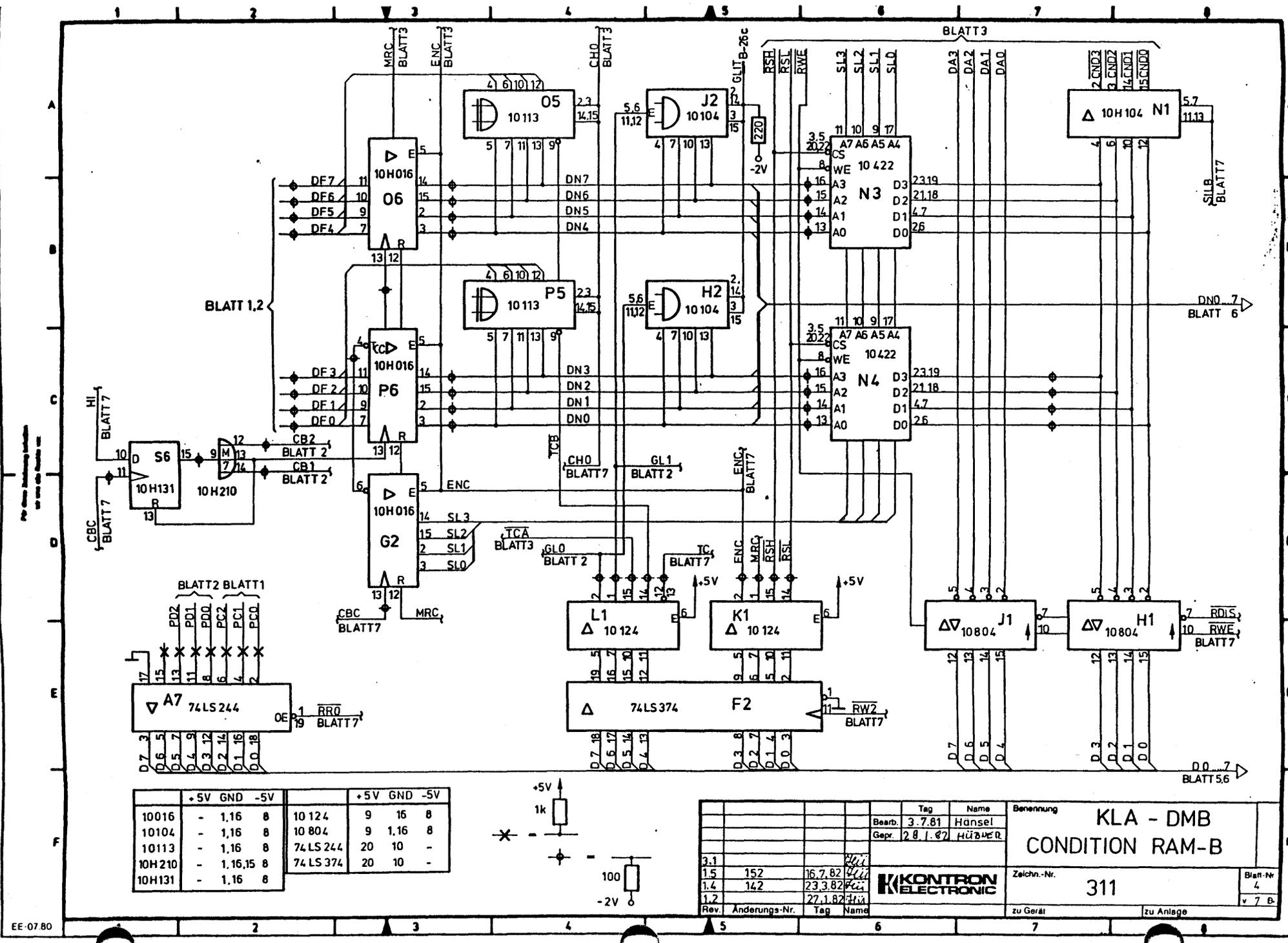
Für diese Schaltung sind alle Bauteile von BLATT 7 zu verwenden



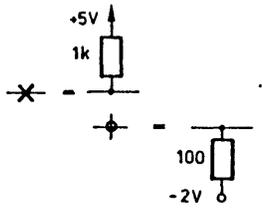
	GND	-5V
10H016	1,16	8
10H104	1,16	8
10 113	1,16	8
10H131	1,16	8
10 422	1,24	12
10H210	1,16,15	8



Rev		Änderungs-Nr.		Tag		Name		Benennung		KLA - DMB CONDITION RAM-A		Zeichn.-Nr. 311		Blatt-Nr. 3	
3.1				16.7.82		Hänsel				KONTRON ELECTRONIC		zu Gerät		zu Anlage	
1.5		152		23.3.82		Hänsel								v 7 Pt	
1.4		142		27.1.82		Hänsel									
1.2															
Bearb.		Tag		Name		Benennung		KLA - DMB CONDITION RAM-A		Zeichn.-Nr. 311		Blatt-Nr. 3		v 7 Pt	
Gepr.		20.1.82		HÄNZNER											



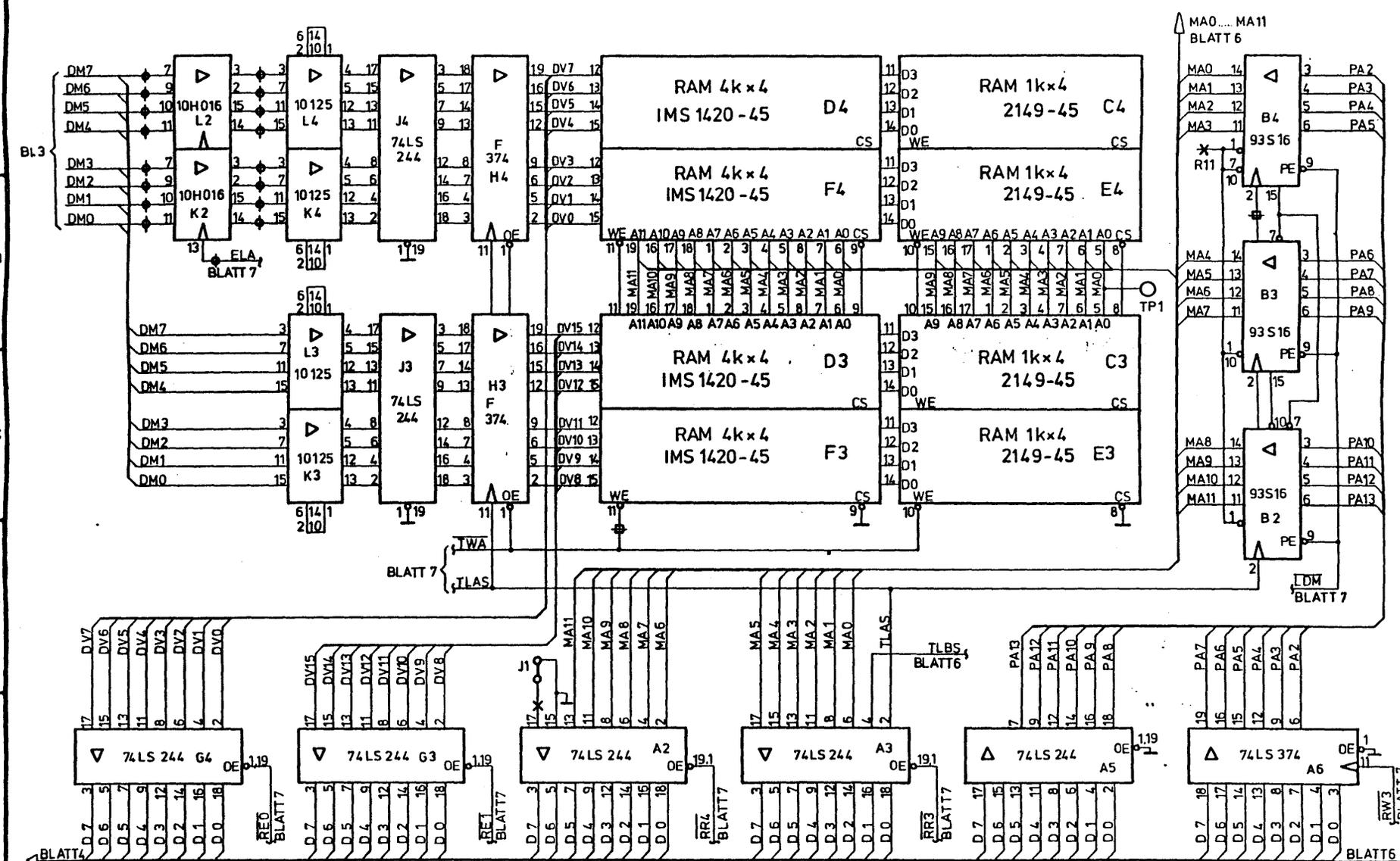
	+5V	GND	-5V		+5V	GND	-5V
10016	-	1,16	8	10124	9	16	8
10104	-	1,16	8	10804	9	1,16	8
10113	-	1,16	8	74LS244	20	10	-
10H210	-	1,16,15	8	74LS374	20	10	-
10H131	-	1,16	8				



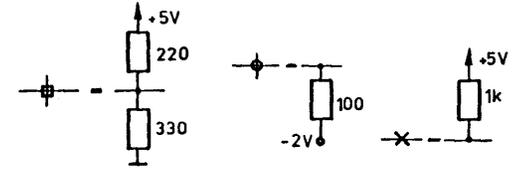
Rev.	Anderungs-Nr.	Tag	Name
3.1			
1.5	152	16.7.82	H
1.4	142	23.3.82	H
1.2		27.1.82	H

Tag	Name	Benennung
3.7.81	Hänsel	KLA - DMB CONDITION RAM-B
28.1.87	HÜBNER	
KONTRON ELECTRONIC		Zeichn.-Nr. 311
zu Gerät		zu Anlage

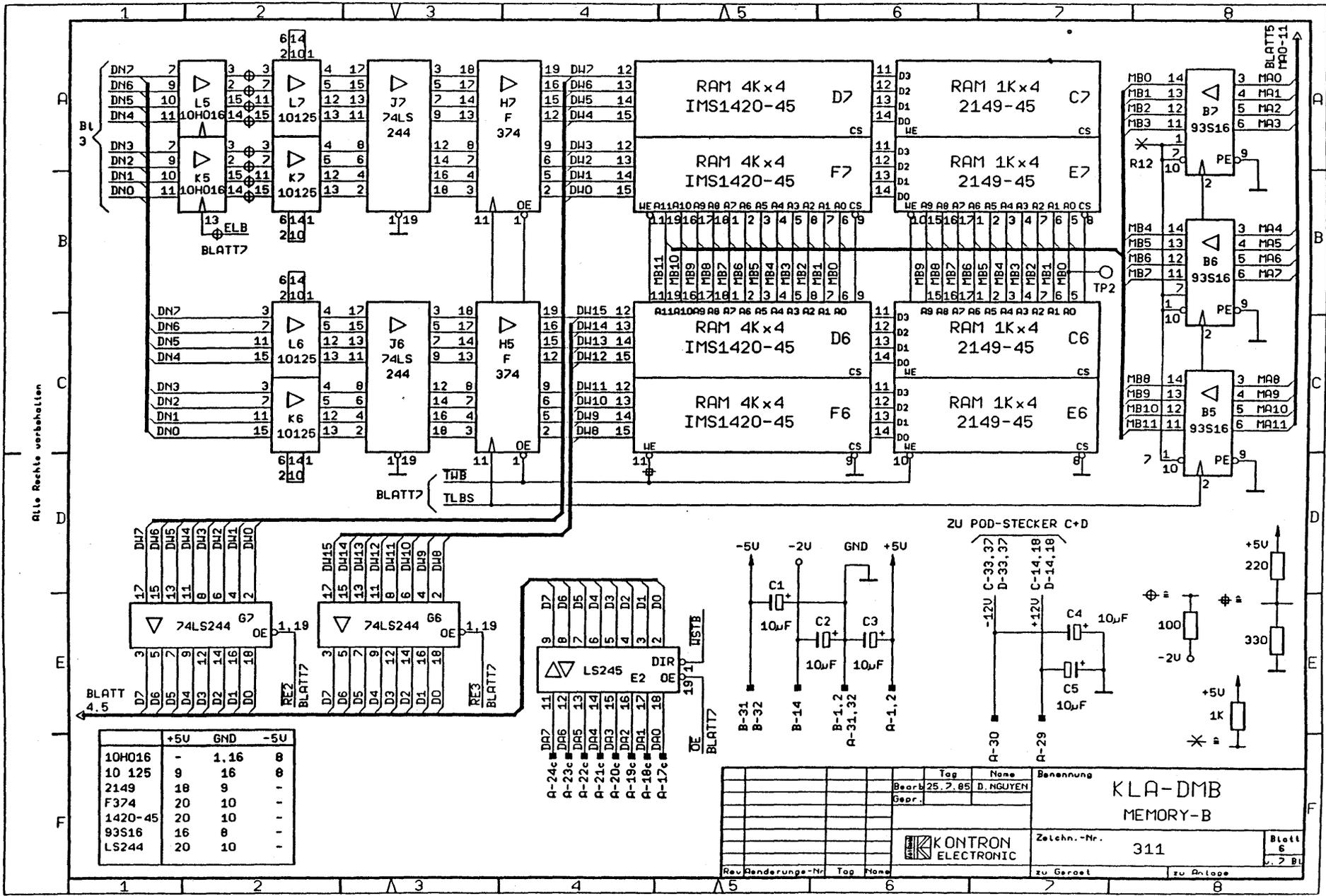
Blatt-Nr. 4
v 7 B.



	+5V	GND	-5V
10H016	-	1.16	8
10 125	9	16	8
2149	18	9	.
F 374	20	10	.
LS 244	20	10	.
93S16	16	8	.
1420-45	20	10	.



Rev.	Anderungs-Nr.	Tag	Name	Benennung	Blatt Nr.
3.1				KLA-DMB MEMORY-A	5
1.5	152	16.7.82	Hänzel		
1.4	142	23.3.82	Hänzel		
1.2		27.1.82	Hänzel	Zeichn.-Nr.	311
				zu Gerät	zu Anlage



Alle Rechte vorbehalten

	+5U	GND	-5U
10H016	-	1.16	8
10 125	9	16	8
2149	18	9	-
F374	20	10	-
1420-45	20	10	-
93S16	16	8	-
LS244	20	10	-

Rev	anderungs-Nr	Tag	Name	Benennung	KLA-DMB MEMORY-B	Zschn.-Nr. 311	Blatt 6 v. 7 Bl
			Bearb. 25.7.85 D. NGUYEN Gepr.				
KONTRON ELECTRONIC				zu Gerat	zu Anlage		

LDP MENU INPUT FIELDS

This appendix contains a list of the LDP Main Menu input fields as shown in Figure A-1 and a brief description of each. The Single-Test Menu is illustrated in subsequent pages.

```
Diagnostic Program for KLA and KSA Rev. 2.5 13-Sept-1984
----- extended version for hardware revision 3 -----
```

commands

- (1) - start complete test-sequence
- (2) - go to single-test menu
- (3) - print a detailed error-description
- (4) - print suspected defective boards
- (5) - exit

switches

- (+) - stop after each screen is on
- (-) - akustik error message is on
- (X) - user guidance for pod-tests is on

information

you can always come back to this menu with **<RETURN>** or **<F1>**
you can always leave the program with **<ESC>** or **<F2>**

please select your input :

Figure A-1. LDP Main Menu

Kontron LA Diagnostic Program (SMK-LA-1010-01)

(1) start complete test-sequence

Runs through all diagnostic tests (see "+" below).

(2) user guidance for pod-test on

Displays backplane diagram, showing unconnected probes as blinking fields. If all probes are connected, this screen does not appear.

(3) go to single-test menu

If you see an error during the first run of diagnostic tests, you can choose to run individual tests. The types of tests are highlighted in reverse video; the list below allows you to select where to run that test. Individual tests are activated with the RUN/STOP key.

(4) print a detailed error-description

Displays final diagnostic test results. You must run the diagnostic tests first in order to get an accurate summary on this screen.

(5) print suspected defective boards

Displays list of suspected defective boards. You must run the diagnostic tests first in order to get an accurate summary on this screen.

(6) exit

Returns you to the Main Menu.

(+) stop after each screen is on

The LA stops after each diagnostic test. If you enter "+" in the input field, this line reads "stop after each screen is off". The LA then runs through all diagnostic tests without stopping.

(-) akustik error message is on

The LA "beeps" at every error. If you enter "-" in the input field, this line reads "akustik error message if off". Then the LA does not "beep" at every error.

The tests in the Single-Test Menu are represented in Figure A-2, which is followed by a list of test names and corresponding page numbers of the sample screen shots.

(G1) - test of data bus and rams	(G9) - probe-tests
(G2) - memory-tests of DMB(s)	(GA) - input-tests
(G3) - memory-tests of TBQ, SEQ, TMB	(GB) - special tests
(G4) - address-counter-tests	(X) - back to main menu
(G5) - glitch-tests CONDITION	(F) - forward
(G6) - glitch-latch-tests	(B) - backward
(G7) - transition-tests	(C) - continous flag
(G8) - qualified-recording-tests	(E) - stop on error

off
off

test of data bus and rams

- (00) - Memorytest (data bus) of condition ram on DMB0
- (01) - Memorytest (data bus) of condition ram on DMB1
- (02) - Memorytest (data bus) of condition ram on DMB2
- (03) - Memorytest (data bus) of condition ram on DMB3
- (04) - Memorytest (data bus) of TBQ qualifier ram
- (05) - Memorytest (data bus) of SEQ level address ram
- (06) - Memorytest (data bus) of SEQ occurence counter ram LO
- (07) - Memorytest (data bus) of SEQ occurence counter ram HI
- (08) - Memorytest (data bus) of SEQ level status ram
- (09) - Memorytest (data bus) of SEQ trigger filter ram

please select your input :

Figure A-2. Single-Test Menu

Kontron LA Diagnostic Program (SMK-LA-1010-01)

<u>Test Name</u>	<u>Page</u>
Data test, address test	1
Clock test of the TBQ board	2
Test of the following clocks via occurrence counter of SEQ	3
Probe identification for connector C - probe J	4
Probe identification for connector C - probe K	5
Qualifier input test of pod J Qualifier input test of pod K	6
Level increment test	7
Trigger-delay-counter test	8
Test of trigger filter 0 on SEQ (via condition 0)	9
Test of trigger filter 1 on SEQ (via condition 1)	10
Test of GLA on DMB0 via condition GLIT on SEQ	11
Test of GLB on DMB0 via condition GLIT on SEQ	
Test of GLA on DMB1 via condition GLIT on SEQ	
Test of GLB on DMB1 via condition GLIT on SEQ	
Test of GLA on DMB2 via condition GLIT on SEQ	
Test of GLB on DMB2 via condition GLIT on SEQ	
Test of GLA on DMB3 via condition GLIT on SEQ	
Test of GLB on DMB3 via condition GLIT on SEQ	
Glitch-latch test of pods 1-8	12
Test of false occurring transitions	13
Transition recording test of pods 1-8	14
Data qualified recording test pods 1-8	15
Test of interlace clocks ILA1, ILB1, ILA2, ILB2 (ILAC)	16
Probe test pods 1-8	17
Probe test probes 1-8	18
Board(s) suspected to be defective	19

Board Specific RAM Data-test Address-Test

TBQ	Qualifier RAM	ok	ok
TBQ	Qualifier RAM	special Address-test	ok
SEQ	Level Address	ok	ok
SEQ	Occurence CNT	ok	ok
SEQ	Occurence CNT	ok	ok
SEQ	Status	ok	ok
SEQ	Trigger filter	ok	ok
DMB 3	Condition RAM	ok	ok
DMB 3	Data RAM	ok	ok
DMB 2	Condition RAM	ok	ok
DMB 2	Data RAM	ok	ok
DMB 1	Condition RAM	ok	ok
DMB 1	Data RAM	ok	ok
DMB 0	Condition RAM	ok	ok
DMB 0	Data RAM	ok	ok
TMB	Data RAM	ok	

test is in hold, type any key to continue ■

clock-tests of the T80-board

test of the 100ms via slow-clock-detection ok

test is in hold, type any key to continue ■

test of the following clocks
via occurrence-counter of SEQ

100 MHz = 10 ns	jitter = + 0006 Samples	ok
50 MHz = 20 ns	jitter = - 0001 Samples	ok
20 MHz = 50 ns	jitter = - 0001 Samples	ok
10 MHz = 100 ns	jitter = - 0000 Samples	ok
1 MHz = 1 us	jitter = + 0001 Samples	ok
100 KHz = 10 us	jitter = + 0001 Samples	ok
10 KHz = 100 us	jitter = + 0001 Samples	ok
1 KHz = 1 ms	jitter = - 0000 Samples	ok
100 Hz = 10 ms	jitter = - 0000 Samples	ok
10 Hz = 100 ms	jitter = - 0000 Samples	ok

test is in hold, type any key to continue ■

probe-identifikation for Connector C (PROBE J) ok
slow-clock-detection for Connector C (PROBE J) ok

test is in hold, type any key to continue ■

probe-identifikation for Connector D (PROBE K) ok
slow-clock-detection for Connector D (PROBE K) ok

test is in hold, type any key to continue ■

Qualfier input test of pod J

ok

(also runs QUALIFIER INPUT TEST OF POD K)

test is in hold, type any key to continue ■

level-increment-test

100 MHz =	10 ns	jitter = + 0000	Samples	ok
50 MHz =	20 ns	jitter = + 0000	Samples	ok
20 MHz =	50 ns	jitter = + 0000	Samples	ok
10 MHz =	100 ns	jitter = + 0000	Samples	ok

test is in hold, type any key to continue ■

trigger-delay-counter-test

50 MHz = 20 ns	Trigger-delay-counter 0	ok
	Trigger-delay-counter 1	ok
	Trigger-delay-counter 2	ok
	Trigger-delay-counter 3	ok
10 MHz = 100 ns	Trigger-delay-counter 0	ok
	Trigger-delay-counter 1	ok
	Trigger-delay-counter 2	ok
	Trigger-delay-counter 3	ok
1 MHz = 1 us	Trigger-delay-counter 0	ok
	Trigger-delay-counter 1	ok
	Trigger-delay-counter 2	ok
	Trigger-delay-counter 3	ok
100 KHz = 10 us	Trigger-delay-counter 0	ok
	Trigger-delay-counter 1	ok
	Trigger-delay-counter 2	ok
	Trigger-delay-counter 3	ok

test is in hold, type any key to continue ■

Test of trigger filter 0 on SEQ (via condition 0)

last level was reached in time jitter = + 0000 Samples ok

test is in hold, type any key to continue ■

Test of trigger filter 1 on SEQ (via condition 1)

last level was reached in time jitter = + 0000 Samples ok

test is in hold, type any key to continue ■

Test of GLA on DMB0 via condition GLIT on SEQ

condition GLITCH ok

(also runs Test of GLB on DMB0 via condition GLIT on SEQ

Test of GLA on DMB1 via condition GLIT on SEQ

Test of GLB on DMB1 via condition GLIT on SEQ

Test of GLA on DMB2 via condition GLIT on SEQ

Test of GLB on DMB2 via condition GLIT on SEQ

Test of GLA on DMB3 via condition GLIT on SEQ

Test of GLB on DMB3 via condition GLIT on SEQ)

test is in hold, type any key to continue ■

glitch-latch-test of pod 1

test of false occurring glitches test of missing glitches

Glitch-latch 01 ok

Glitch-latch 01 ok

Glitch-latch 03 ok

Glitch-latch 03 ok

Glitch-latch 05 ok

Glitch-latch 05 ok

Glitch-latch 07 ok

Glitch-latch 07 ok

(also runs glitch-latch-test of pods 2 - 8)

test is in hold, type any key to continue ■

test of false occurring transitions ok

test is in hold, type any key to continue ■

transition recording test of pod 1

Transitional clocking signal (TCLK) ok

(also runs transition recording test of pods 2 - 8)

test is in hold, type any key to continue ■

data qualified recording test pod 1 ok

(also runs data qualified recording test of pods 2 - 8)

test is in hold, type any key to continue **■**

Test of interlace clocks ILA1,ILB1,ILA2,ILB2,(ILAC)

ILA1	ok
ILB1	ok
ILA2	ok
ILB2	ok

test is in hold, type any key to continue

Probe-test probe 1

- Test 1 : Threshold hardware or all Inputs on Probe or OMB ok
- Test 2 : Test of all channels via changing Threshold voltage(no input needed)
- Test 3 : Test of all channels via ECL-input-signal (Threshold is fix)
- Test 4 : Test of overshoot respectively positive offset voltage
- Test 5 : Test of undershoot respectively negative offset voltage

	Test 2 :	Test 3 :	Test 4 :	Test 5 :
Channel 00	ok	ok	ok	ok
Channel 01	ok	ok	ok	ok
Channel 02	ok	ok	ok	ok
Channel 03	ok	ok	ok	ok
Channel 04	ok	ok	ok	ok
Channel 05	ok	ok	ok	ok
Channel 06	ok	ok	ok	ok
Channel 07	ok	ok	ok	ok

test is in hold, type any key to continue ■

(also runs probe-test on pods 2 - 8)

Probe-test probe 1

ok

(also runs probe-test probe 2 - 8)

test is in hold, type any key to continue

board(s) suspected to be defective :

No defective board detected

Press **RETURN** or **RUN/STOP** to continue **2**

LDP TEST FAILURES

This appendix describes the possible board-specific LDP test failures and includes sample screen shots.

Simulated error on: TBQ board

Possible errors detected in the following tests:

Data test, address test

Test of the following clocks via occurrence counter on SEQ

Probe identification for connector D (probe K)

Qualifier input test of pod K

Level increment test

Trigger-delay-counter test

Transition recording test of pods 1-8

Boards(s) suspected to be defective:

TBQ - Time Base and Clock Qualifier

SEQ - Trigger Sequencer Controller

DMB0 - Data Memory Board 0

DMB1 - Data Memory Board 1

DMB2 - Data Memory Board 2

DMB3 - Data Memory Board 3

Suggested correction: TBQ board replacement

Board: Specific-RAM Data-test Address-Test

TBQ	Qualifier RAM	error	error
TBQ	Qualifier RAM	special Address-test	error
SEQ	Level Address	ok	ok
SEQ	Occurence CNT	ok	ok
SEQ	Occurence CNT	ok	ok
SEQ	Status	ok	ok
SEQ	Trigger filter	ok	ok
DMB 3	Condition RAM	ok	ok
DMB 3	Data RAM	ok	ok
DMB 2	Condition RAM	ok	ok
DMB 2	Data RAM	ok	ok
DMB 1	Condition RAM	ok	ok
DMB 1	Data RAM	ok	ok
DMB 0	Condition RAM	ok	ok
DMB 0	Data RAM	ok	ok
TMB	Data RAM	ok	

test is in hold, type any key to continue ■

test of the following clocks
via occurrence-counter of SEQ

100 MHz = 10 ns	jitter = + 0006 Samples	ok
50 MHz = 20 ns	jitter = + 19E3 Samples	too fast
20 MHz = 50 ns	jitter = - 0001 Samples	ok
10 MHz = 100 ns	jitter = - 0000 Samples	ok
1 MHz = 1 us	jitter = - 0000 Samples	ok
100 KHz = 10 us	jitter = + 0002 Samples	ok
10 KHz = 100 us	jitter = + 0001 Samples	ok
1 KHz = 1 ms	jitter = - 0000 Samples	ok
100 Hz = 10 ms	jitter = - 0000 Samples	ok
10 Hz = 100 ms	jitter = - 0001 Samples	ok

test is in hold, type any key to continue ■

probe-identifikation for Connector D (PROBE K) ok
slow-clock-detection for Connector D (PROBE K) **error**

test is in hold, type any key to continue ■

Qualfier input test of pod K

error

Qualifier input 00	error
Qualifier input 01	error
Qualifier input 02	error
Qualifier input 03	error
Qualifier input 04	error
Qualifier input 05	error

test is in hold, type any key to continue ■

level-increment-test

100 MHz =	10 ns	jitter = + 0000	Samples	ok
50 MHz =	20 ns	jitter = - 00A1	Samples	too fast
20 MHz =	50 ns	jitter = + 0000	Samples	ok
10 MHz =	100 ns	jitter = + 0000	Samples	ok

test is in hold, type any key to continue ■

trigger-delay-counter-test

50 MHz = 20 ns

Trigger-delay-counter 0	too early
Trigger-delay-counter 1	too early
Trigger-delay-counter 2	too early
Trigger-delay-counter 3	too early

10 MHz = 100 ns

Trigger-delay-counter 0	ok
Trigger-delay-counter 1	ok
Trigger-delay-counter 2	ok
Trigger-delay-counter 3	ok

1 MHz = 1 us

Trigger-delay-counter 0	ok
Trigger-delay-counter 1	ok
Trigger-delay-counter 2	ok
Trigger-delay-counter 3	ok

100 KHz = 10 us

Trigger-delay-counter 0	ok
Trigger-delay-counter 1	ok
Trigger-delay-counter 2	ok
Trigger-delay-counter 3	ok

probably error on preset lines

test is in hold, type any key to continue

transition recording test of pod 1

Transitional clocking signal (TCLK) **error**

test is in hold, type any key to continue ■

board(s) suspected to be defective :

TBQ time-base and qualifier board

SEQ sequence and control board

DMB0 data-memory-board 0

DMB1 data-memory-board 1

DMB2 data-memory-board 2

DMB3 data-memory-board 3

Press **RETURN** or **RUN/STOP** to continue ■

Simulated error on: SEQ board

Possible errors detected in the following tests:

Data test, address test

Test of the following clocks via occurrence counter on SEQ

Level increment test

Trigger-delay-counter test

Test of trigger filter 0 on SEQ (via condition 0)

Test of trigger filter 1 on SEQ (via condition 1)

Test of GLA and GLB on DMB0 via condition GLIT on SEQ

Data qualified recording test of pods 1-8

Boards(s) suspected to be defective:

TBQ - Time Base and Clock Qualifier

SEQ - Trigger Sequencer Controller

DMB0 - Data Memory Board 0

DMB1 - Data Memory Board 1

DMB2 - Data Memory Board 2

DMB3 - Data Memory Board 3

Suggested correction: SEQ board replacement

Board Specific RAM Data-test Address-Test

TBQ	Qualifier RAM	ok		ok
TBQ	Qualifier RAM		special Address-test	ok
SEQ	Level Address	error		error
SEQ	Occurence CNT	error		error
SEQ	Occurence CNT	error		error
SEQ	Status	error		error
SEQ	Trigger filter	error		error
DMB 3	Condition RAM	ok		ok
DMB 3	Data RAM	ok		ok
DMB 2	Condition RAM	ok		ok
DMB 2	Data RAM	ok		ok
DMB 1	Condition RAM	ok		ok
DMB 1	Data RAM	ok		ok
DMB 0	Condition RAM	ok		ok
DMB 0	Data RAM	ok		ok
TMB	Data RAM	ok		

test is in hold, type any key to continue ■

test of the following clocks
via occurrence-counter of SEQ

100 MHz = 10 ns	jitter = - 01FD Samples	too slow
50 MHz = 20 ns	jitter = - 0000 Samples	ok
20 MHz = 50 ns	jitter = - 0201 Samples	too slow
10 MHz = 100 ns	jitter = - 0000 Samples	ok
1 MHz = 1 us	jitter = + 0001 Samples	ok
100 KHz = 10 us	jitter = - 0001 Samples	ok
10 KHz = 100 us	jitter = - 0001 Samples	ok
1 KHz = 1 ms	jitter = - 0200 Samples	too slow
100 Hz = 10 ms	jitter = - 0000 Samples	ok
10 Hz = 100 ms	jitter = - 0003 Samples	ok

test is in hold, type any key to continue ■

level-increment-test

100 MHz = 10 ns	jitter = - 008C Samples	too fast
50 MHz = 20 ns	jitter = - 0118 Samples	too fast
20 MHz = 50 ns	jitter = - 02BA Samples	too fast
10 MHz = 100 ns	jitter = - 0575 Samples	too fast

test is in hold, type any key to continue =

trigger-delay-counter-test

50 MHz = 20 ns

Trigger-delay-counter 0 too late
Trigger-delay-counter 1 too late
Trigger-delay-counter 2 too late
Trigger-delay-counter 3 too late

10 MHz = 100 ns

Trigger-delay-counter 0 too late
Trigger-delay-counter 1 too late
Trigger-delay-counter 2 too late
Trigger-delay-counter 3 too late

1 MHz = 1 us

Trigger-delay-counter 0 too late
Trigger-delay-counter 1 too late
Trigger-delay-counter 2 too late
Trigger-delay-counter 3 too late

100 KHz = 10 us

Trigger-delay-counter 0 too late
Trigger-delay-counter 1 too late
Trigger-delay-counter 2 too late
Trigger-delay-counter 3 too late

probably error on preset lines

test is in hold, type any key to continue

.. Test of trigger filter 0 on SEQ (via condition 0)

last level was ~~not reached~~ jitter = - 0001 Samples ~~error~~

test is in hold, type any key to continue ■

Test of trigger filter 1 on SEQ (via condition 1)

last level was **not reached** jitter = - 0001 Samples **error**

test is in hold, type any key to continue ■

Test of 6LA on DMB0 via condition 6LIT on SEQ

condition 6LITCH ~~error~~

condition 6LICHT is missing

test is in hold, type any key to continue ■

Test of GLB on DMB0 via condition GLIT on SEQ
condition GLITCH ~~error~~
condition GLICHT is missing

test is in hold, type any key to continue ■

data qualified recording test pod 1 **errors**

Condition 2 **errors**

Condition 3 **errors**

test is in hold, type any key to continue ■

board(s) suspected to be defective :

TBQ time-base and qualifier board
SEQ sequence and control board
DMB0 data-memory-board 0
DMB1 data-memory-board 1
DMB2 data-memory-board 2
DMB3 data-memory-board 3
TMB time-measurement-board

Press **RETURN** or **RUN/STOP** to continue ■

Simulated error on: DMB0 board*

Possible errors detected in the following tests:

Data test, address test

Data qualified recording test of pod 1

Probe test probe 1

Boards(s) suspected to be defective:

DMB0 - Data Memory Board 0

Suggested correction: DMB0 board replacement

* All four DMBs (DMB0 to DMB3) are identical and therefore interchangeable. The eight pods or probes, which are also interchangeable, are divided among these four boards in the following arrangement:

DMB0 = pods 1 and 2

DMB1 = pods 3 and 4

DMB2 = pods 5 and 6

DMB3 = pods 7 and 8

Board Specific RAM Data-test Address Test

TBQ Qualifier RAM ok ok
TBQ Qualifier RAM special Address-test ok
SEQ Level Address ok ok
SEQ Occurence CNT ok ok
SEQ Occurence CNT ok ok
SEQ Status ok ok
SEQ Trigger filter ok ok

DMB 3 Condition RAM ok ok
DMB 3 Data RAM ok ok
DMB 2 Condition RAM ok ok
DMB 2 Data RAM ok ok
DMB 1 Condition RAM ok ok
DMB 1 Data RAM ok ok
DMB 0 Condition RAM ok ok
DMB 0 Data RAM error ok

TMB Data RAM ok

test is in hold, type any key to continue ■

data qualified recording test pod 1 **error!**

Condition 2 **error!**

Condition 3 **error!**

test is in hold, type any key to continue ■

Probe-test probe 1
Error on Address : 0004

error

test is in hold, type any key to continue ■

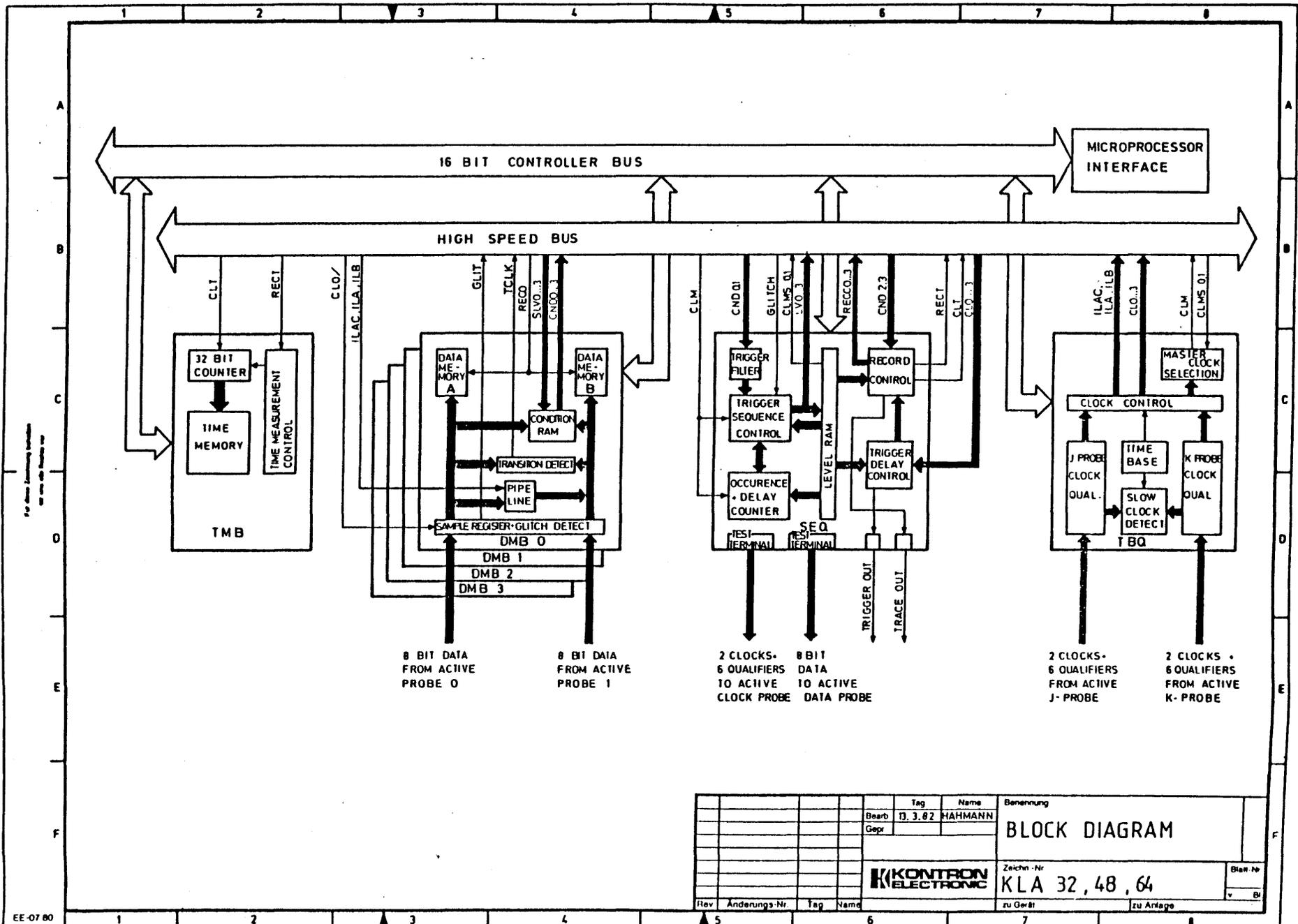
board(s) suspected to be defective :

DMB0 data-memory-board 0

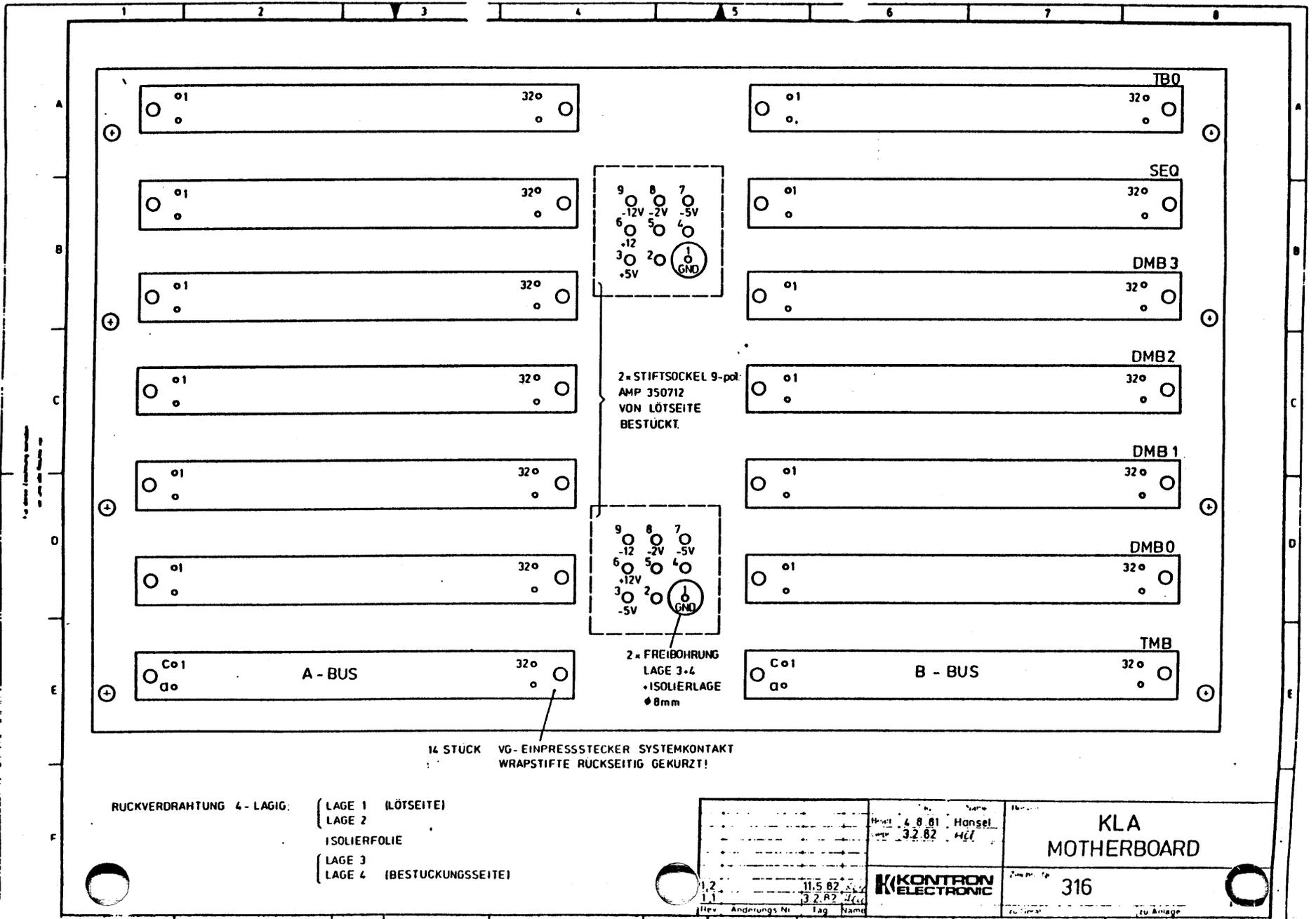
Press **RETURN** or **RUN/STOP** to continue .

ADDITIONAL SCHEMATICS

Note: These schematics are duplicates of those found in the Service Manual: Kontron LA, Volume 1 and the Kontron Logic Analyzer Series III Operations manual; they are provided here for easy reference.



Rev	Anderungs-Nr.	Tag	Name	Tag	Name	Benennung	Blatt-Nr.
				13.3.82	HAHMANN	BLOCK DIAGRAM	v. Bl.
						Zeichn.-Nr.	KLA 32, 48, 64
						zu Gerät	

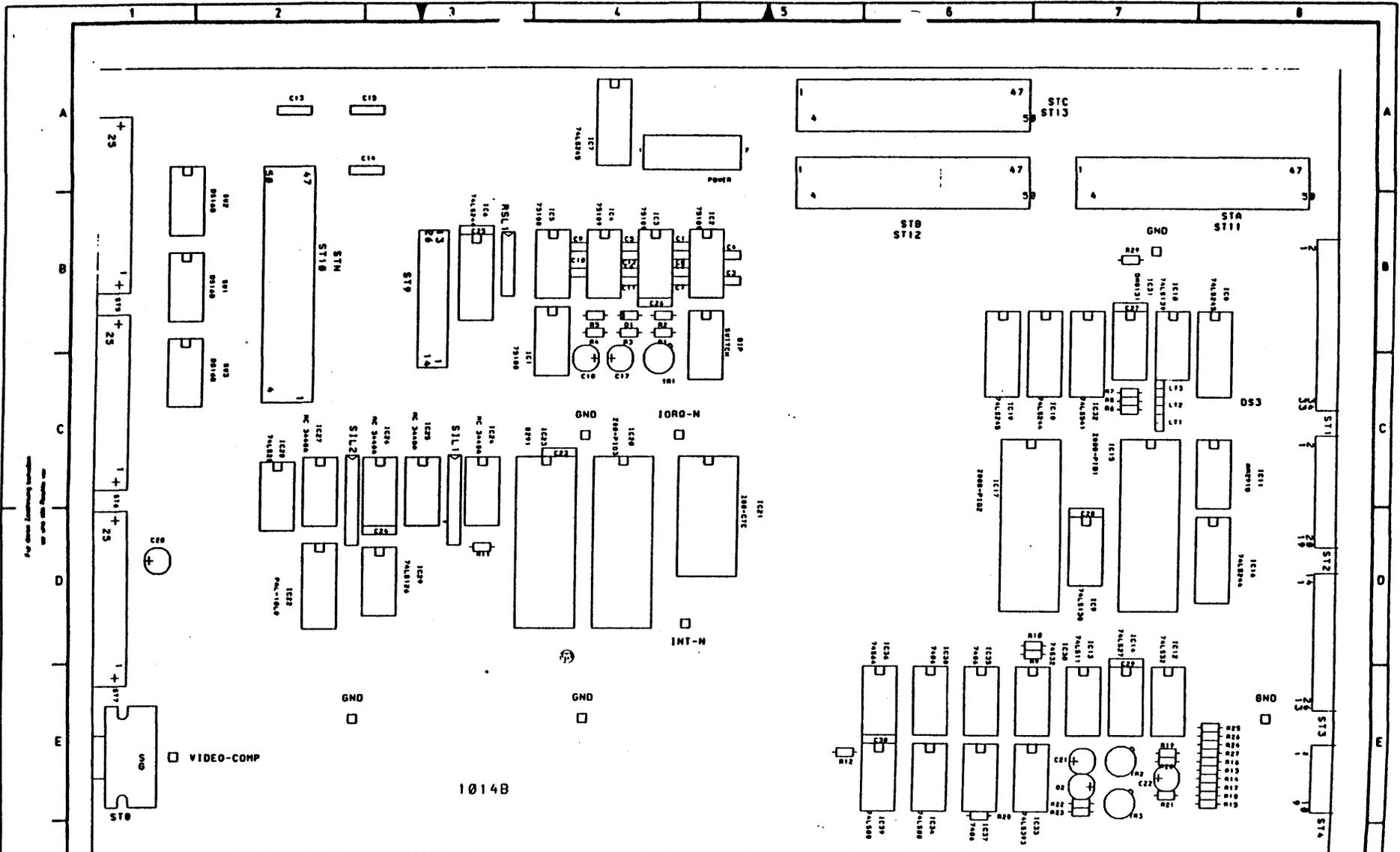


14 STÜCK VG-EINPRESSSTECKER SYSTEMKONTAKT
WRAPSTIFTE RÜCKSEITIG GEKURZT!

RÜCKVERDRÄHTUNG 4-LAGIG:

- (LAGE 1 (LÖTSEITE)
- (LAGE 2
- ISOLIERFOLIE
- (LAGE 3
- (LAGE 4 (BESTÜCKUNGSSEITE)

11.5.82 13.2.82		Hansel Hil	KLA MOTHERBOARD
11.5.82 13.2.82		KONTRON ELECTRONIC	316
11.5.82 13.2.82	Tag Name	Tag Name	Tag Name



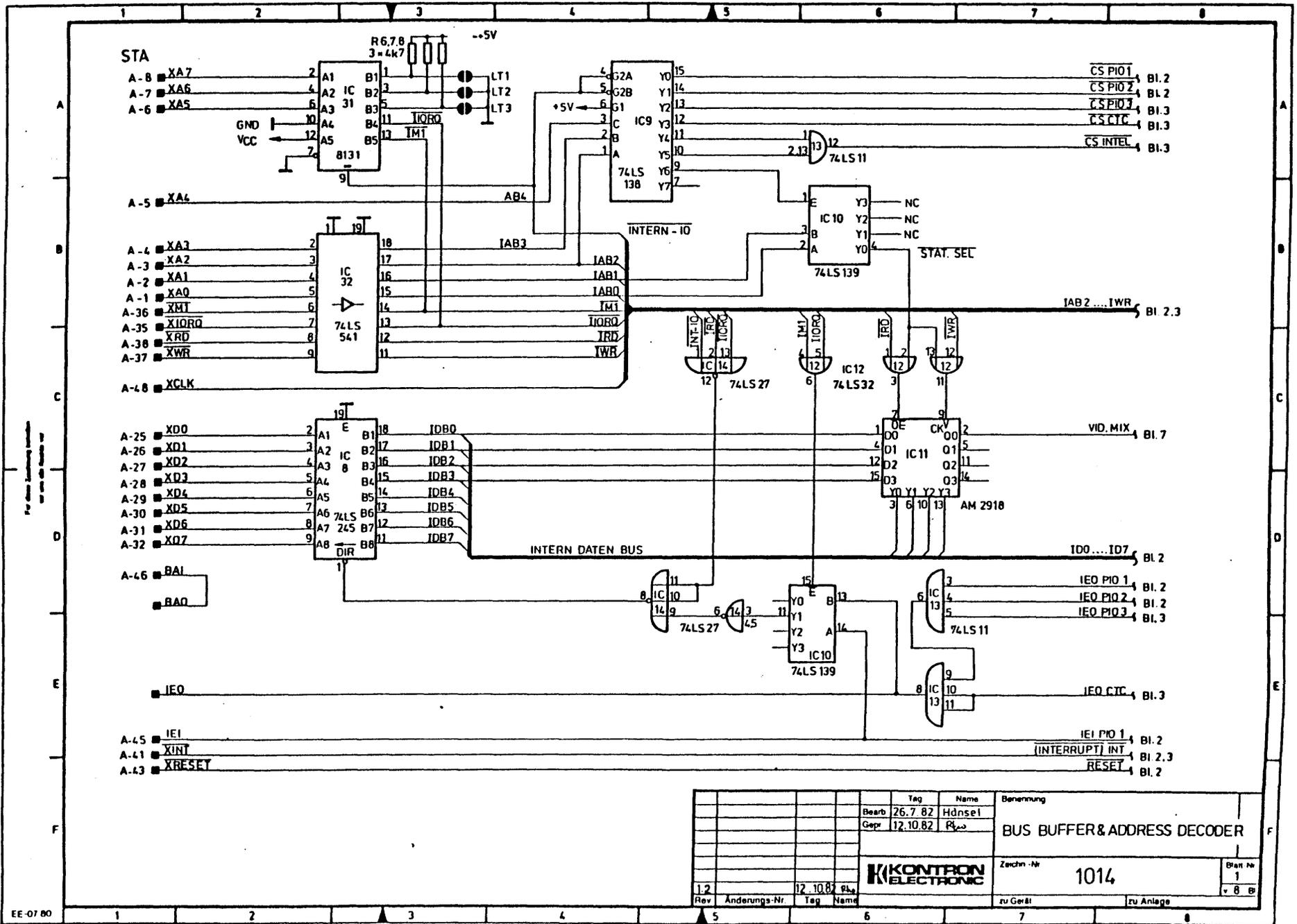
Rev		2	20.10.87	PL
Änderungs-Nr				
Tag		20.10.82	Hansel	
Name				
Bezeichnet		20.10.82	PL	
Gepr				
Zu Gerät				
Zu Anlage				

Brennung
KLA - INTERFACE

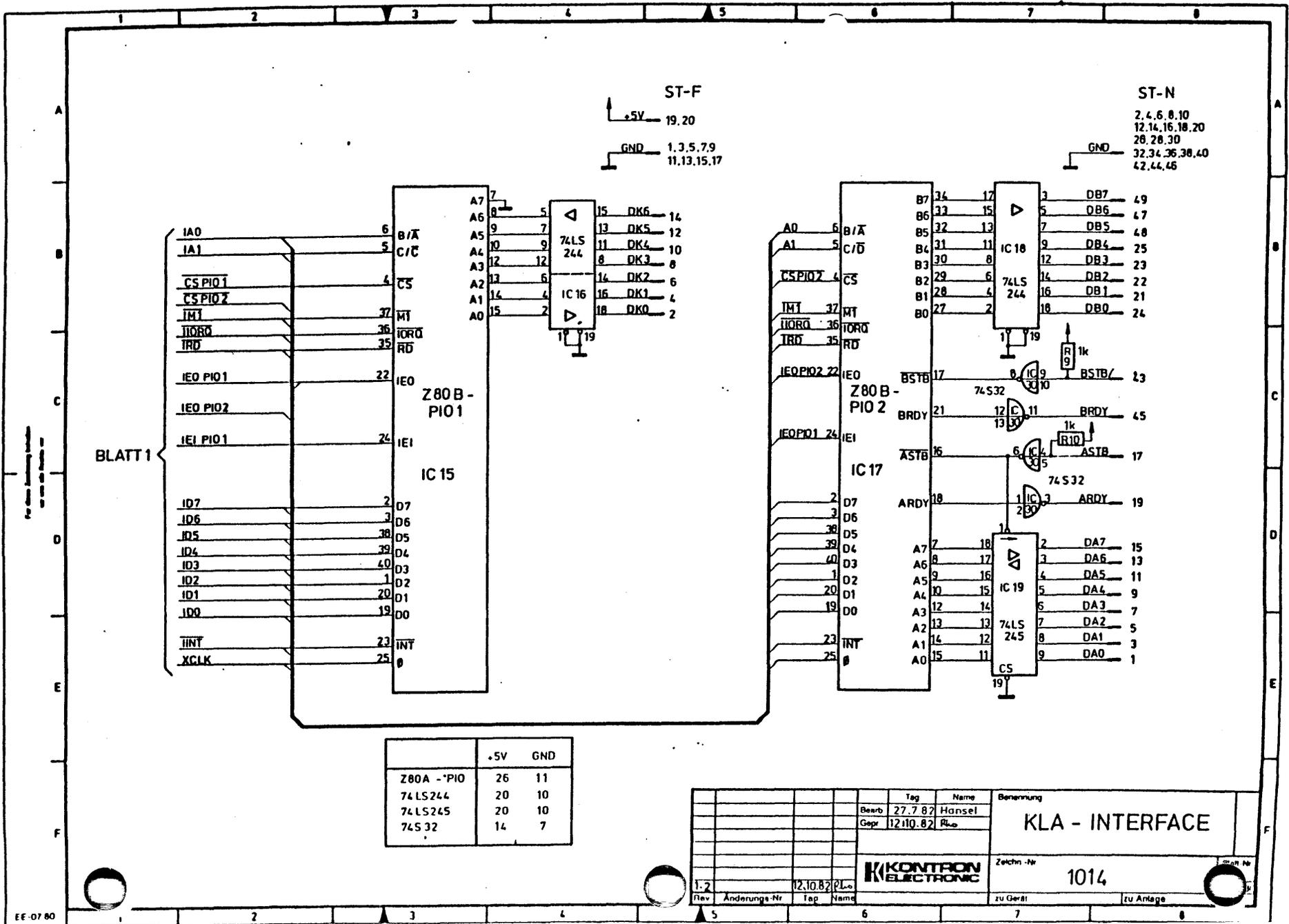


Zeichn-Nr
1014

(Plan-Nr)



Tag	Name	Bemennung
Bearb. 26.7.82	Hänsel	BUS BUFFER & ADDRESS DECODER
Gepr. 12.10.82	PL	
		Zeichn.-Nr. 1014
Rev. 1.2	Änderungs-Nr.	zu Gerät
12.10.82	PL	zu Anlage
		Blatt Nr. 1
		v. 8 Bl.



ST-F
 +5V 19, 20
 GND 1, 3, 5, 7, 9
 11, 13, 15, 17

ST-N
 2, 4, 6, 8, 10
 12, 14, 16, 18, 20
 28, 28, 30
 32, 34, 36, 38, 40
 42, 44, 46

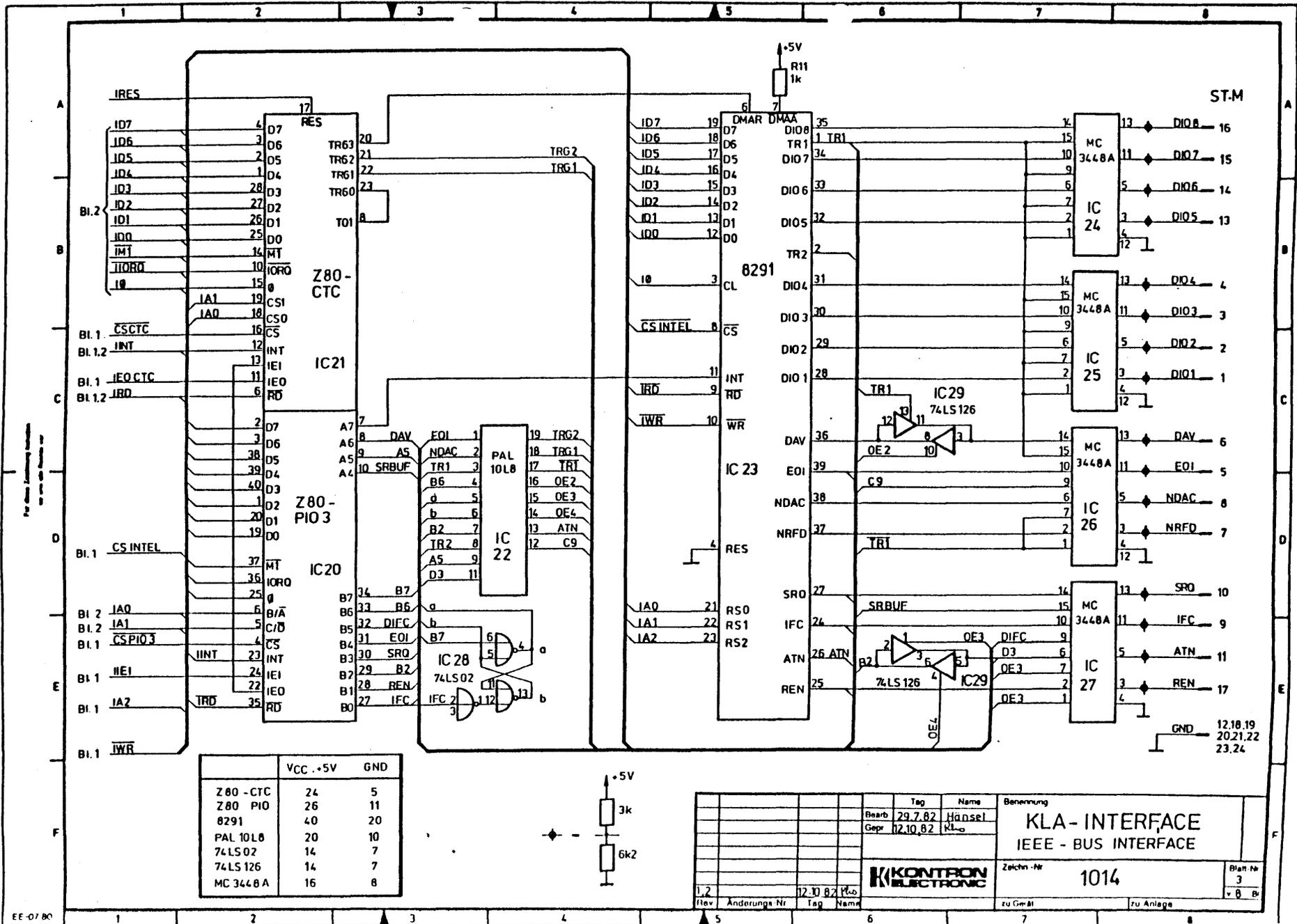
BLATT 1

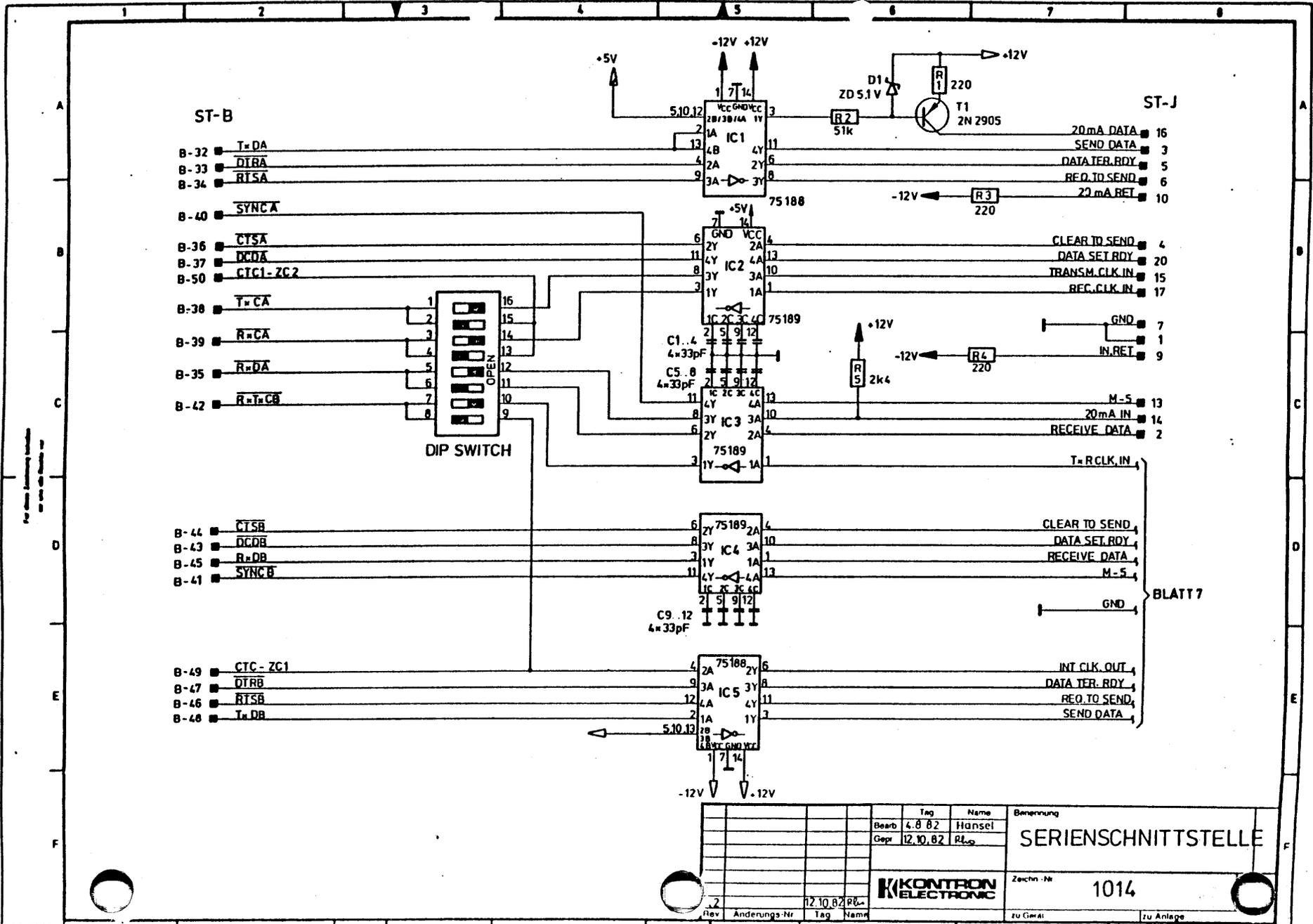
	+5V	GND
Z80A -*PIO	26	11
74LS244	20	10
74LS245	20	10
74S32	14	7

Rev	Änderungs-Nr	Tag	Name	Bemerkung
1.2		12.10.82	RL	

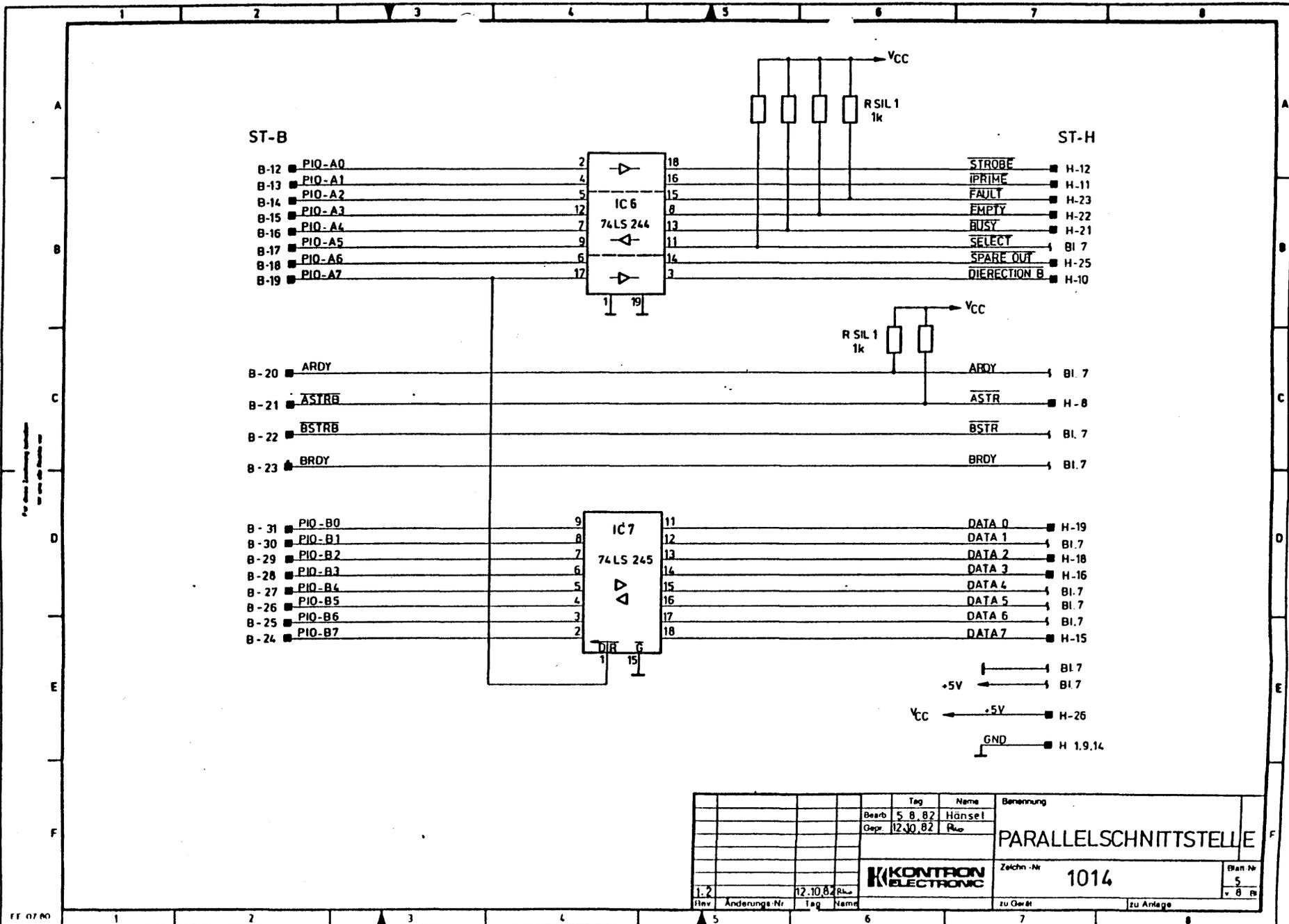
Bearb	27.7.82	Hansel
Gepr	12.10.82	RL

KONTRON ELECTRONIC		Zeichn.-Nr	1014
zu Gerät		zu Anlage	





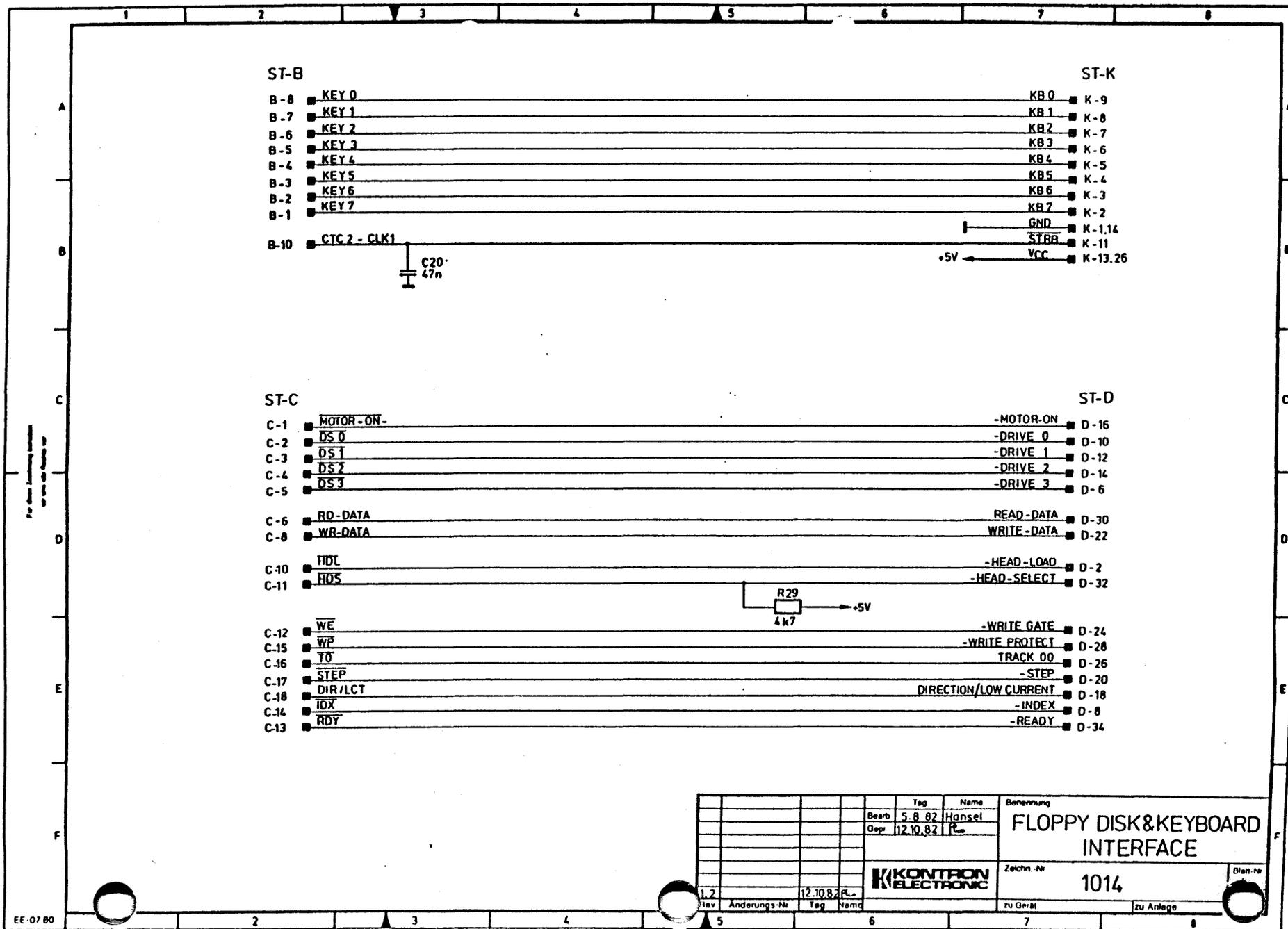
		Tag	Name	Bemerkung
Bearb.	4.8.82	Hänsel		
Gepr.	12.10.82	RL		
SERIENSCHNITTSTELLE				
KONTRON ELECTRONIC			Zeichn.-Nr.	1014
Rev.	Änderungs-Nr.	Tag	Name	Zu Gepr.
2		12.10.82	RL	
				Zu Anlage



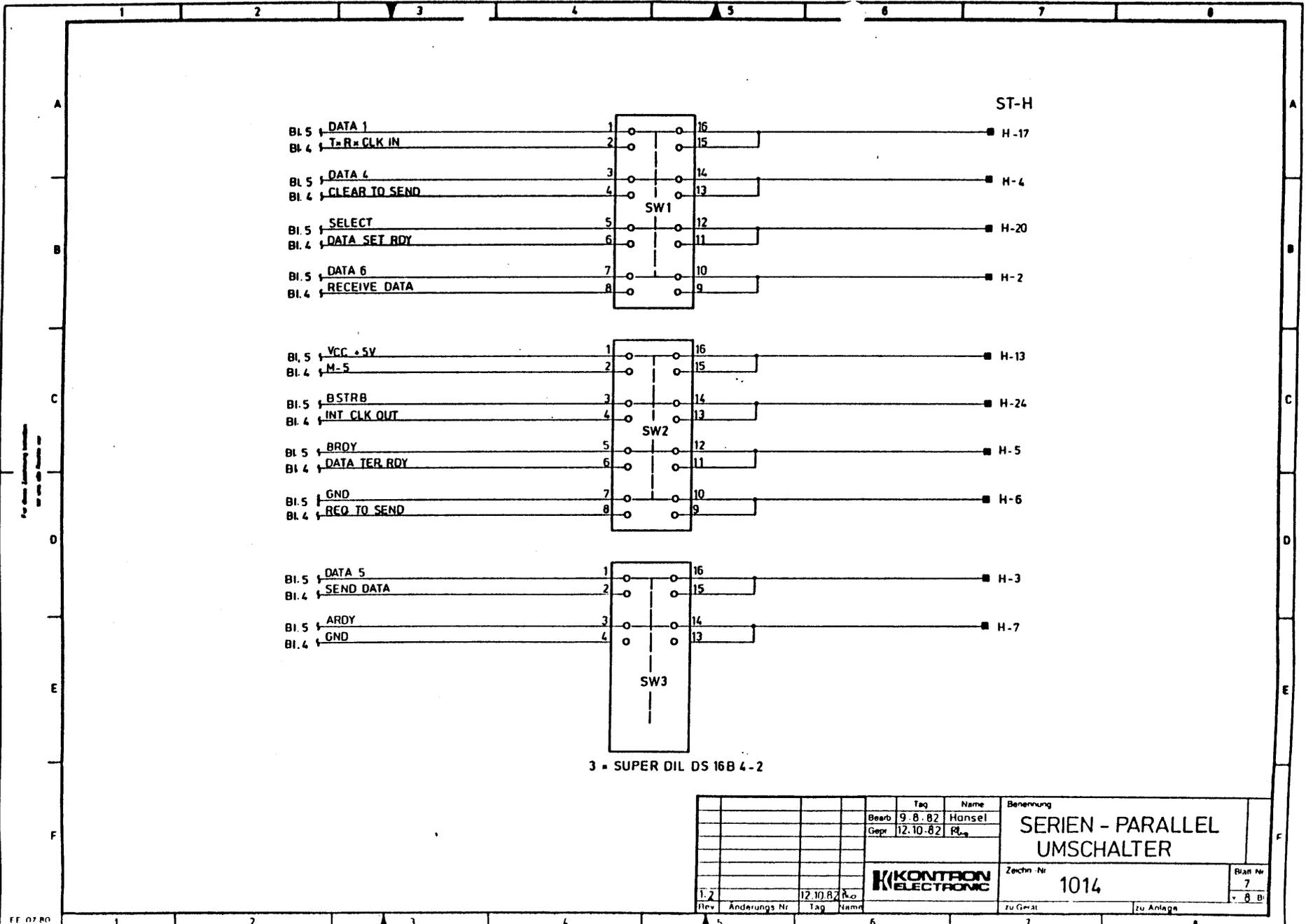
			Tag	Name	Benennung
			Bearb 5.8.82	Hönsel	PARALLELSCHNITTSTELLE
			Gepr. 12.10.82	R...	
					Zeichn.-Nr. 1014
					Blatt Nr. 5
					v. 8 (8)



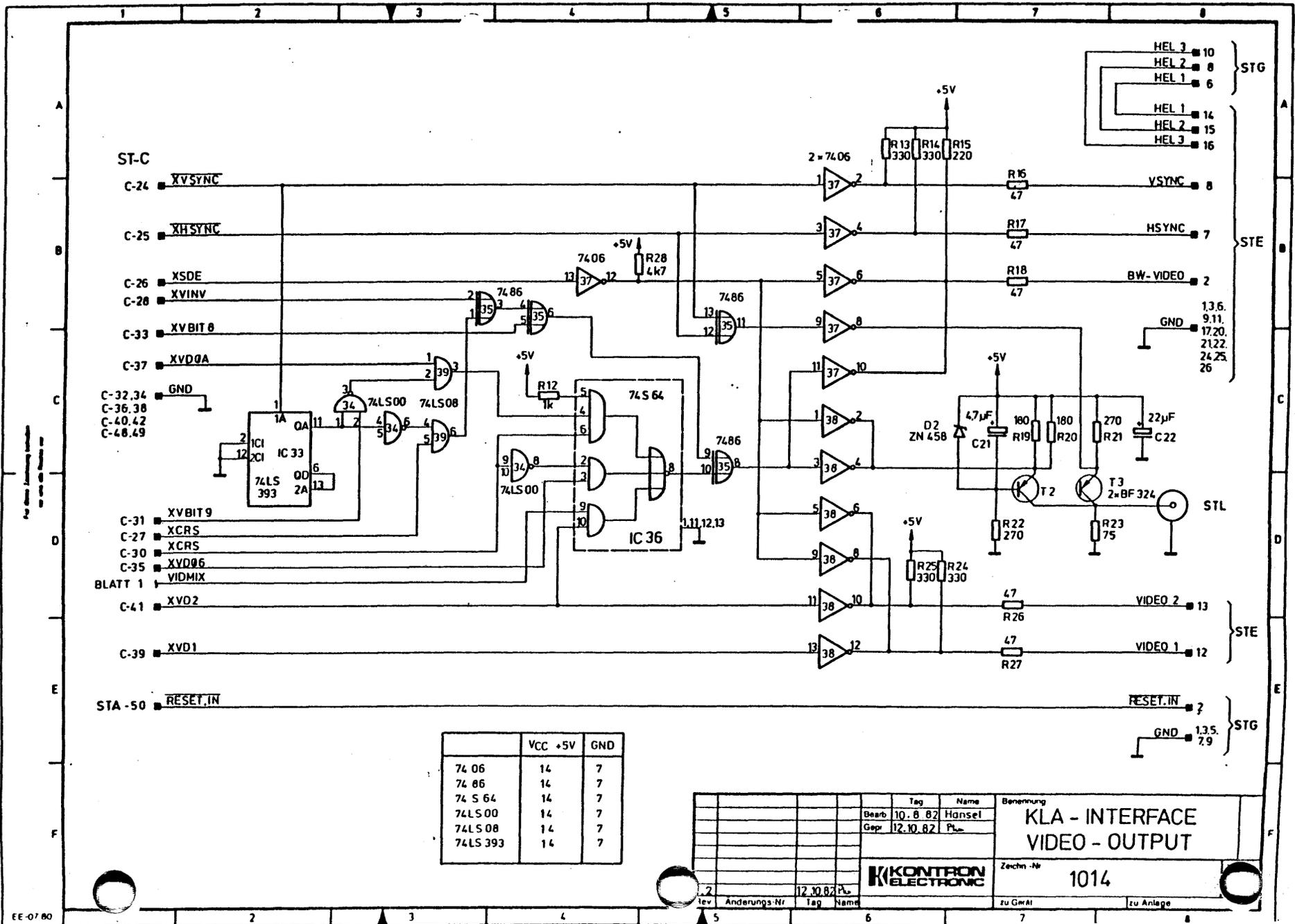
1.2	Anderungs-Nr.	12.10.82	Tag	Name	zu Gerät	zu Anlage
-----	---------------	----------	-----	------	----------	-----------



Bearb	5.8.82	Hansel	Benennung
Gepr	12.10.82	Fl	
			FLOPPY DISK & KEYBOARD INTERFACE
			Zeichn.-Nr 1014
1.2	12.10.82	Fl	Dian.-Nr
Anderungs-Nr	Tag	Name	Zu Gerät
			Zu Anlage



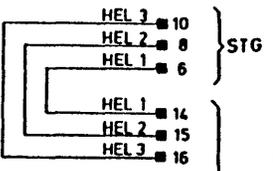
				Tag	Name	Benennung	
				Bearb 9.8.82	Hansel	SERIEN - PARALLEL UMSCHALTER	
				Gepr 12.10.82	RL		
						Zeichn. Nr.	Blatt Nr.
						1014	7
							v. 8 Bl.
1.2				12.10.82	RL		
Rev	Anderungs Nr.	Tag	Name			Zu Gerät	Zu Anlage



ST-C

- C-24 XVSYNC
- C-25 XHSYNC
- C-26 XSDE
- C-28 XVINV
- C-33 XVBIT 8
- C-37 XVD0A
- C-32,34 GND
- C-36,38
- C-40,42
- C-48,49
- C-31 XVBIT 9
- C-27 XCRS
- C-30 XCRS
- C-35 XVD06
- BLATT 1 VIDMIX
- C-41 XVD2
- C-39 XVD1

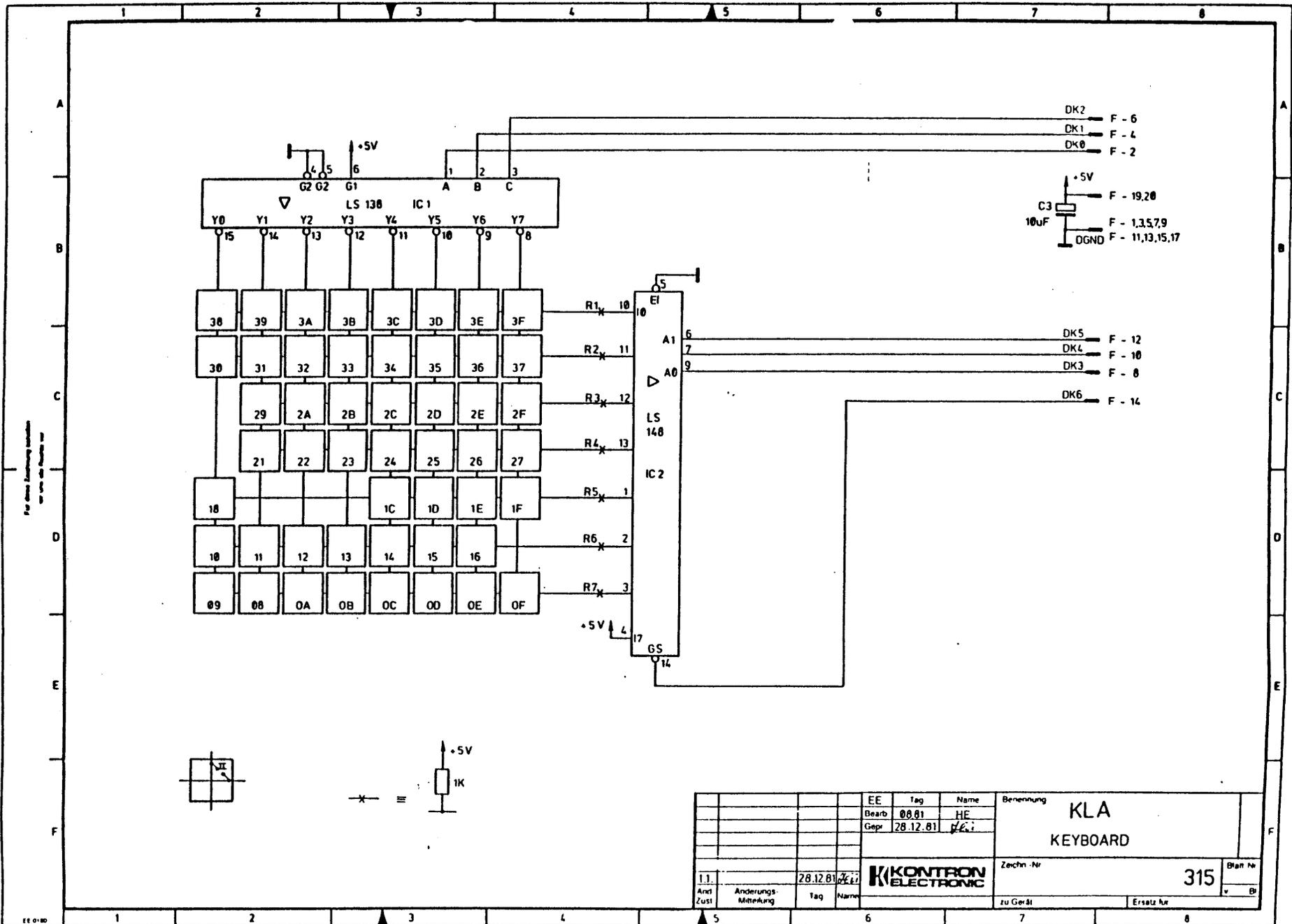
STA-50 RESET.IN



	VCC +5V	GND
74 06	14	7
74 86	14	7
74 S 64	14	7
74LS00	14	7
74LS08	14	7
74LS393	14	7

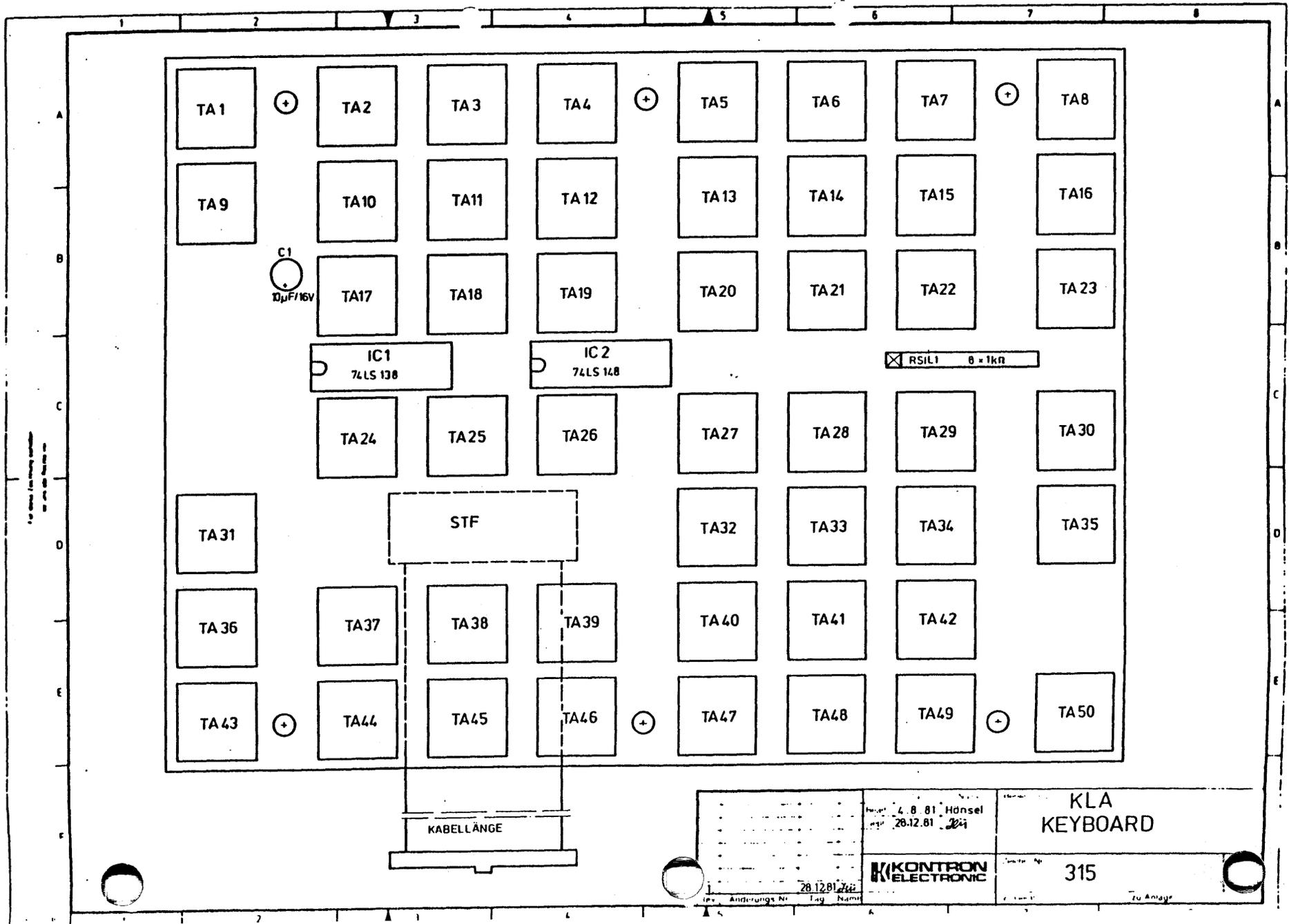
Tag	Name	Benennung
Bearb 10.8.82	Hansel	KLA - INTERFACE VIDEO - OUTPUT
Gepr 12.10.82	Plu	
Zu GW#		Zu Anlage
Zu Anlage		

KONTRON ELECTRONIC
 Zeichn-Nr 1014



Für diese Schaltung werden
die Bauteile in der Liste
auf Seite 10 benötigt

EE	Tag	Name	Benennung		
Bearb	08.01	HE	KLA KEYBOARD		
Gepr	28.12.81	HE			
			Zechn.-Nr	315	Blatt Nr
			zu Gerät	Ersatz für	
1.1.	28.12.81	HE			
Änd					
Zust					



TA 1

TA 2

TA 3

TA 4

TA 5

TA 6

TA 7

TA 8

TA 9

TA 10

TA 11

TA 12

TA 13

TA 14

TA 15

TA 16

TA 17

TA 18

TA 19

TA 20

TA 21

TA 22

TA 23

IC 1
74LS 138

IC 2
74LS 148

RS1 8 x 1kΩ

TA 24

TA 25

TA 26

TA 27

TA 28

TA 29

TA 30

TA 31

STF

TA 32

TA 33

TA 34

TA 35

TA 36

TA 37

TA 38

TA 39

TA 40

TA 41

TA 42

TA 43

TA 44

TA 45

TA 46

TA 47

TA 48

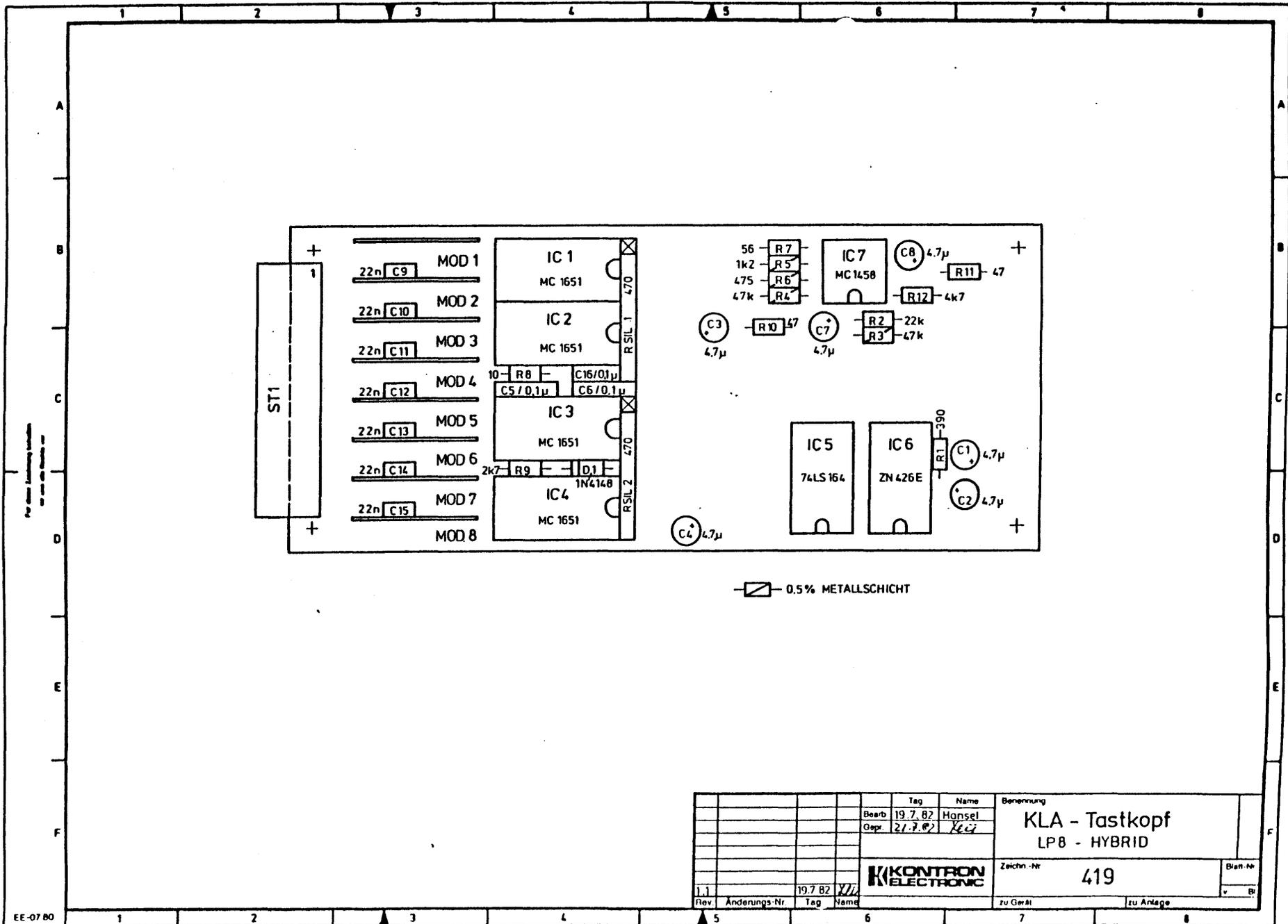
TA 49

TA 50

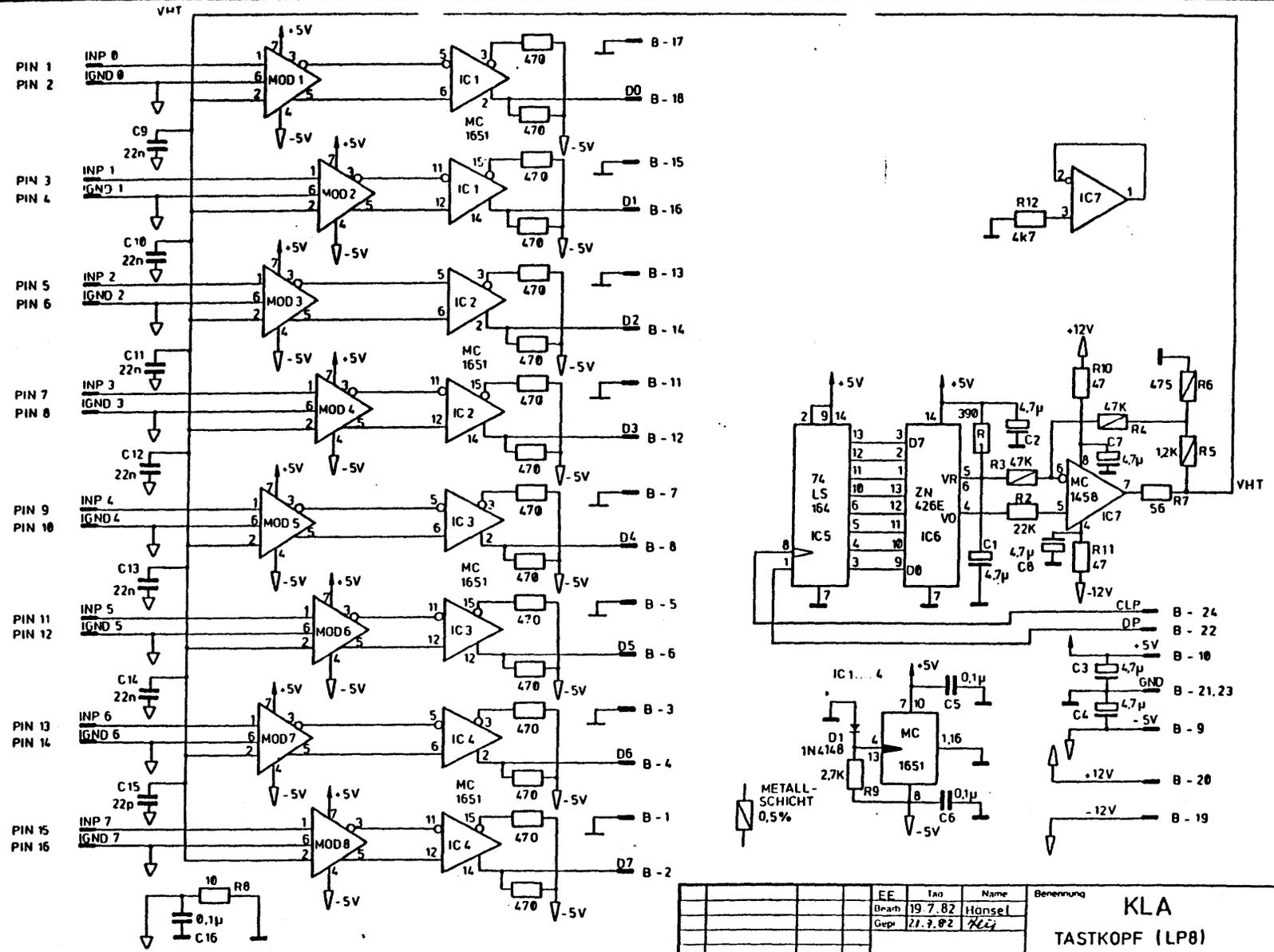
KABELLÄNGE

20.12.81
Hörsel
20.12.81
KONTRON ELECTRONIC
28.12.81

KLA
KEYBOARD
315
Zu Anlage



Rev.	Änderungs-Nr.	Tag	Hand	Tag	Name	Bemerkung	Zeichn.-Nr.	Blatt-Nr.
1.1		19.7.82	YJL	19.7.82	Hönsel	KLA - Tastkopf LP8 - HYBRID	419	zu Gerät
				27.7.82	Kec			
				KONTRON ELECTRONIC				

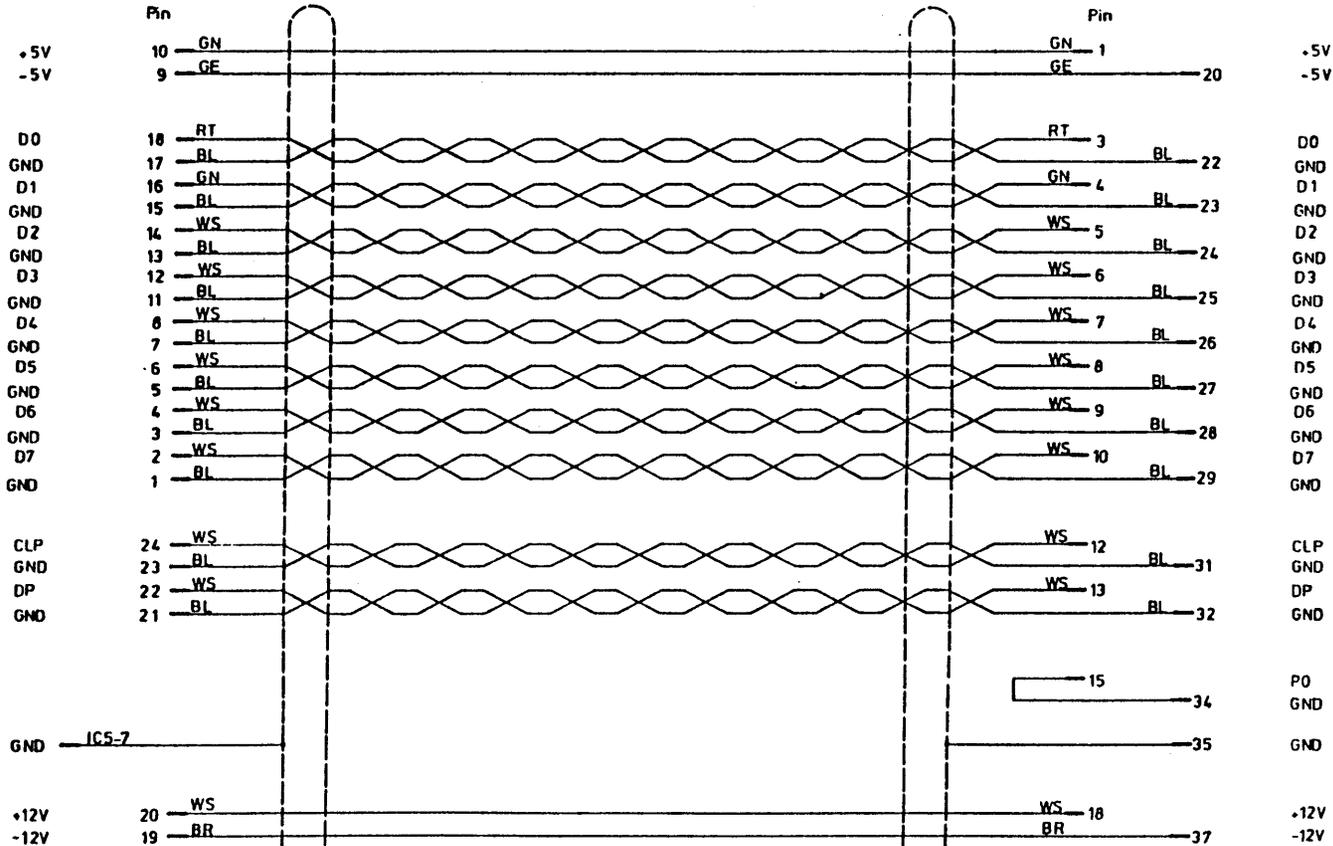


EE	Tag	Name	Benennung	KLA	
Druck	19.7.82	Hönsel			TASKOPF (LP8)
Gespr.	21.7.82	Kli			
			Zechn. Nr.	419	
1.1	19.7.82	Kli	zu Gerät		
Rev	Anderungs-Nr	Tag	zu Anlage		

Tastkopf 363

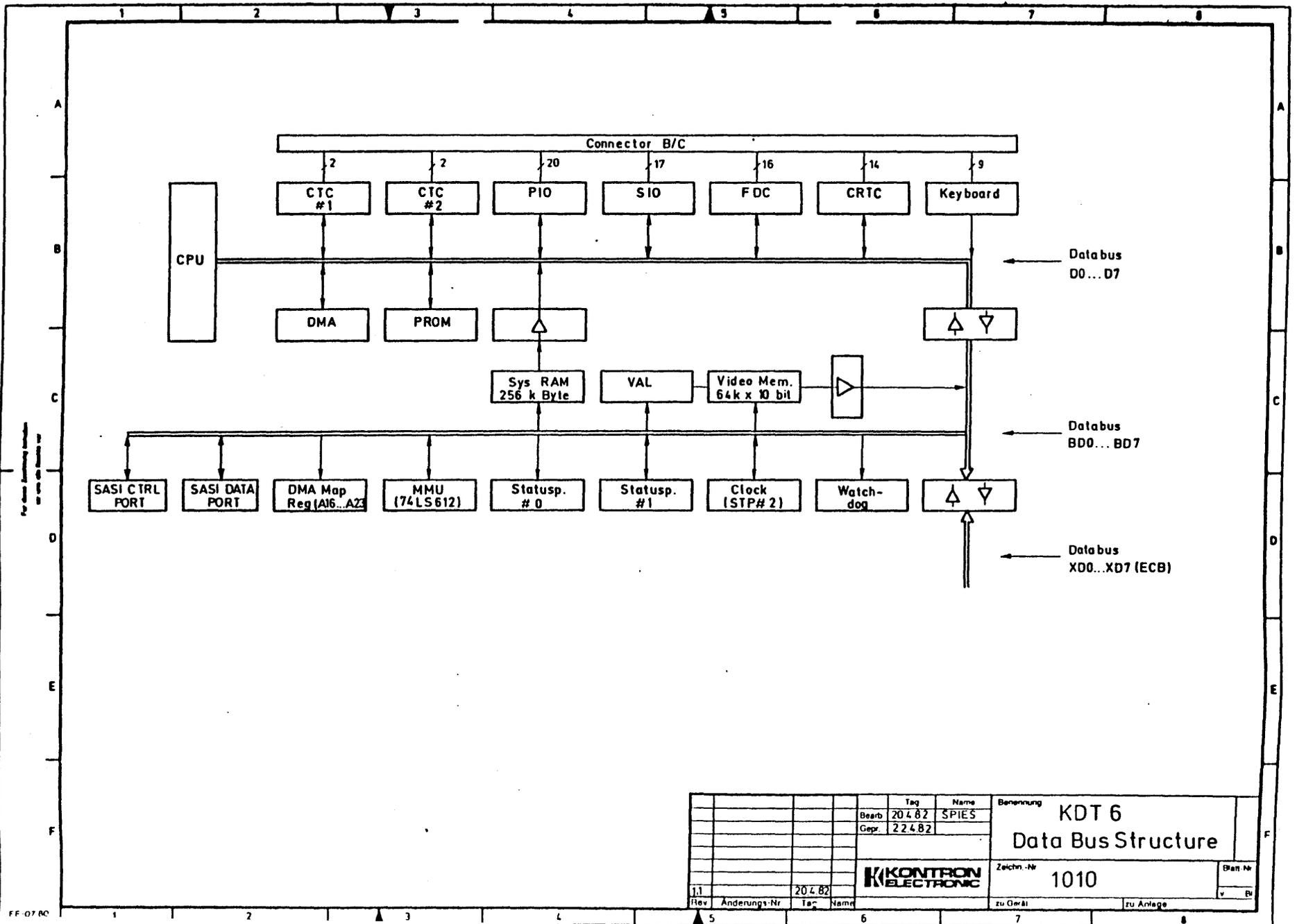
**STECKER
DCP - 375**

SIGNAL

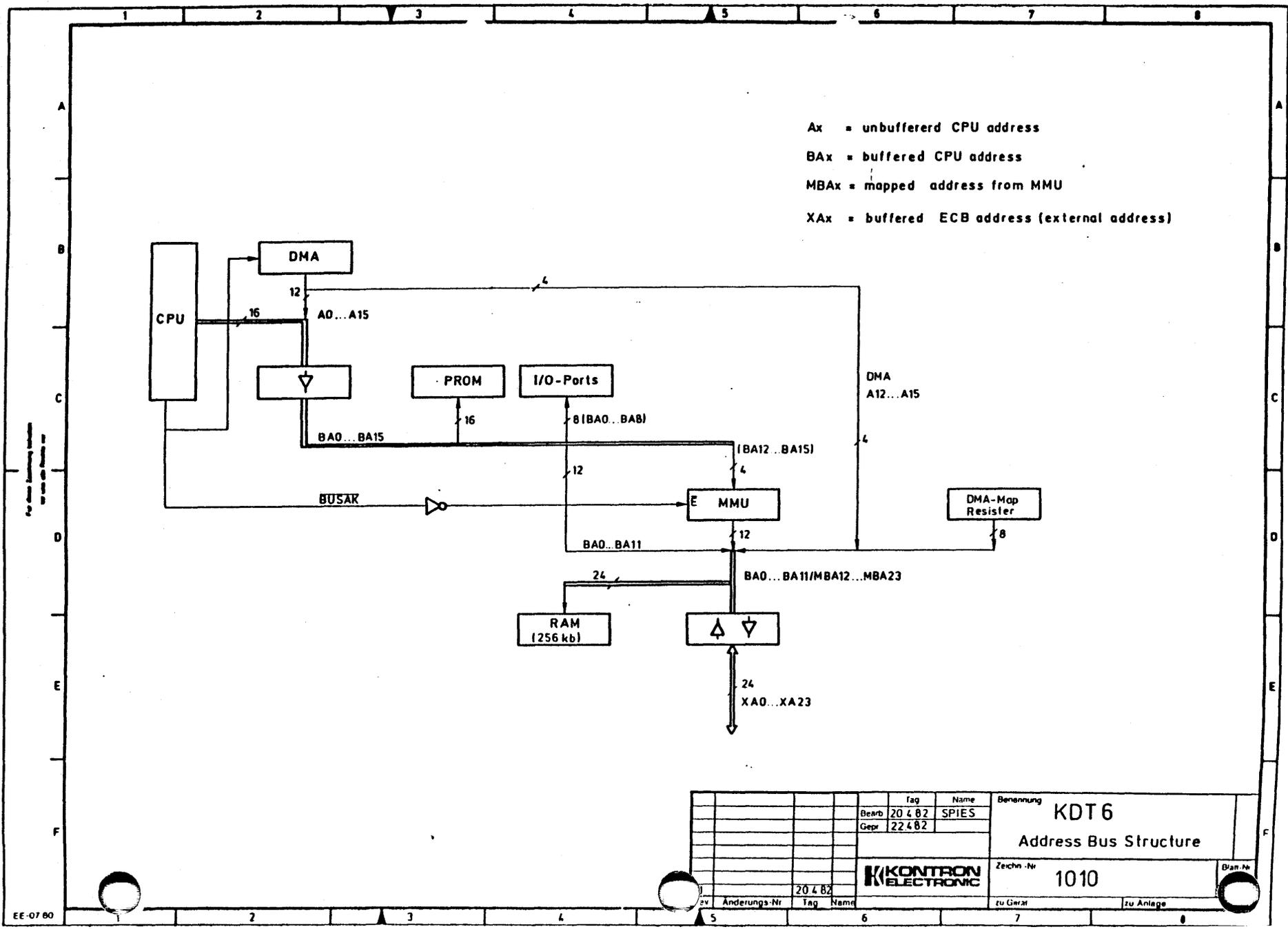


KABELLÄNGE: 200cm
 KABEL: METROFUNK
 TYP: 4*LIY - AWG 26 } -CY
 +10*2LIY - AWG 28 } SCHWARZ

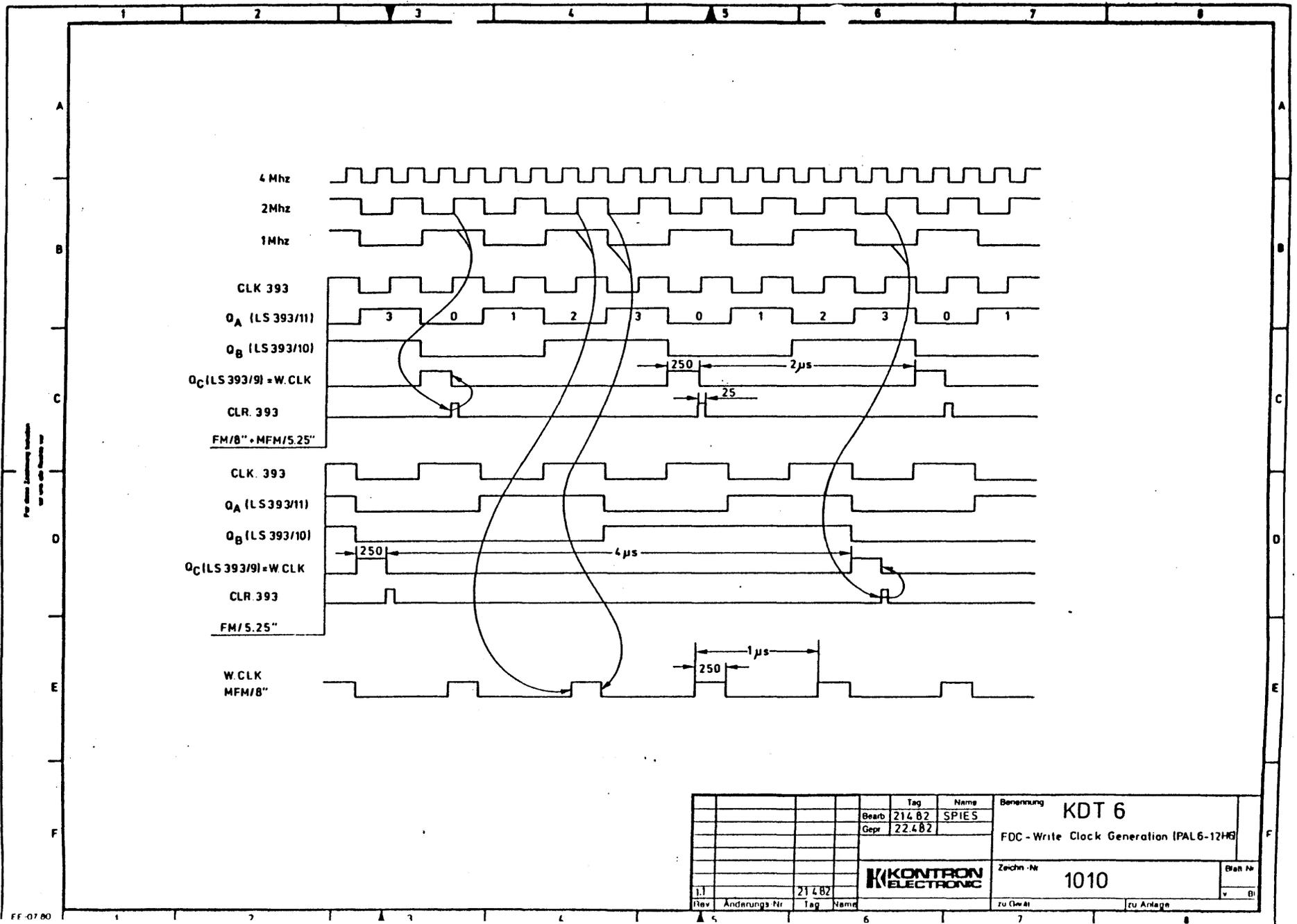
1.1		19.7.82		KONTRON ELECTRONIC		Benennung KLA TASTKOPF - KABEL LP8 - HYBRID		Zeichn.-Nr. 419		Blatt-Nr.	
Anderungs-Nr.		Tag		Name		Zu Gezeichnet		Zu Gezeichnet		Anlage	



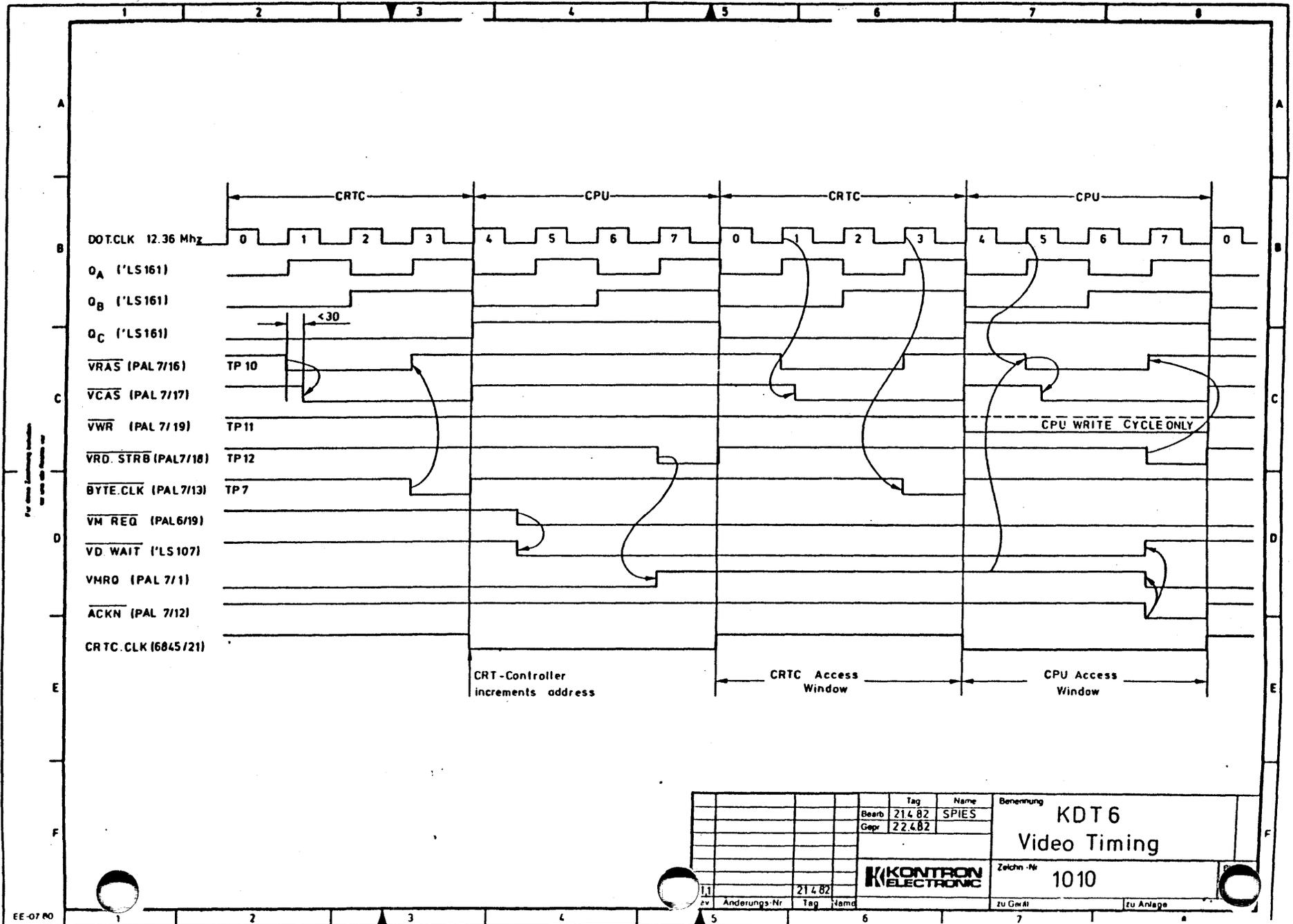
Rev	Anderungs-Nr	Tag	Name	Benennung	Blatt-Nr
1,1		20.4.82	SPIES	KDT 6 Data Bus Structure	1010
		22.4.82			
KONTRON ELECTRONIC				Zeichn.-Nr.	Blatt-Nr.
				zu Gerät	zu Anlage

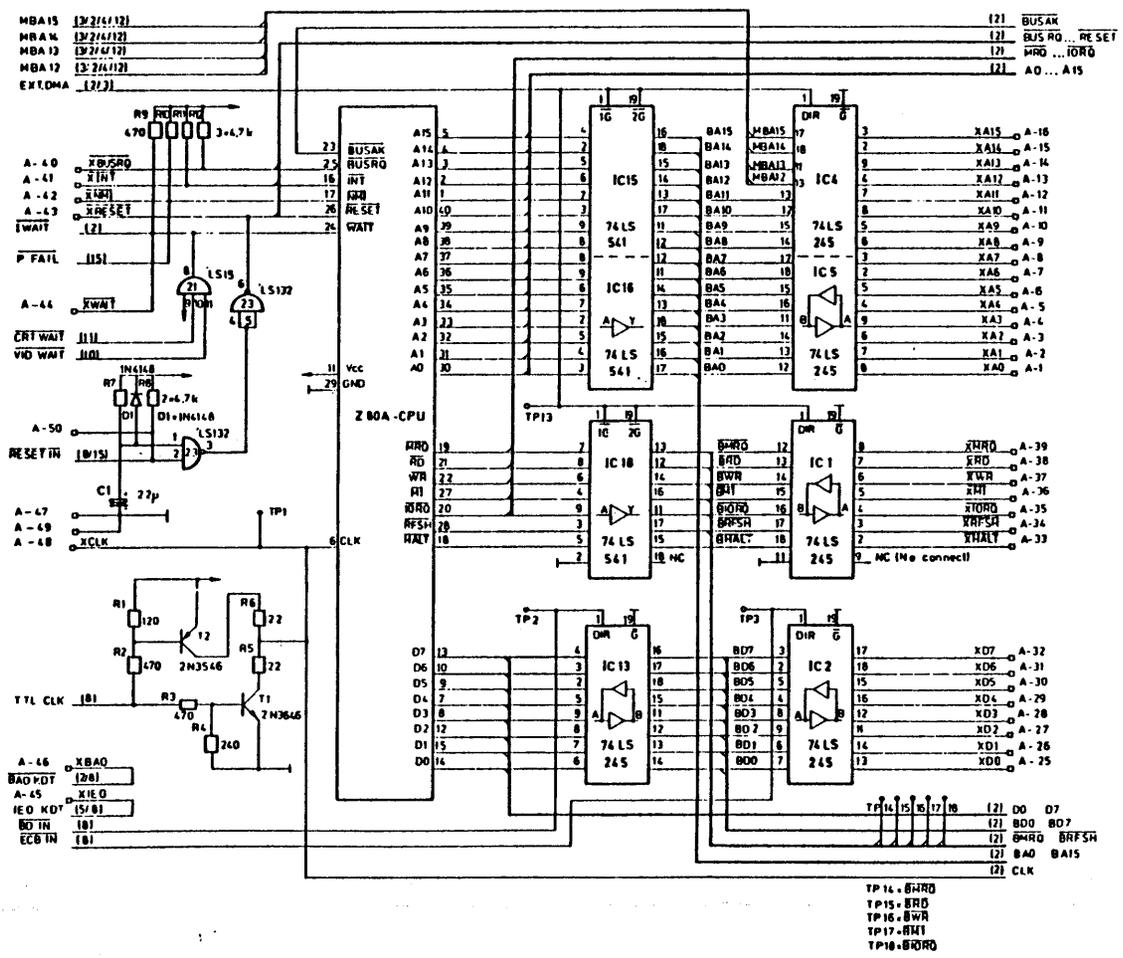


			Tag	Name	Benennung
			Bearb.	20.4.82	SPIES
			Gepr.	22.4.82	
					Zechn.-Nr.
					1010
			zu Gerät		zu Anlage

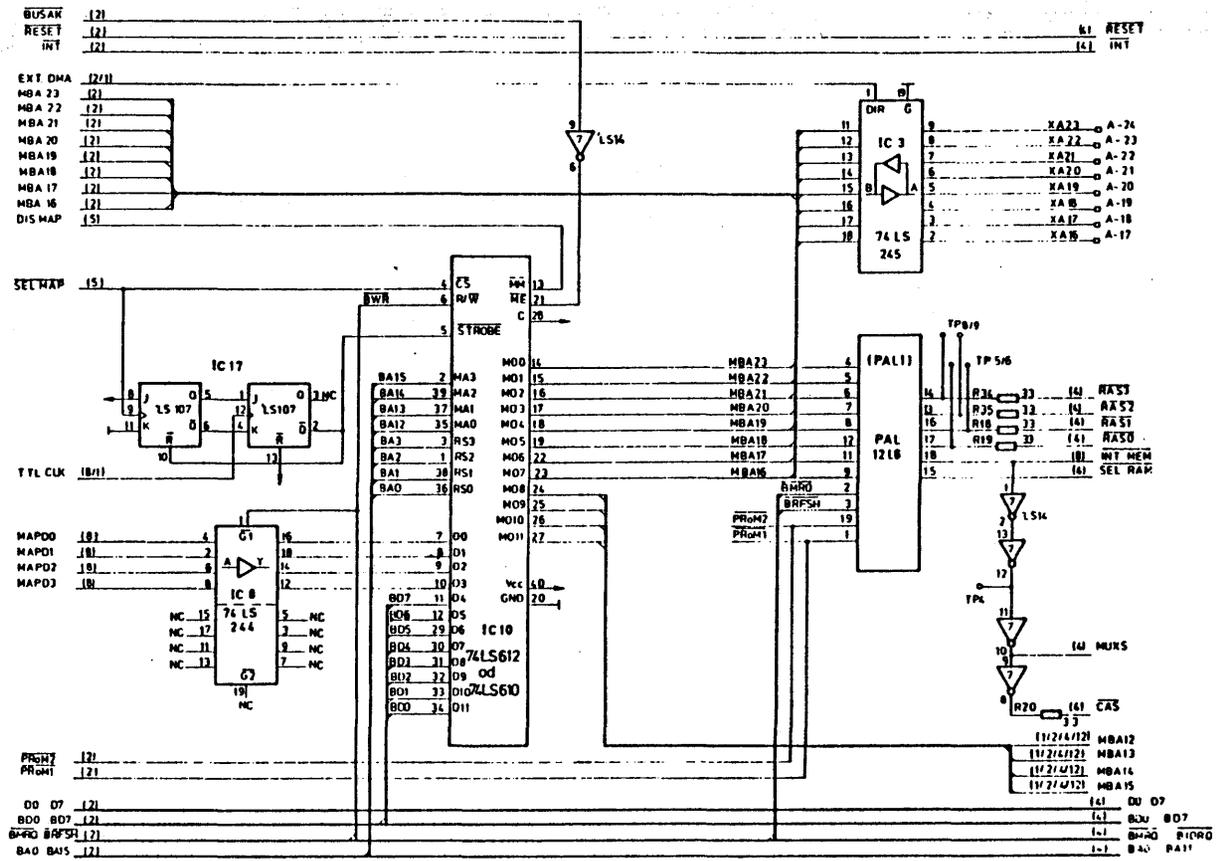


			Tag	Name	Benennung	KDT 6	
			Bearb. 21.4.82	SPIES	FDC - Write Clock Generation (PAL6-12H8)		
			Gepr. 22.4.82		Zeichn.-Nr.	1010	Blatt Nr.
							v. Bl.
1.1		21.4.82			zu (Gerät)		zu Anlage
Rev	Änderungs-Nr.	Tag	Name	KONTRON ELECTRONIC			



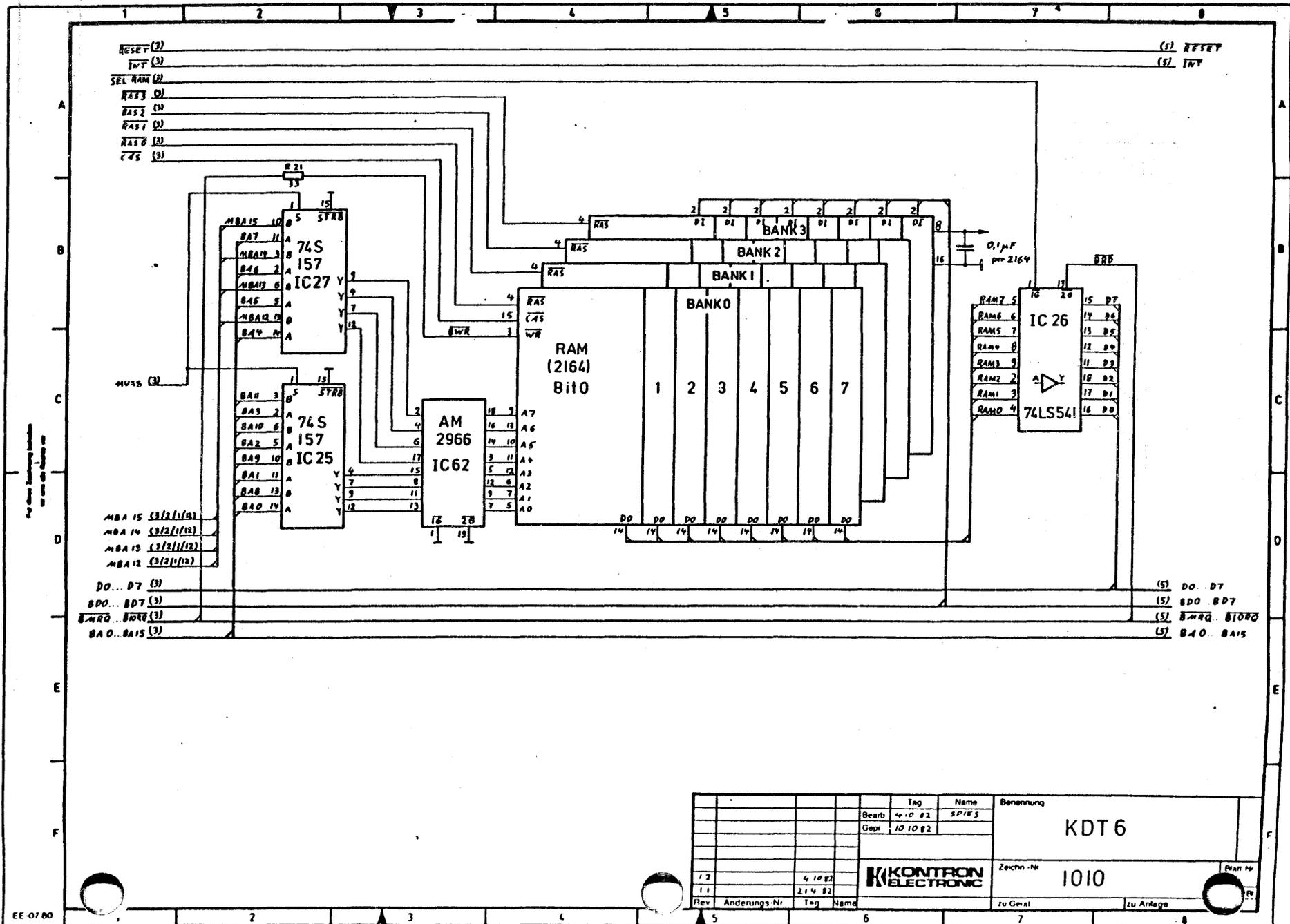


Part No.	214 07	SP1ES	Bezeichnung	KDT 6
Order	214 07	SP1ES		
Drawn	214 07	SP1ES		
Checked				
Approved				
Scale	1:1			
Sheet No.	1			
Total Sheets	1			
Project No.	1010			
Rev.				
Author				
Designer				
Checker				
Approver				

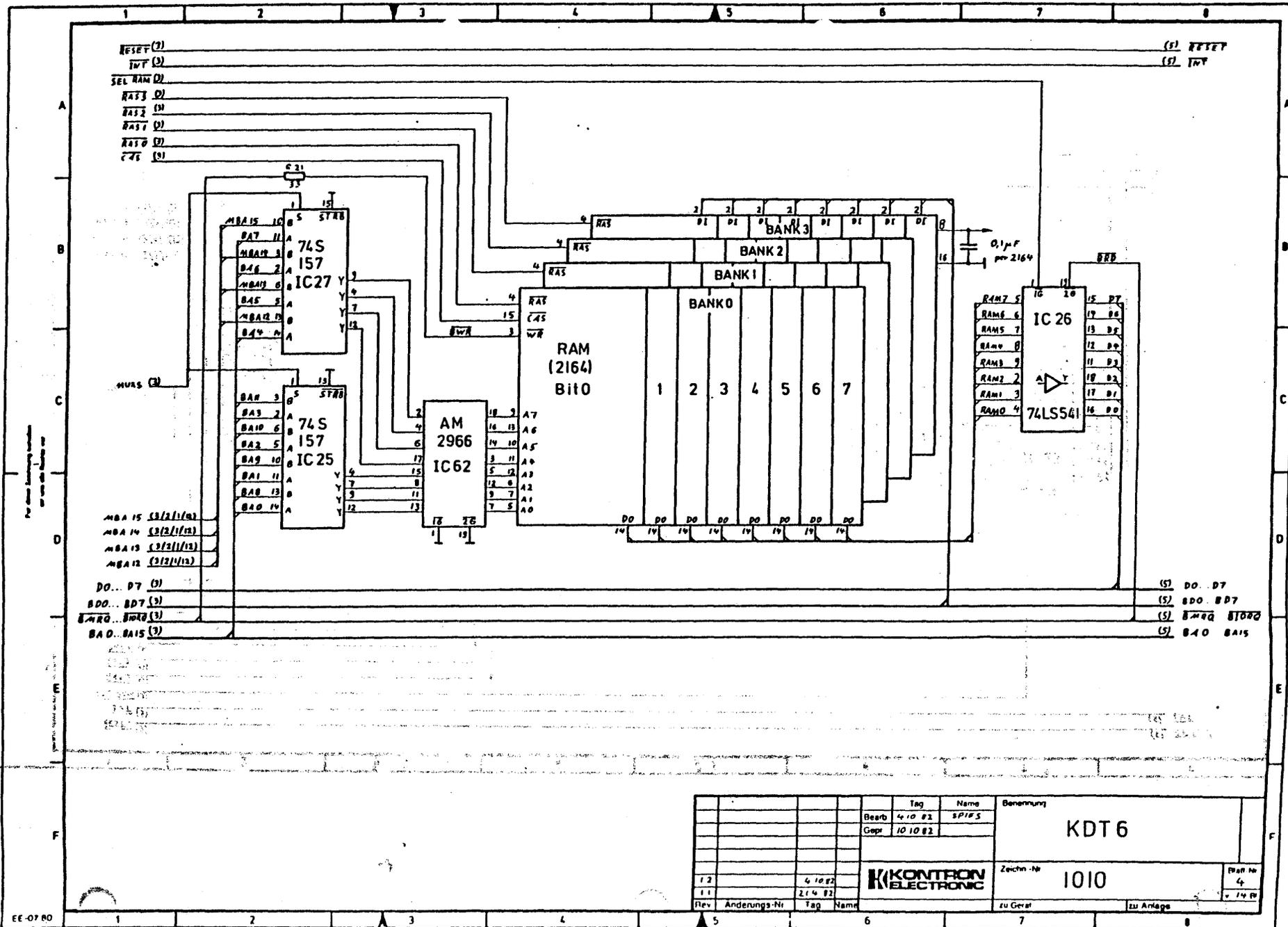


Tag	name	Benennung
Bezn	21.4.82	SPIES
Opp	10.10.82	
		Zusatz-Nr.
		1010
1.2	1002	Blatt Nr.
1.1	21.4.82	13
Rev.	Änderungen Nr.	Tag
KONTAKT		in Größe
KONTAKT		in Anzahl

62-07 00



Rev	Anderungs-Nr	Tag	Name	Benennung
1.2		4.10.82	SPIES	KDT6
1.1		2.14.82		
KONTRON ELECTRONIC				Zeichn.-Nr 1010
			Zu Geat	Blatt-Nr 10
			Zu Anlage	

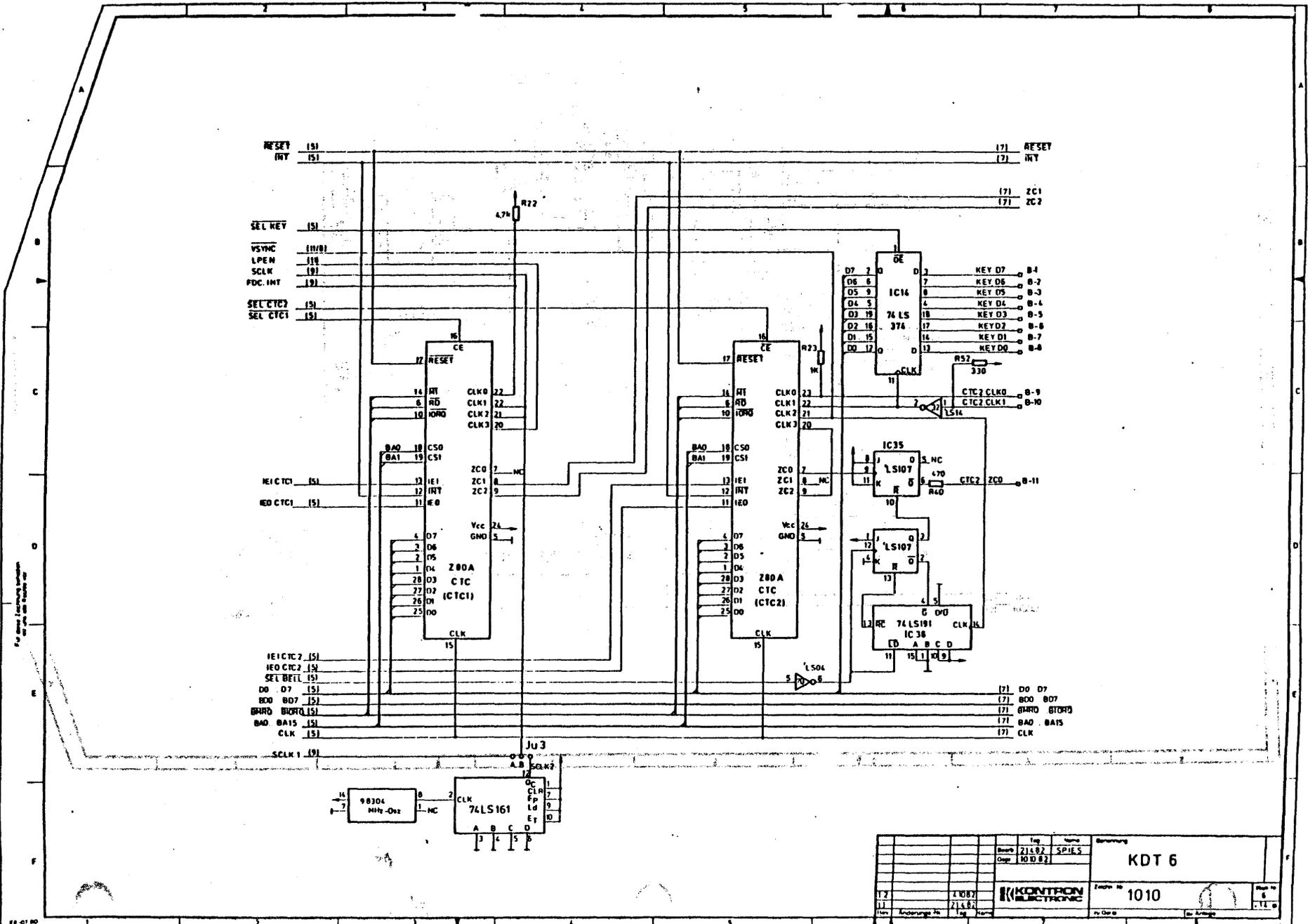


RESET (2) (S) RESET
 INT (2) (S) INT
 SEL RAM (2)
 RAS3 (2)
 RAS2 (2)
 RAS1 (2)
 RAS0 (2)
 WE (2)

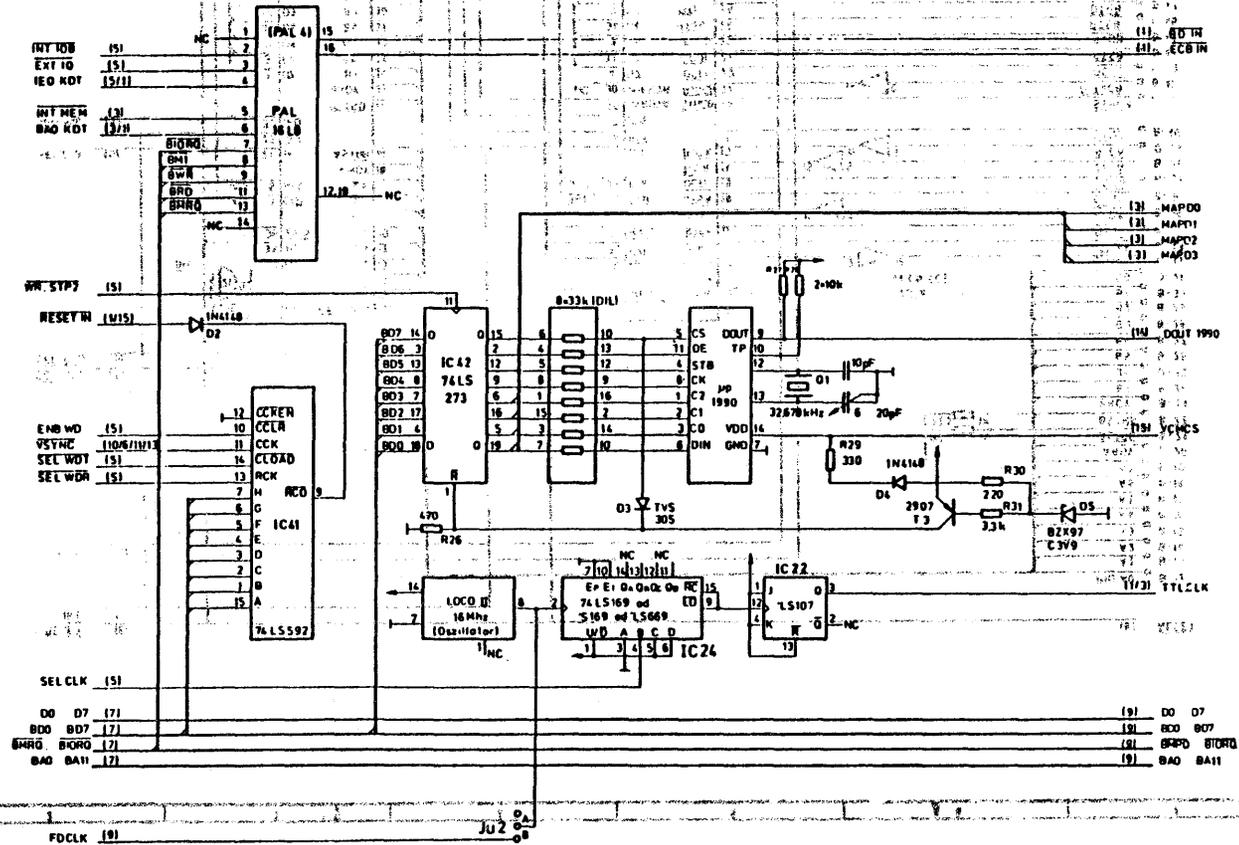
MURS (2)
 MBA15 (3/2/1/0)
 MBA14 (3/2/1/0)
 MBA13 (3/2/1/0)
 MBA12 (3/2/1/0)

DO... D7 (2) (S) DO... D7
 BDO... BD7 (2) (S) BDO... BD7
 BWR... BWR0 (2) (S) BWR... BWR0
 BA0... BA15 (2) (S) BA0... BA15

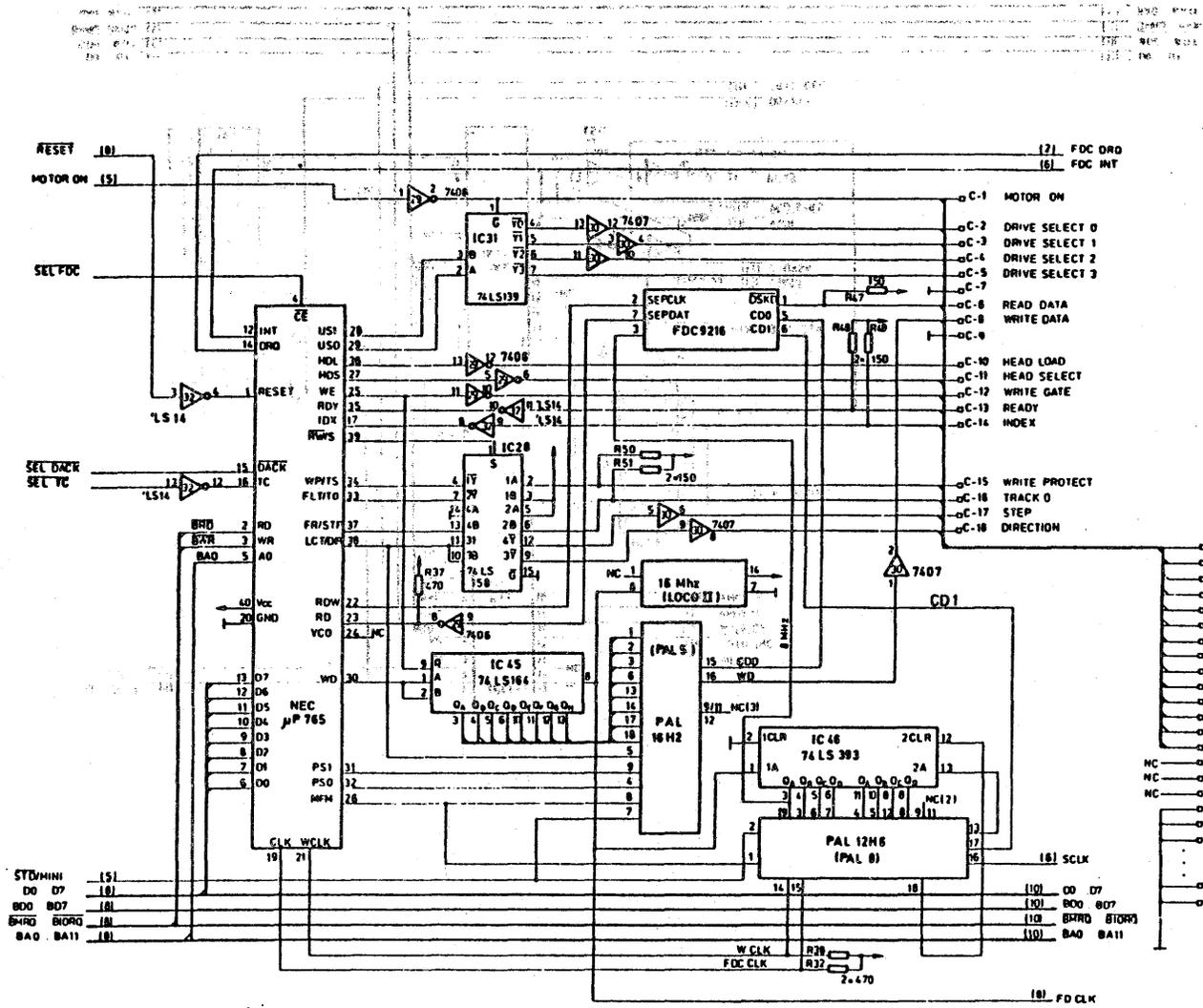
Rev	1.2	4.10.82	Tag	10.10.82	Name	SPIES	Benennung	KDT 6
Rev	1.1	2.14.82	Tag		Name		Zeichn.-Nr.	1010
Rev			Tag		Name		zu Gerät	
Rev			Tag		Name		zu Anlage	



Rev	1.0	Rev	1.0
Drawn	21.8.82	Checked	21.8.82
Checked	21.8.82	Approved	21.8.82
KONTROL		KONTROL	
ELECTRONIC		ELECTRONIC	
1010		1010	



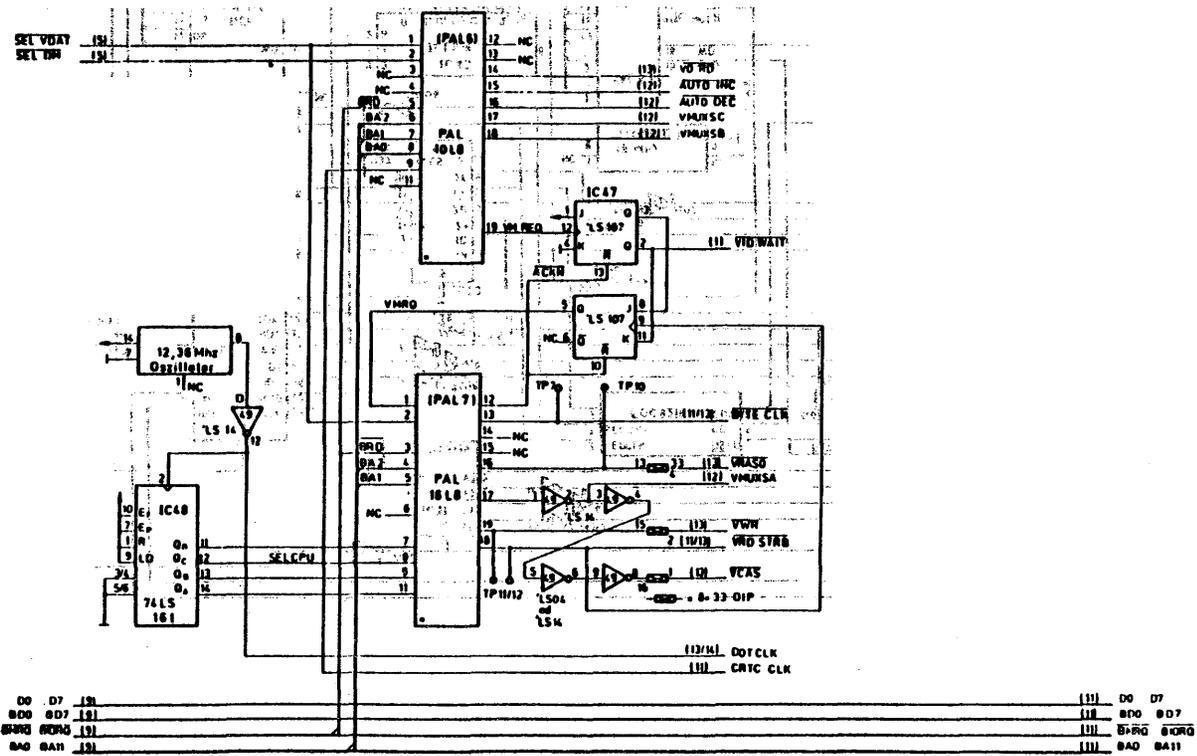
Name		KOT 6	
Drawn	21.8.82	S.P.F.S.	
Check	10.9.81		
Techn. No.		1010	
KONTRON ELECTRONIC			
Anschlüsse		Pin Bezeichnung	



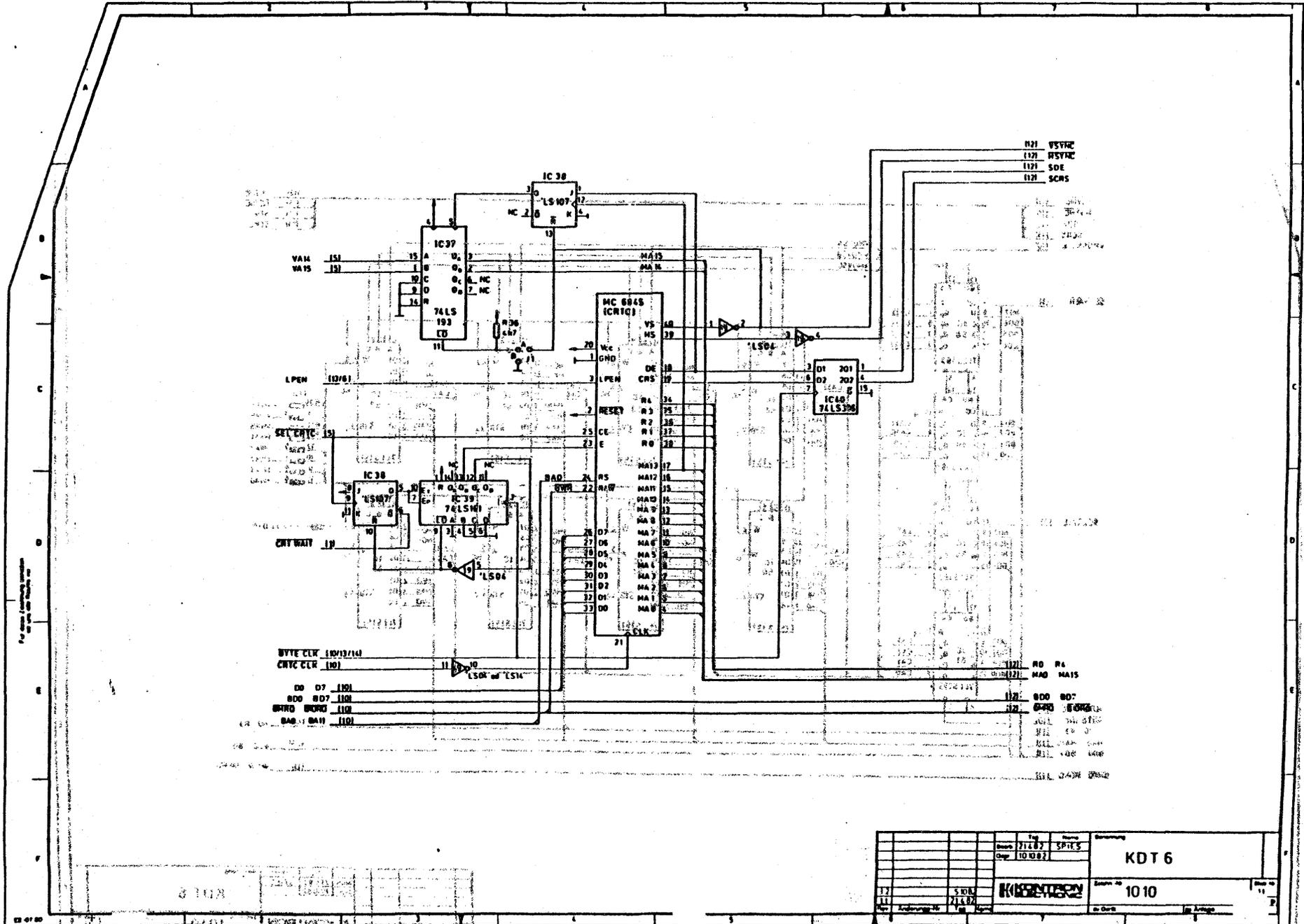
RESET .10)
 MOTOR ON .15)
 SEL FDC
 SEL BACK
 SEL VC
 BRD 2 RD
 BDR 3 WR
 BAO 5 A0
 40 Vcc
 20 GND
 13 D7
 12 D6
 11 D5
 10 D4
 9 D3
 8 D2
 7 D1
 6 D0
 PS1 31
 PS0 32
 MFM 28
 CLK WCLK
 19 21
 STD/INH .15)
 DO D7 .18)
 BDO B07 .18)
 BDR B0RD .18)
 BAO BA11 .18)

12) FDC DRD
 16) FDC INT
 C-1 MOTOR ON
 C-2 DRIVE SELECT 0
 C-3 DRIVE SELECT 1
 C-4 DRIVE SELECT 2
 C-5 DRIVE SELECT 3
 C-7
 C-8 READ DATA
 C-8 WRITE DATA
 C-9
 C-10 HEAD LOAD
 C-11 HEAD SELECT
 C-12 WRITE GATE
 C-13 READY
 C-14 INDEX
 C-15 WRITE PROTECT
 C-18 TRACK 0
 C-17 STEP
 C-18 DIRECTION
 F-2 MOTOR ON
 F-6 READY
 F-8 INDEX
 F-10 DRIVE SELECT 0
 F-12 DRIVE SELECT 1
 F-16 MOTOR ON
 F-18 DIRECTION
 F-20 STEP
 F-22 WRITE DATA
 F-24 WRITE GATE
 F-26 TRACK 0
 F-28 WRITE PROTECT
 F-30 READ DATA
 F-32 HEAD SELECT
 NC F-4
 NC F-14
 NC F-34
 F-1
 F-3
 F-5
 F-31
 F-33
 18) FDC CLK

Rev	1	11/82	SPES	KDT 6
Drawn	11/82	1010.82		
Checked				
Approved				
Part No.	1010			
Quantity				
Material				
Notes				



Date: 21.6.92		Sheet: 5 of 5		KDT 6
Day: 10.10.92				
10107		10107		1010
KINSON ELECTRONIC		KINSON ELECTRONIC		10



- 121 V5V6
- 122 H5V6
- 123 SDE
- 124 SCRS

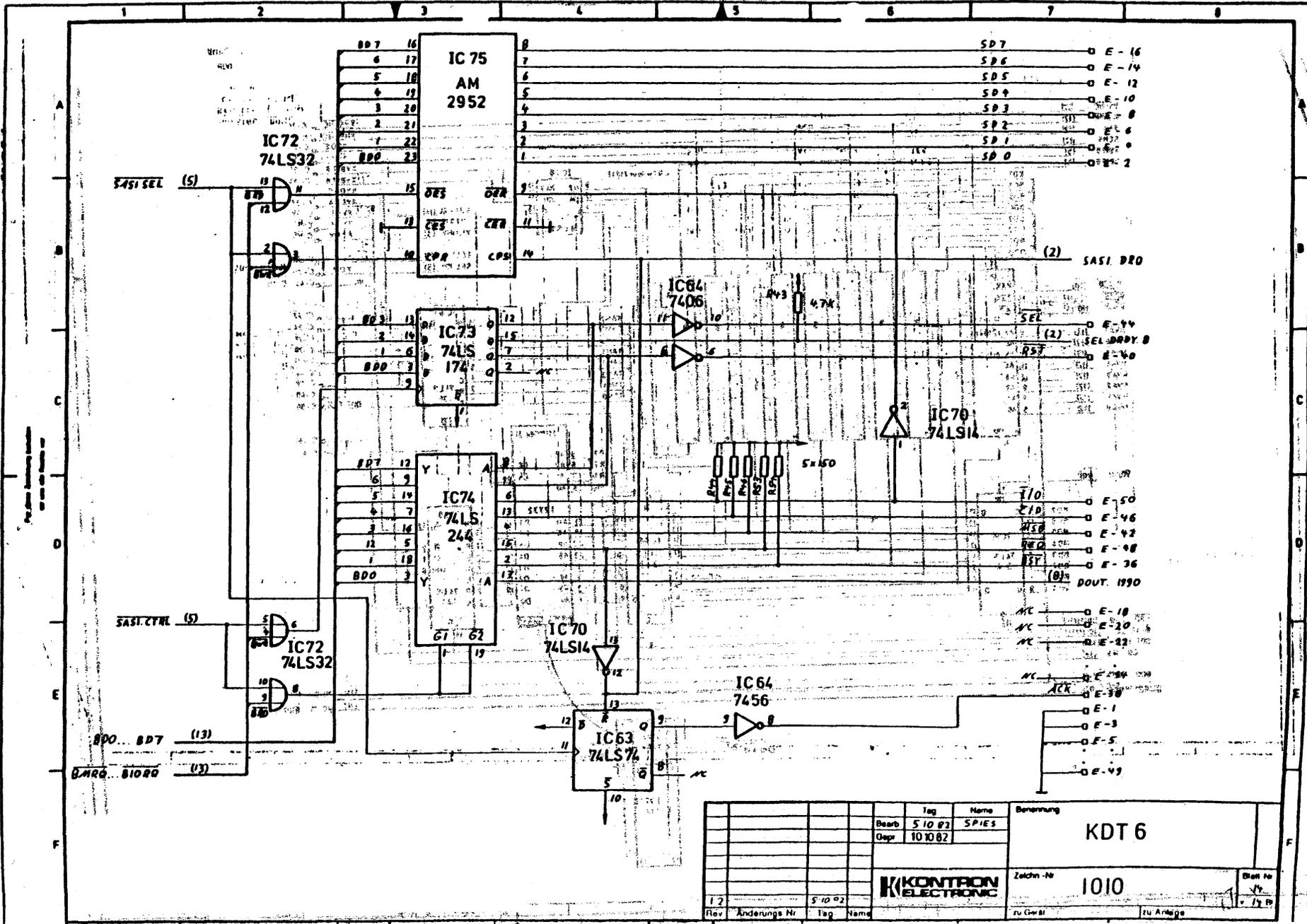
- 121 RD R4
- 122 MAD MA15

- 123 B00 B07
- 124 B00 B07

KDT 6

Rev	1	10/10/82	SPICES
Drawn	10/10/82		
Checked			
			Sheet No 10 10
Part No 10 10			Rev No 11

3 1118



Beard	5 10 82	Name	SPIES	Benennung	KDT 6
Gepr	10 10 82				
				Zeichn.-Nr.	1010
				Blatt Nr.	1/1
Rev	5 10 82	Tag	Name	zu Gepr	zu Anlage